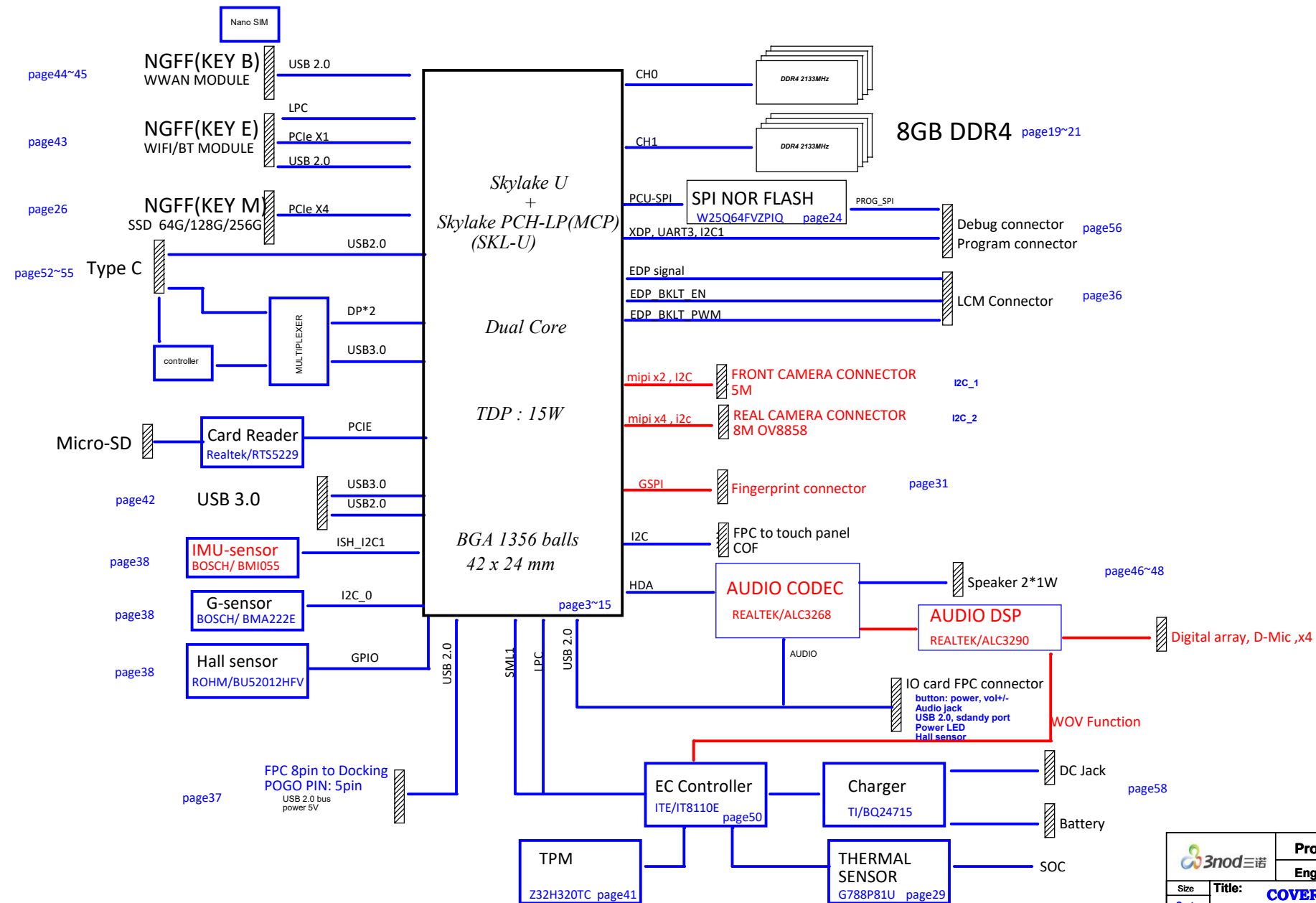


Basing on SKYLAKE-U MRD BASE BOARD

Miix510 for Lenovo



		Project: Miix510	
		Engineer: Jacky	
Size	Title: COVER PAGE	Rev	
Custom		V01	
Date: Wednesday, May 24, 2017	Sheet 1	of 69	

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04--SKL-U(2/12)DDR4	34 -- NC_HDMI LEVEL SHIFTERS	64--PWR-NA
05--SKL-U(3/12)SPI,ESPI,SMB,LPC	35 -- NC_HDMI CONNECTOR	65--PWR-+1.8V_PRIM
06--SKL-U(4/12)HDA,EMMC,SD	36 -- DISPLAY	66--PWR-CPU_VR_IC
07--SKL-U(5/12)CLK,GPIO	37 -- TOUCH PANEL AND DOCK	67--PWR-VCC_CORE/GT/SA
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20--DDR4_CHB	50 -- EMBEDDED CONTROLLER	
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22--NA	52 -- TYPE-C MULTIPLEXER	
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24 -- SYSTEM FLASH	54 -- NC TYPE-C BOOST VR	
25 -- NC EMMC	55 -- TYPE-C CONNECTOR	
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27 -- NC MICRO-SD CARD	57 -- HW Change list	
28 -- NC_SD CARD POWER	58--PWR_DCIN/BATT CONN	
29 -- CPU THERMAL SENSOR	59--PWR_CHARGER(OZ8690)	
30 -- FAN conn	60--PWR-+V5P0A / +V3P3A	

Armour3 12.2" SDV plan				
	44	40	40	42
Component	SKU1	SKU2	SKU3	SKU4
Color	Sliver	Sliver	Sliver	Sliver
MB	Intel Core i3-6006U	Intel Core i3-7100U	Intel Core i5-8200U	Intel Core i7-8500U
CPU	Samsung 4G 4*1GB	Hynix 4G 4*1GB	Samsung 8G 4*2GB	Micron 16G 8*2GB
RAM	国名技术 HW	Infineon HW	国名技术 HW	Infineon HW
TPM	TBD	TBD	TBD	TBD
SSD	国显 12.2-inch, 1920x1200	国显 12.2-inch, 1920x1200	国显 12.2-inch, 1920x1200	国显 12.2-inch, 1920x1200
LCD Module	莱宝 12.2-inch	莱宝 12.2-inch	莱宝 12.2-inch	莱宝 12.2-inch
Pannel	BT Pen	Active Pen	TBD	TBD
active pen	Chicony 45W 20V 2.25A	Delta 45W 20V 2.25A	Liteon 45W 20V 2.25A	Delta 45W 20V 2.25A
Adapter	欣旺达 TI+ATL	欣旺达 TI+ATL	欣旺达 TI+ATL	欣旺达 TI+ATL
Battery	NA	NA	NA	NA
Keyboard	OV5670/OV5670	OV5670/OV8858	OV5670/OV5670	OV5670/OV8858
Camera	Intel 3165 1*1 AC	Liteon 1*1	Intel 2*2	Liteon 2*2
WLAN module	NA	L831	L830	EM7455/TBD
LTE Module	力普斯	尚德铭泰	力普斯	尚德铭泰
Speaker	TBD	TBD	TBD	TBD
Antenna	藏旭	藏旭	国日宏	国日宏
LCD_FPC	藏旭	藏旭	国日宏	国日宏
TP_FPC	藏旭	藏旭	国日宏	国日宏
pogo_pin_FPC	藏旭	藏旭	国日宏	国日宏
IO_FFC	藏旭	藏旭	国日宏	国日宏
Package	NA	NA	NA	NA

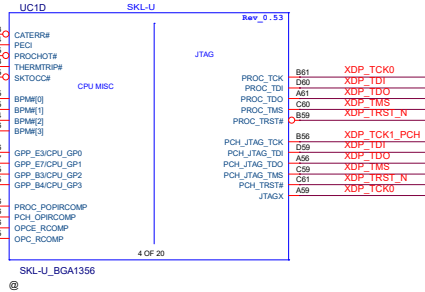
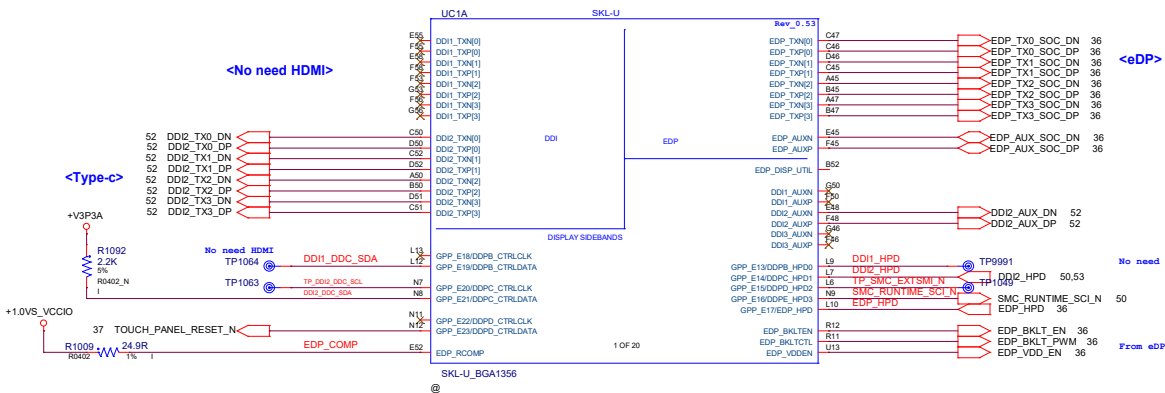
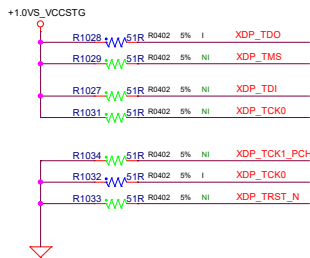
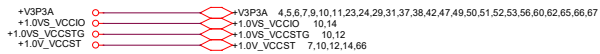
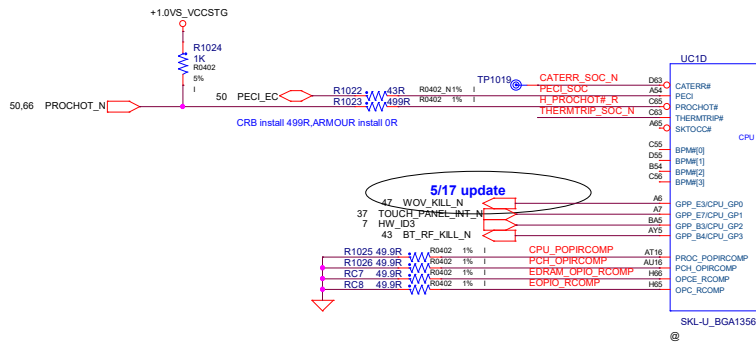
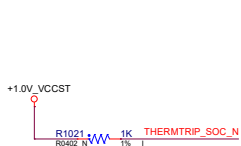
INTERNAL ONLY

BPAGE DRAWING

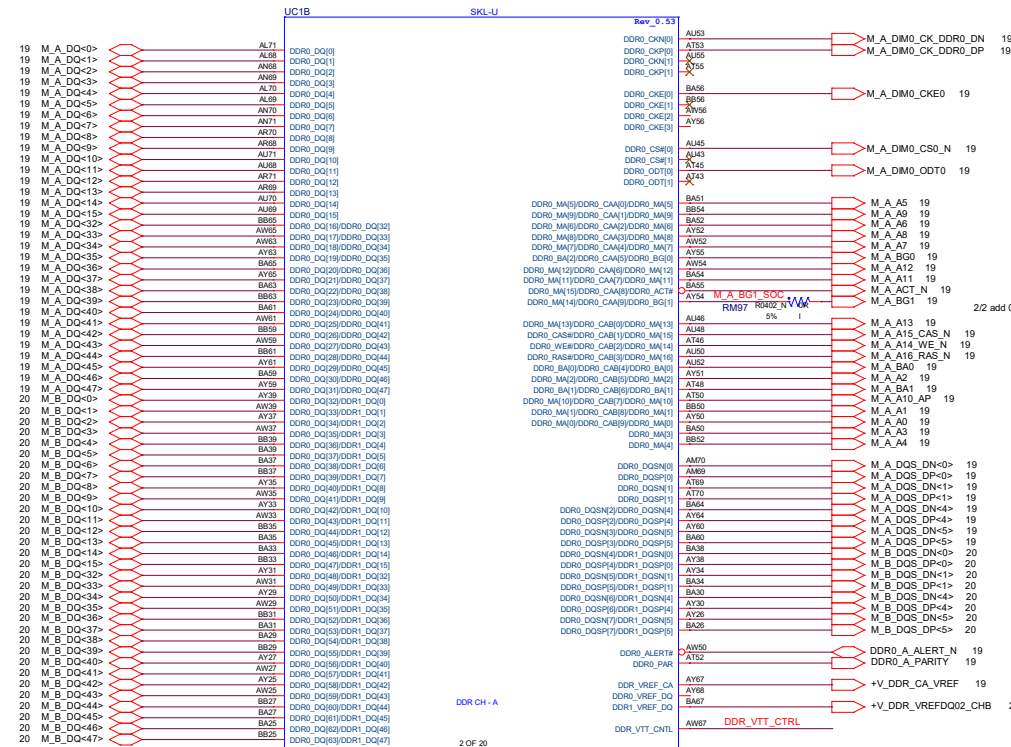
sky_y_mtd_...
Wed Jun 03 11:22:42 2015

		Project: Miix510	
		Engineer: Jacky	
Size	Title: TABLE OF CONTENTS	Rev	
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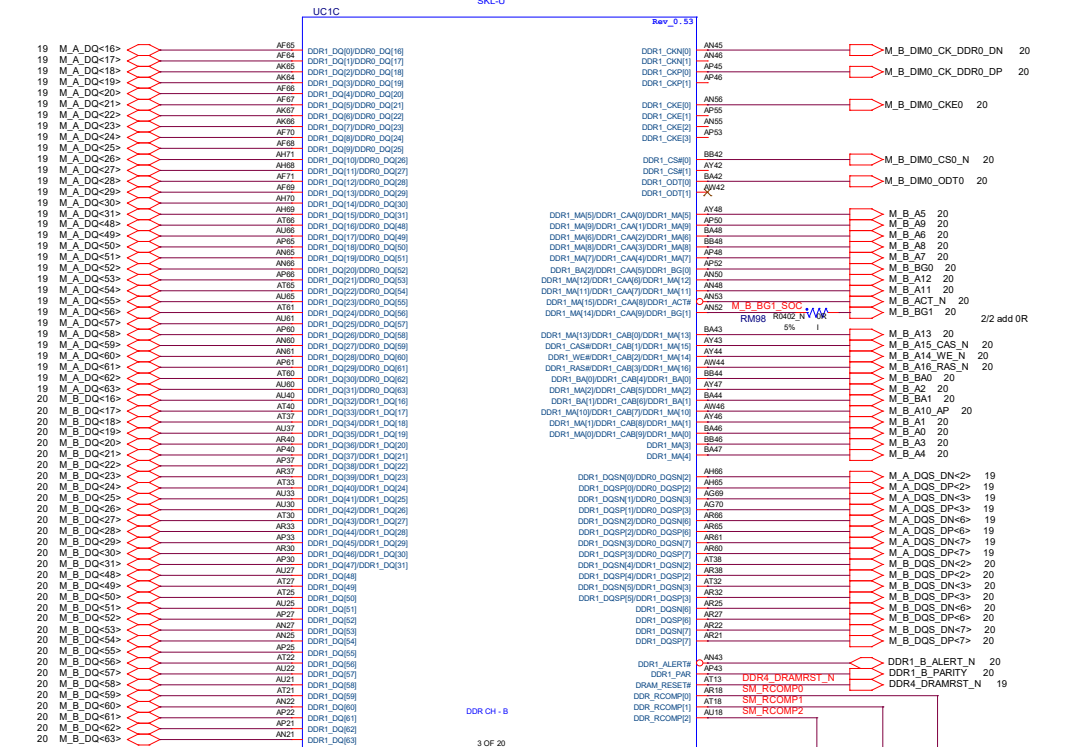
DDPB_CTRLDATA / GPP_E19	Display Port B Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port B is not detected. (Default) 1 = Port B is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
DDPC_CTRLDATA / GPP_E21	Display Port C Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port C is not detected. (Default) 1 = Port C is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.



Non-Interleaved



Non-Interleaved

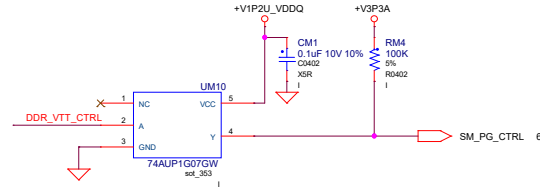


1. To support DDP, need to change two pins on DRAM. You have reserved them. Pls install the BOM.

	X16 SDP	X16 DDP TwinDie
DRAM M9 pin	VSS	Connect to CPU BG1
DRAM E9 pin	VSS	UZQ

	SDP	DDP
Memory size	4Gb or 8Gb	16Gb
DRAM M9 pin	RM95, RM96, RM97, RM98 need install	RM95, RM96, RM97, RM98 need install
DRAM E9 pin	RM79, RM81, RM83, RM85, RM87, RM89, RM91, RM93 need install 0 ohm	RM79, RM81, RM83, RM85, RM87, RM89, RM91, RM93 need install 240 ohm
DDR_RCOMP0	RM3 200R need install	RM3 121R need install

2/2 Add (4Gb 8Gb) & (16Gb) BOM option table

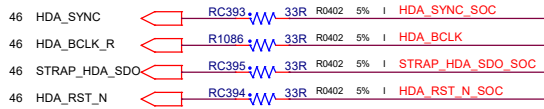


To Enable ME Override

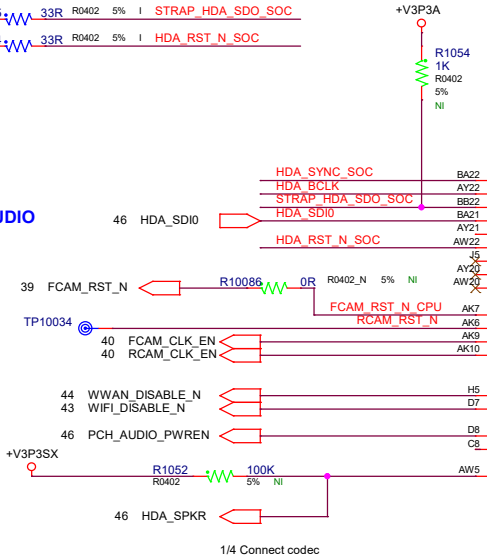
37.50 ME_Flash_EN  R9848 R0402_N 5% I STRAP_HDA_SDO_SOC

Difference with armour
Add EC to enable ME override

5/23 R9848 install BIOS request



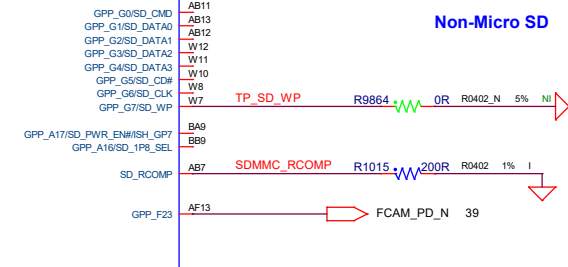
HDA for AUDIO



+V3P3A 3,4,5,7,9,10,11,23,24,29,31,37,38,42,47,49,50,51,52,53,56,60,62,65,66,67
+V3P3SX 5,7,9,10,23,26,30,31,36,37,38,39,40,41,43,44,45,46

HDA_SDO/ I2S_TXD0	Flash Descriptor Security Override	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Enable security measures defined in the Flash Descriptor. (Default) 1 = Disable Flash Descriptor Security (override). This strap should only be asserted high using external pull-up in manufacturing/debug environments ONLY. Notes: - The internal pull-down is disabled after PLTRST# de-asserts. - Asserting HDA_SDO high on the rising edge of PCH_PWROK will also halt Intel Management Engine after Chipset bring up and disable runtime Intel ME features. This is a debug mode and must not be asserted after manufacturing/debug. - This signal is in the primary well.
SPKR / GPP_B14	Top Swap Override	Rising edge of PCH_PWROK	The signal has a weak internal pull-down. 0 = Disable "Top Swap" mode. (Default) 1 = Enable "Top Swap" mode. This inverts an address on access to SPI and firmware hub, so the processor believes it fetches the alternate boot block instead of the original boot-block. PCH will invert A16 (default) for cycles going to the upper two 64-KB blocks in the FWI or the appropriate address lines (A16, A17, or A18) as selected in Top Swap Block size soft strap. Notes: - The internal pull-down is disabled after PLTRST# de-asserts. - Software will not be able to clear the Top Swap bit until the system is rebooted. - The status of this strap is readable using the Top Swap bit (Bus0, Device31, Function0, offset DCH, bit4). - This signal is in the primary well.

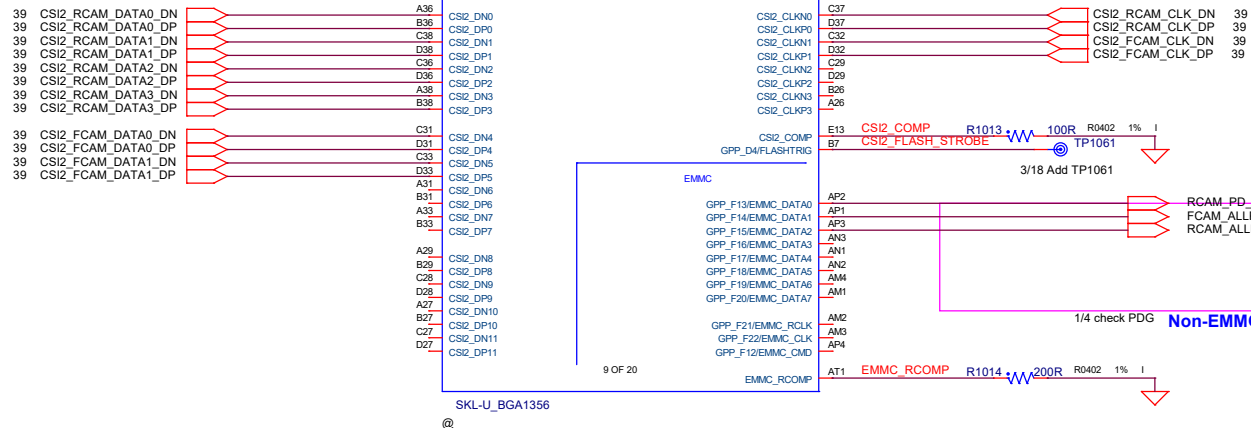
Non-Micro SD



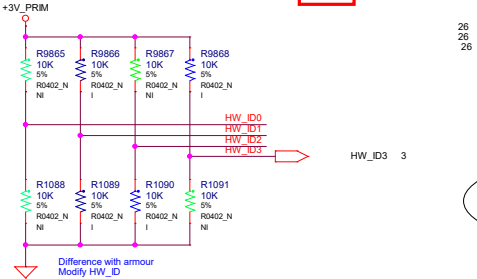
Difference with armour
Add 0ohm NI

Rear Camera1 8M

Front Camera 5M

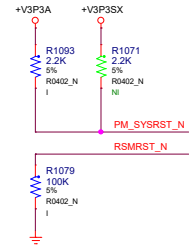
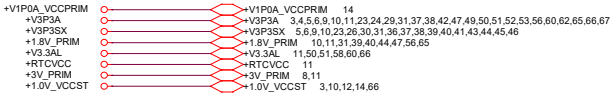


	SDV	STV	STT	SVT
HW_ID0	0	1	0	1
HW_ID1	0	0	1	1

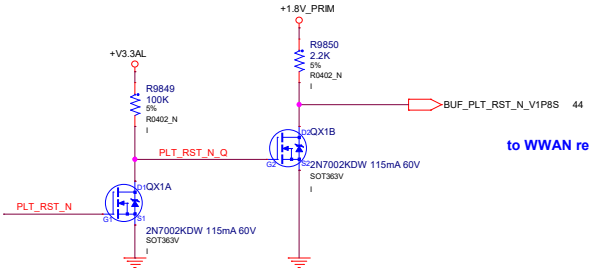


	TPM U9505	non-TPM U9505	non FP sensor	have FP sensor
HW_ID2	0	1	0	1
HW_ID3	0	1	0	1

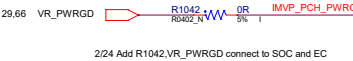
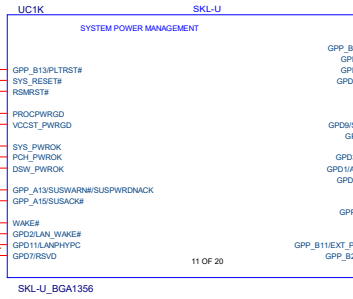
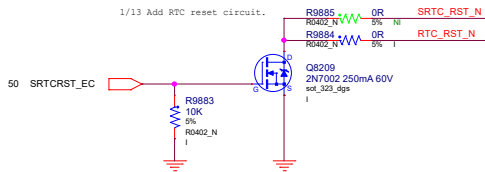
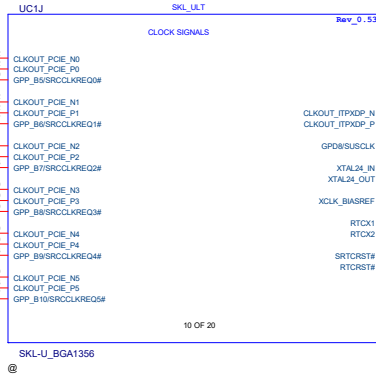
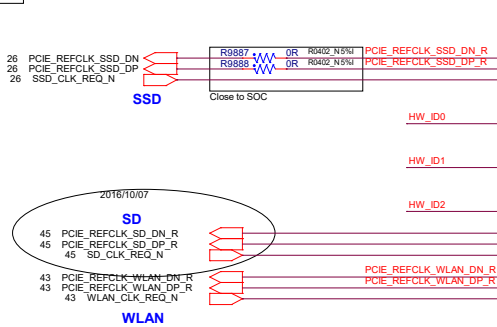
5/30 HW_ID3 add SAR sensor to decide on driver request



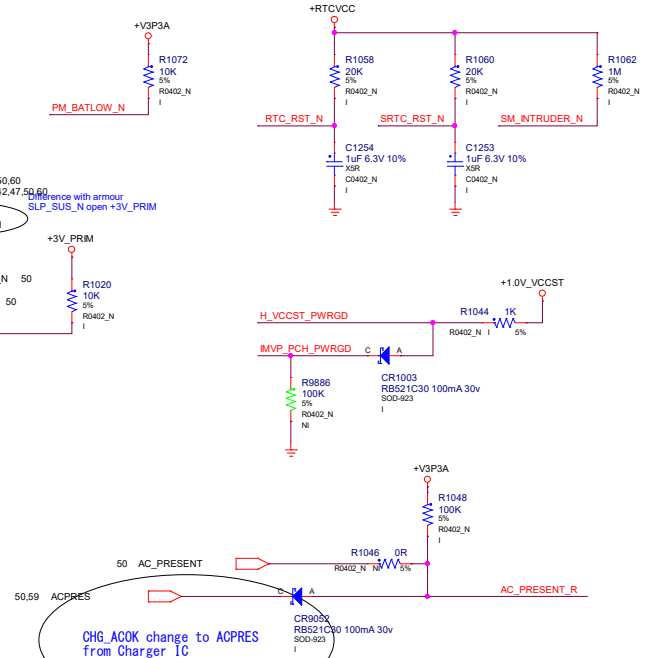
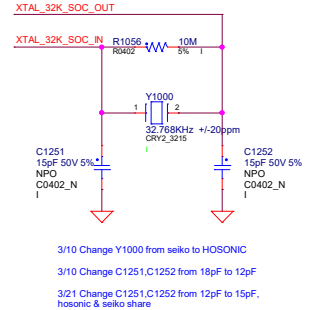
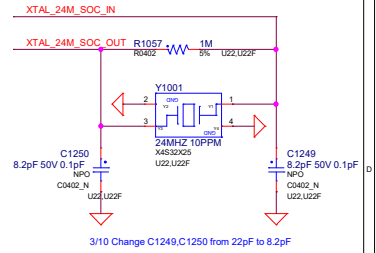
Difference with armour
Del U1201 Low-power buffer(74AUP1G07GW)
and add Dual MOS to change level

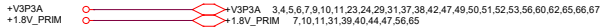
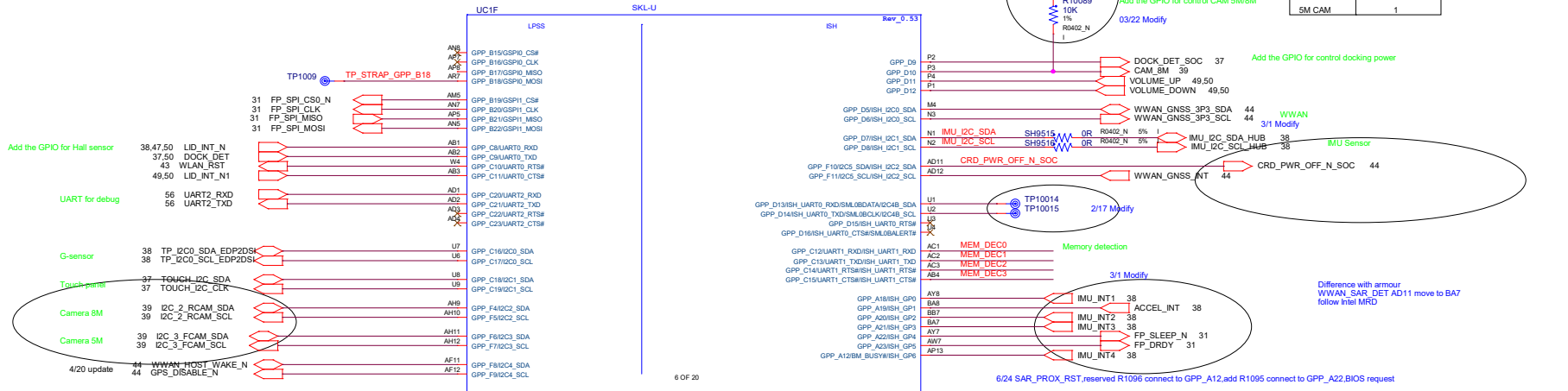


to WWAN reset pin



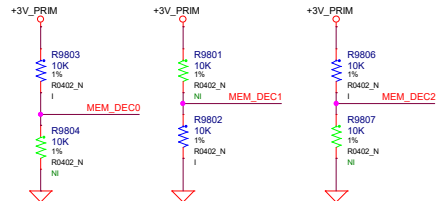
22/4 Add R1042.VR_PWRGD connect to SOC and EC



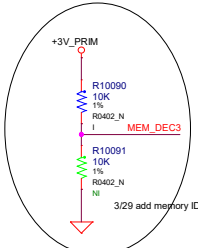


Memory Detection

3/2 Change memory ID PU from +1.8V_PRIM to +3V_PRIM



Mem_DEC3	Voltage
One Channel	0V
Two Channel	3.3V



Default

GSPi0_MOSI / GPP_B18	No Reboot	Rising edge of PCH_PWR0K	The signal has a weak internal pull-down. 0 = Disable "No Reboot" mode. (Default) 1 = Enable "No Reboot" mode (PCH will disable the TCO Timer system reboot feature). This function is useful when running ITP/XDP. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.						
GSPi1_MOSI / GPP_B22	Boot BIOS Strap Bit BBS	Rising edge of PCH_PWR0K	This Signal has a weak internal pull-down. This field determines the destination of accesses to the BIOS memory range. Also controllable using Boot BIOS Destination bit (Bus0, Device31, Function0, offset BCh, bit 6). <table><tr><th>Bit 6</th><th>Boot BIOS Destination</th></tr><tr><td>0</td><td>SPI (Default)</td></tr><tr><td>1</td><td>LPC</td></tr></table> Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. If option 1 (LPC) is selected, BIOS may still be placed on LPC, but all platforms are required to have SPI flash connected directly to the PCH's SPI bus with a valid descriptor in order to boot. 3. Boot BIOS Destination select to LPC by functional strap or using Boot BIOS Destination bit will not affect SPI accesses initiated by Intel ME or Integrated GbE LAN. 4. This signal is in the primary well.	Bit 6	Boot BIOS Destination	0	SPI (Default)	1	LPC
Bit 6	Boot BIOS Destination								
0	SPI (Default)								
1	LPC								

	Hynix 4GB SDP	Micron 4GB SDP	Samsung 4GB SDP	Hynix 8GB DDP	Micron 8GB DDP	Samsung 8GB DDP	Hynix 8GB SDP	Micron 8GB SDP	Samsung 8GB SDP	Hynix 16GB DDP	Micron 16GB DDP	Samsung 16GB DDP
MEM_DEC0	0	1	0	1	0	1	0	1	0	1	0	1
MEM_DEC1	0	0	1	1	0	0	0	0	1	1	0	0
MEM_DEC2	0	0	0	0	1	1	0	0	0	0	1	1
MEM_DEC3	0	0	0	0	0	0	1	1	1	1	1	1

MB	CPU	Intel Core i3-6006U	Intel Core i3-7100U	Intel Core i5-8200U	Intel Core i7-8500U
RAM	Samsung 4G 4*1GB	Hynix 4G 4*1GB	Samsung 8G 4*2GB	Micron 16G 8*2GB	
TPM	国名技术 HW	Infineon HW	国名技术 HW	Infineon HW	

RAM	8Gb*16 DDR4 2400 SDRAM (单颗容量 1GB)	Samsung	K4A8G165WC-BCRC	BS	1	(C/8Gb /18nm/SDP)	SM30N71798
		Micron	MT40A512M16LY-075.H	BS	2	(1xnm/Z11C/8Gb*16/SDP)	SM30K25300
		Hynix	H5AN8G6NAFR-UHC	BS	3		SM30L08875
	16Gb*16 DDR4 2400 SDRAM (单颗容量 2GB)	Samsung	K4AAG165WB-MCRC	BS	1	(B/8Gb /20nm/DDP)	SM30L08872
		Hynix	H5ANAG6NAMR-UHC	BS	3	(A/8Gb /22nm/DDP)	SM30N07785
		Micron	MT40A1G16WBU-083E-B	BS	2	(Z01A/8Gb/20nm/DDP)	SM30L08873

Table 1-3. PCH HSIO Detail

SKU	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
Base-U	USB 3.0/ OTG	USB 3.0/ SSIC	USB 3.0	USB 3.0	PCIe*	PCIe	PCIe/ LAN	PCIe/ LAN	PCIe/ LAN	PCIe/ LAN	SATA	SATA	PCIe/ LAN	PCIe/ LAN	PCIe	PCIe
Premium-U	USB 3.0/ OTG	USB 3.0/ SSIC	USB 3.0	USB 3.0	PCIe*	PCIe/ USB 3.0	PCIe/ LAN	PCIe/ LAN	PCIe/ LAN	PCIe/ LAN	PCIe/ SATA	PCIe/ SATA	PCIe/ LAN	PCIe/ LAN	PCIe/ SATA	PCIe/ SATA
Premium-Y	USB 3.0/ OTG	USB 3.0/ SSIC	USB 3.0	USB 3.0	PCIe*	PCIe/ USB 3.0	PCIe/ LAN	PCIe/ LAN	PCIe/ LAN	PCIe/ LAN	PCIe/ SATA	PCIe/ SATA	PCIe/ LAN	PCIe/ LAN	N/A	N/A

NGFF WIFI Module

5/4 WIFI PCIe port 8 change to port 4, because PCH HSIO 8 can use PCIe interface (for Base-U)

45 PCIe_SD_LN0_RX_SOC_DN
45 PCIe_SD_LN0_RX_SOC_DP
45 PCIe_SD_LN0_TX_SOC_DN
45 PCIe_SD_LN0_TX_SOC_DP

C9586 0.22uF 10V 10% C0402 NX5R I CPU_SD_TX_DN
C9587 0.22uF 10V 10% C0402 NX5R I CPU_SD_TX_DP

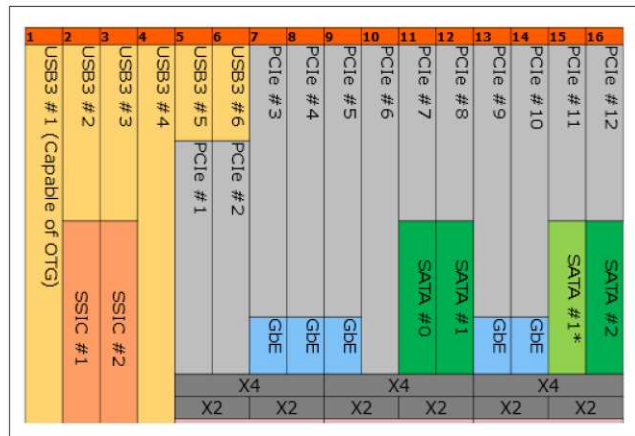
2016/10/07

NGFF SSD

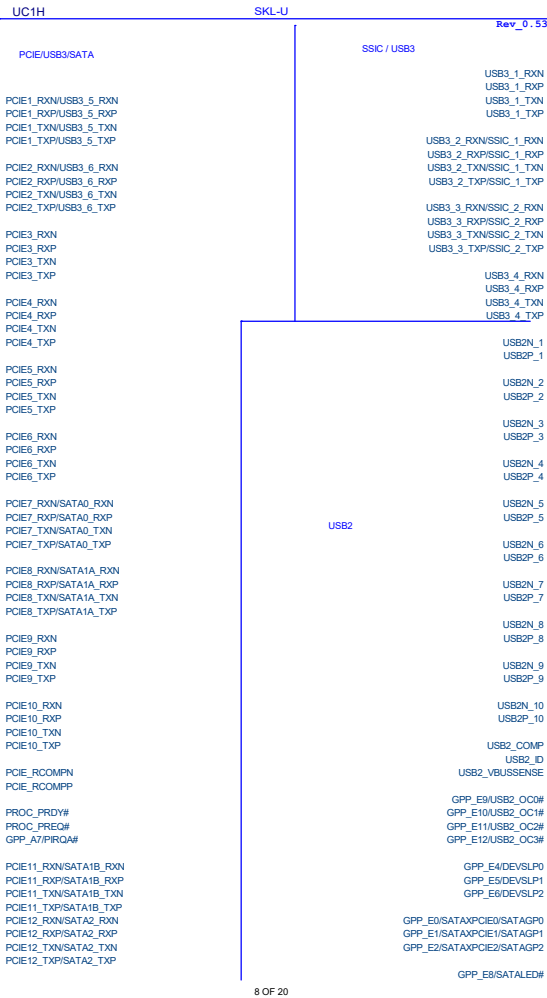
Difference with armour
SSD interface SATA change to PCIe
SATA1A change to PCIe port 9,10,11,12

Checklist
Gen1 and Gen2=100nF
Gen3=220nF

High Speed I/O (HSIO) Lane Multiplexing in SKL-U



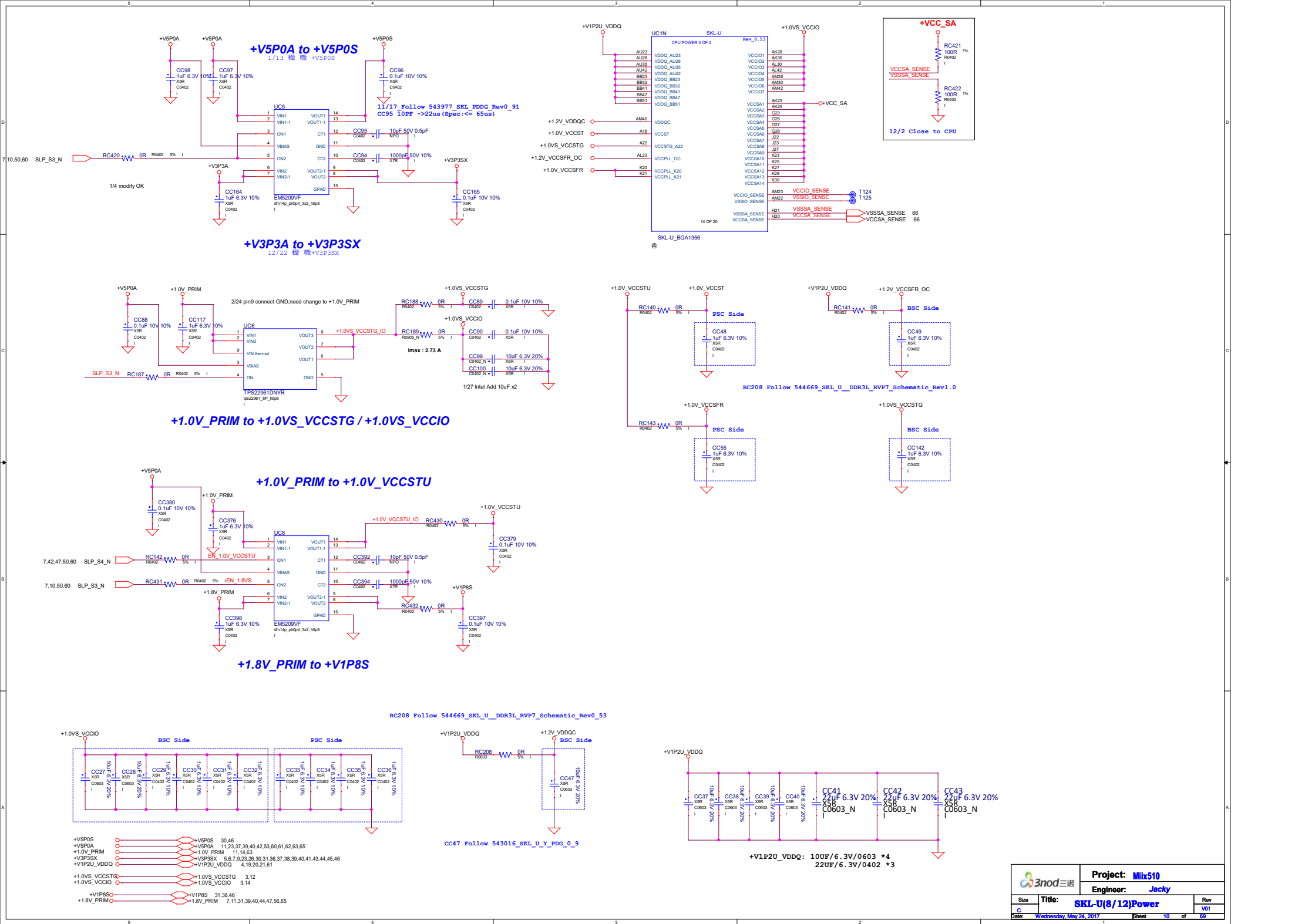
+V3P3A 3 4,5,6,7,10,11,23,24,29,31,37,38,42,47,49,50,51,52,53,56,60,62,65,66,67
+V3P3SX 5,6,7,10,23,26,30,31,36,37,38,39,40,41,43,44,45,46



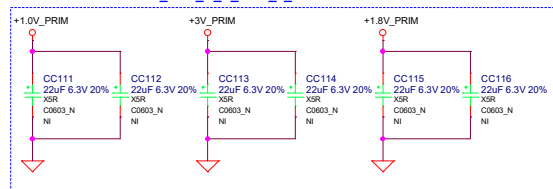
GPIO	DEVICE CONTROL
USB_OC0#	Type C
USB_OC1#	USB2 Port 2
USB_OC2#	NA
USB_OC3#	WWAN_PWR_ON
DEVSLP0	NA
DEVSLP1	NA
DEVSLP2	NGFF SSD KEY M
SATA_GP0	NA
SATA_GP1	NA
SATA_GP2	SSD_SATA_PCIE_DET_N



NOTE:
USE FITC TO ALLOW SELECTION OF
PCIe VS SATA BASED ON STRAPPING:
GPP_E_2 FOR SATA2/PCIe:
1 - SATA2, 0 - PCIe P9,P10,P11,P12



Follow 543016_SKL_U_Y_PDG_0_9



Follow 543016_SKL_U_Y_PDG_0_9

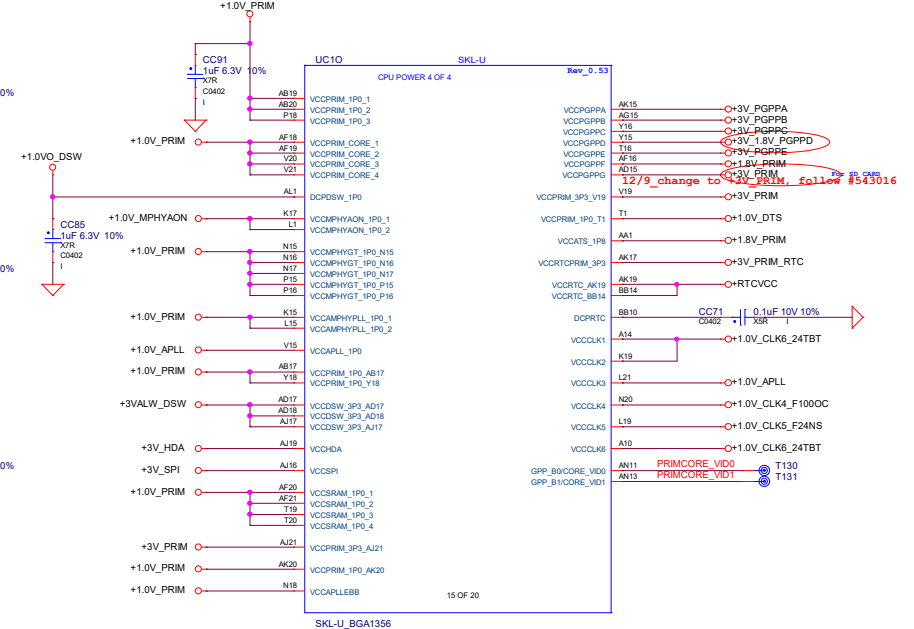
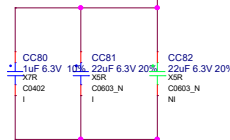
near pin K15, L15

near pin N18

near pin AF20,
AF21, T19, T20

near pin N15, N16
N17, P15, P16

Intel review: need close to pin AA1



RTC Battery

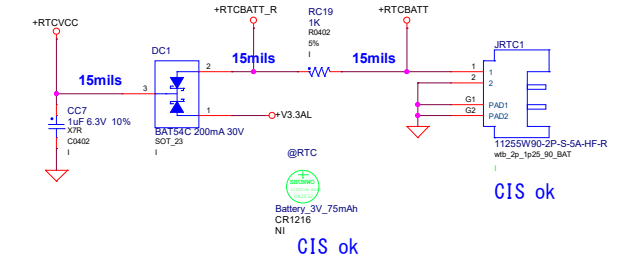
3/9 Del RC429,don't connect to BATT_RTC

Per 543016_SKL_U_Y_PDG_0_9

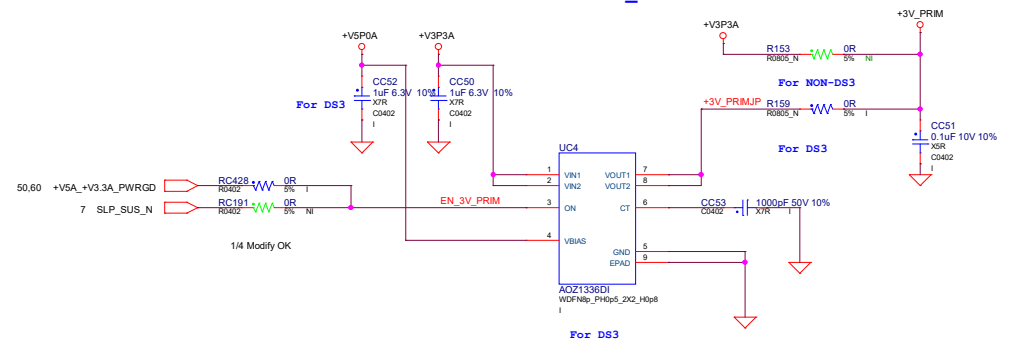
VCCRTC does not exceed 3.2 V From PD0

Power Rail	Voltage
+CHGRTC	3.383V (MAX)
BAT54C (VF)	240 mV
+3VL_RTC	3.143V
Result : Pass	

CC7 Close UC1.AK19.

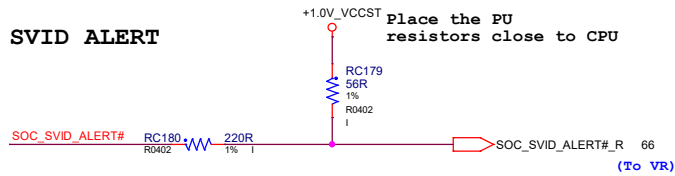


+V3P3A to +3V_PRIM

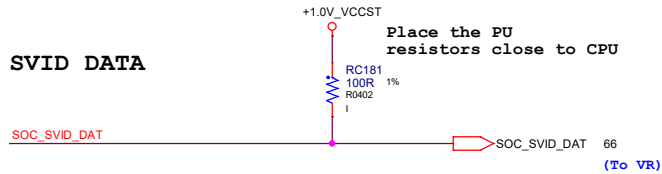


For CPU2+3e SKU

SVID ALERT



SVID DATA



+VCC_CORE 15.67
+1.0VS_VCCSTG 3.10
+VCC_GT 15.67
+1.0V_VCCST 3.7,10,14,66

Trace Length < 25 mils

Trace Length < 25 mils

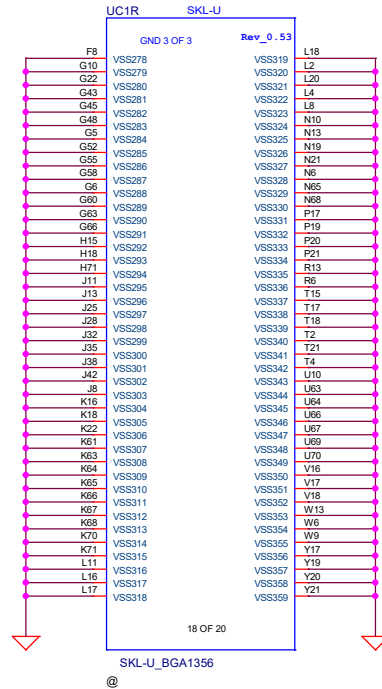
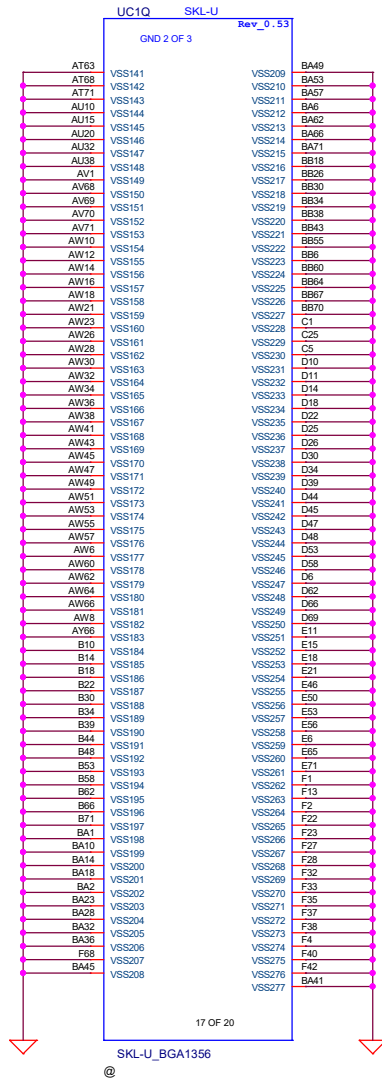
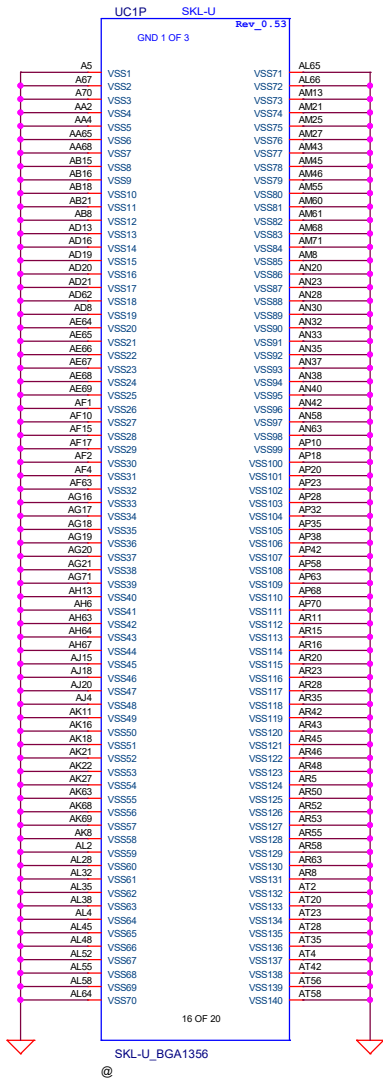
12/2 Close to CPU

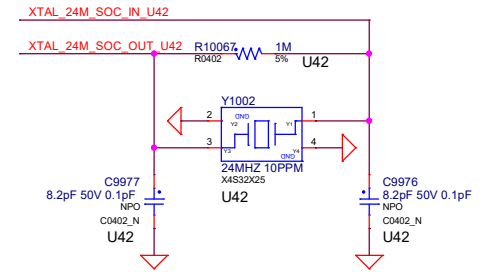
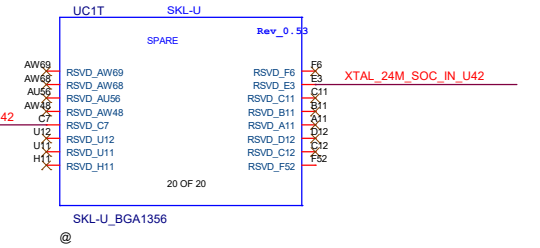
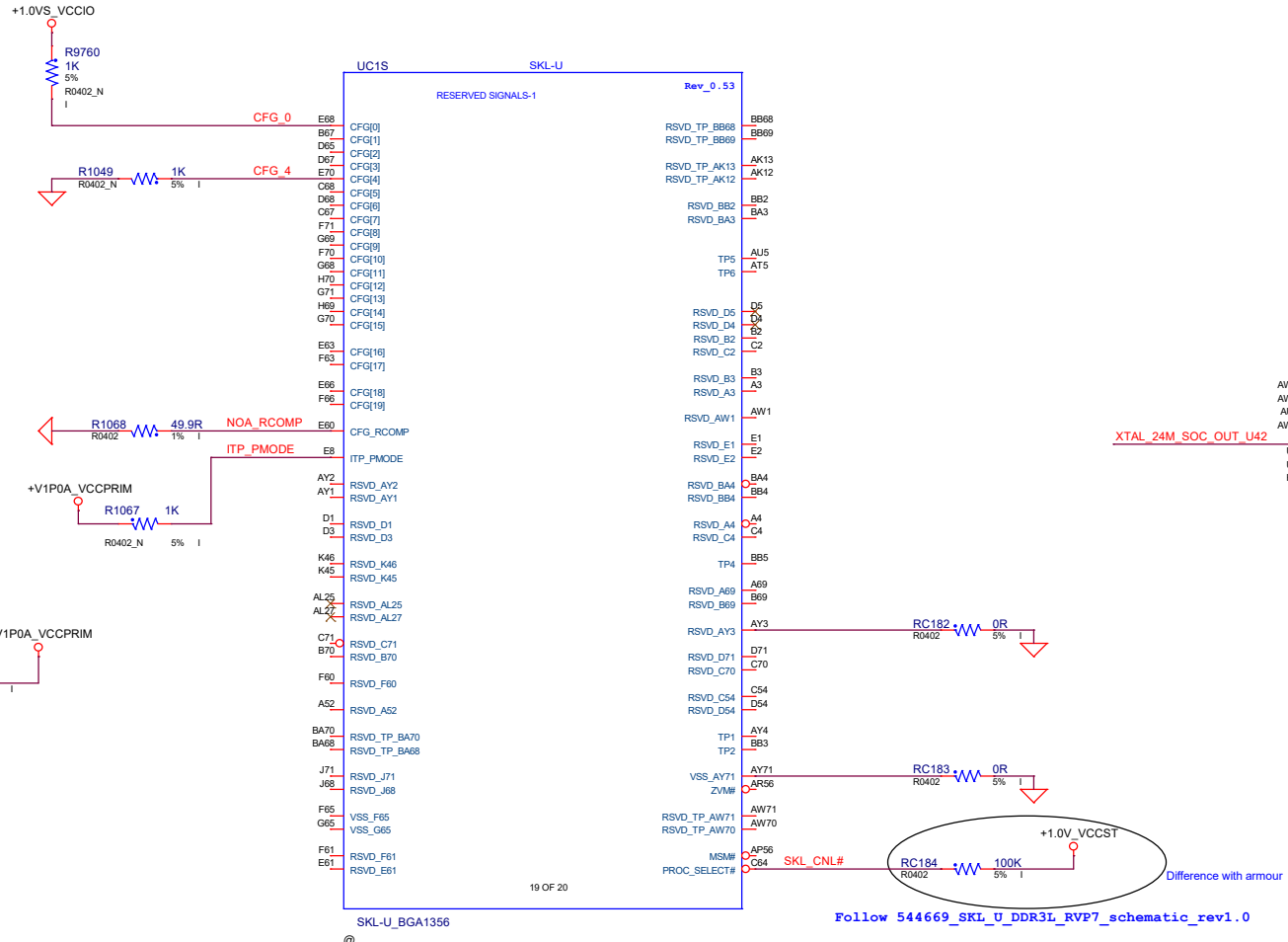
Package Sensing Recommendations

Power Rail Sense Line	R1, R2	Trace Impedance	Trace Length Match
Vcc_SENSE / Vss_SENSE	100Ω	50Ω	<25 mils
VccGT_SENSE / VssGT_SENSE			
VccGTx_SENSE / VssGTx_SENSE			
VccSA_SENSE / VssSA_SENSE			
VccIO_SENSE / VssIO_SENSE ^[1]		NA	

Note: [1] Does not apply when rails are merged.

		Project: MiiX510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	SKL-U[10/12]Power,SVID	V01	
Date:	Wednesday, May 24, 2017	Sheet	12 of 69

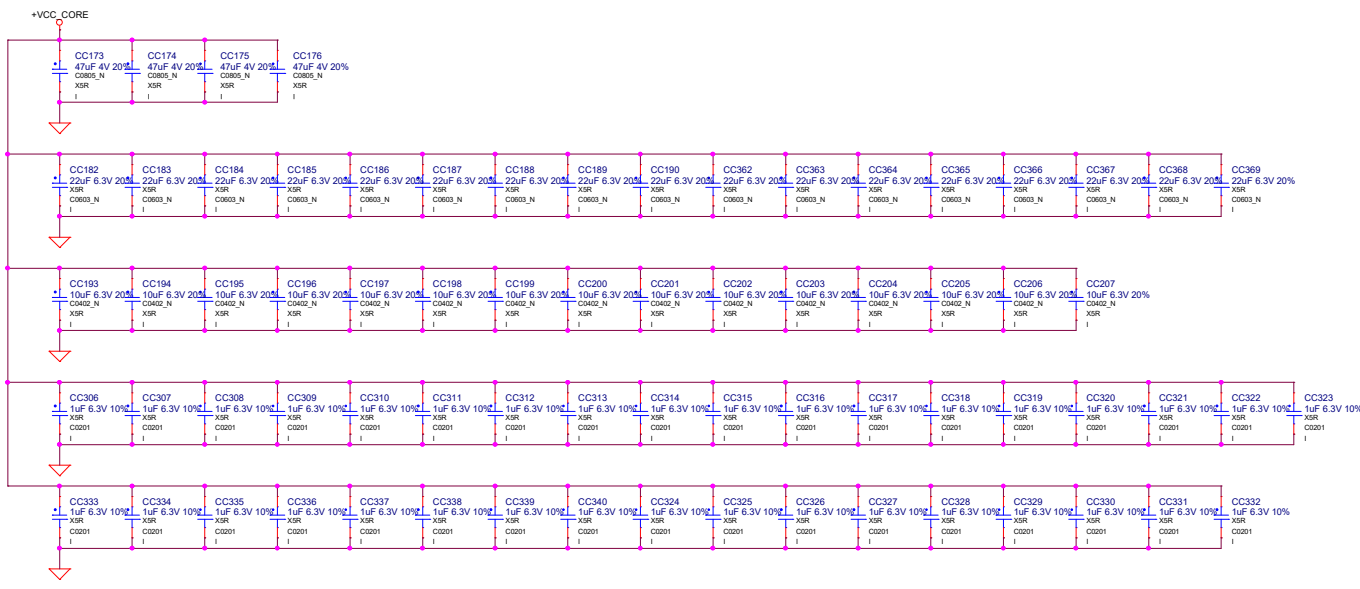




- +1.0V_VCCIO 3.10
- +1.0V_VCCPRIM 7
- +1.0V_PRIM 10,11,63
- +1.0V_VCCST 3,7,10,12,66

For 2+3e Solution
PM_ZVM#
PM_MSM#

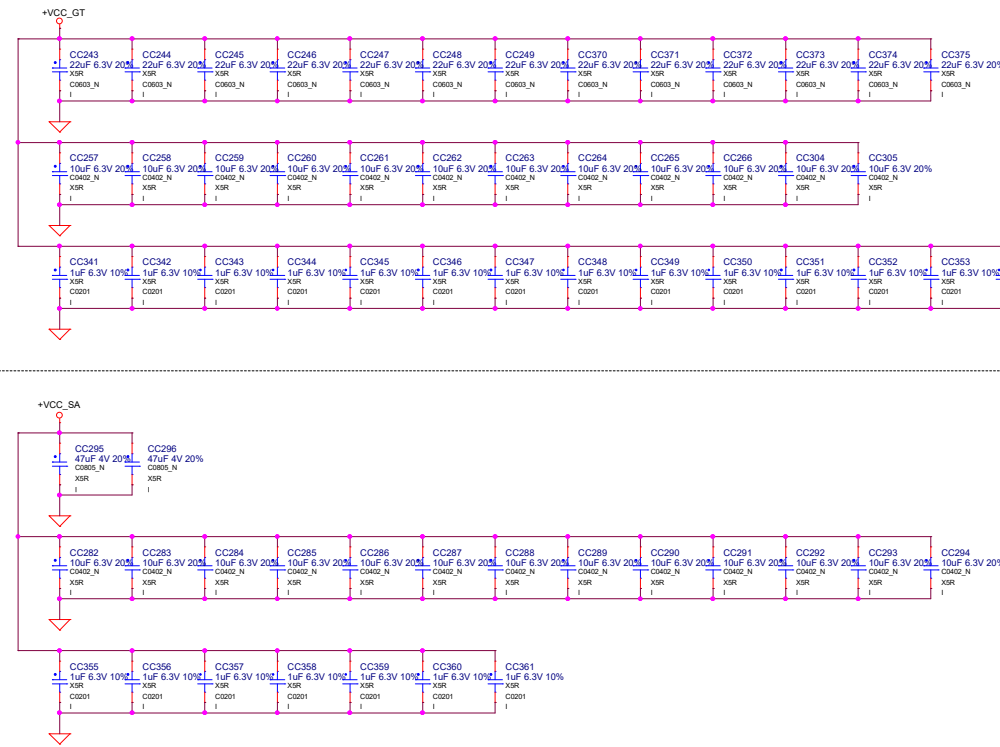
Display Port Presence Strap	
CFG4	1 : Disabled; No Physical Display Port attached to Embedded Display Port 0 : Enabled; An external Display Port device is connected to the Embedded Display Port



12/30 check PD6
& 220uF pull power side

+VCC_CORE
47uF x8
22uF x9
10uF x15
1uF x35

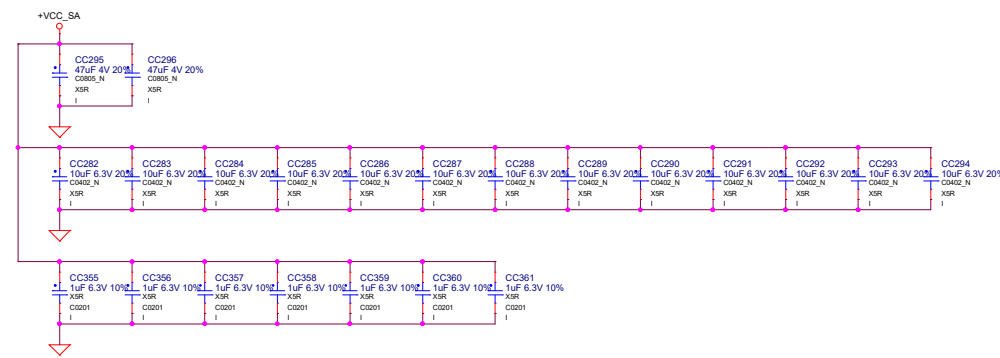
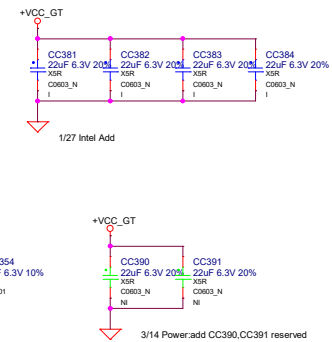
change 47uF x4
cgange 22uF x17



12/30 check PD6
& 220uF pull power side

+VCC_GT
47uF x3
22uF x7
10uF x12
1uF x14

change 47uF x0
cgange 22uF x13



+VCC_SA
47uF x2
10uF x13
1uF x7

12/30 check PD6

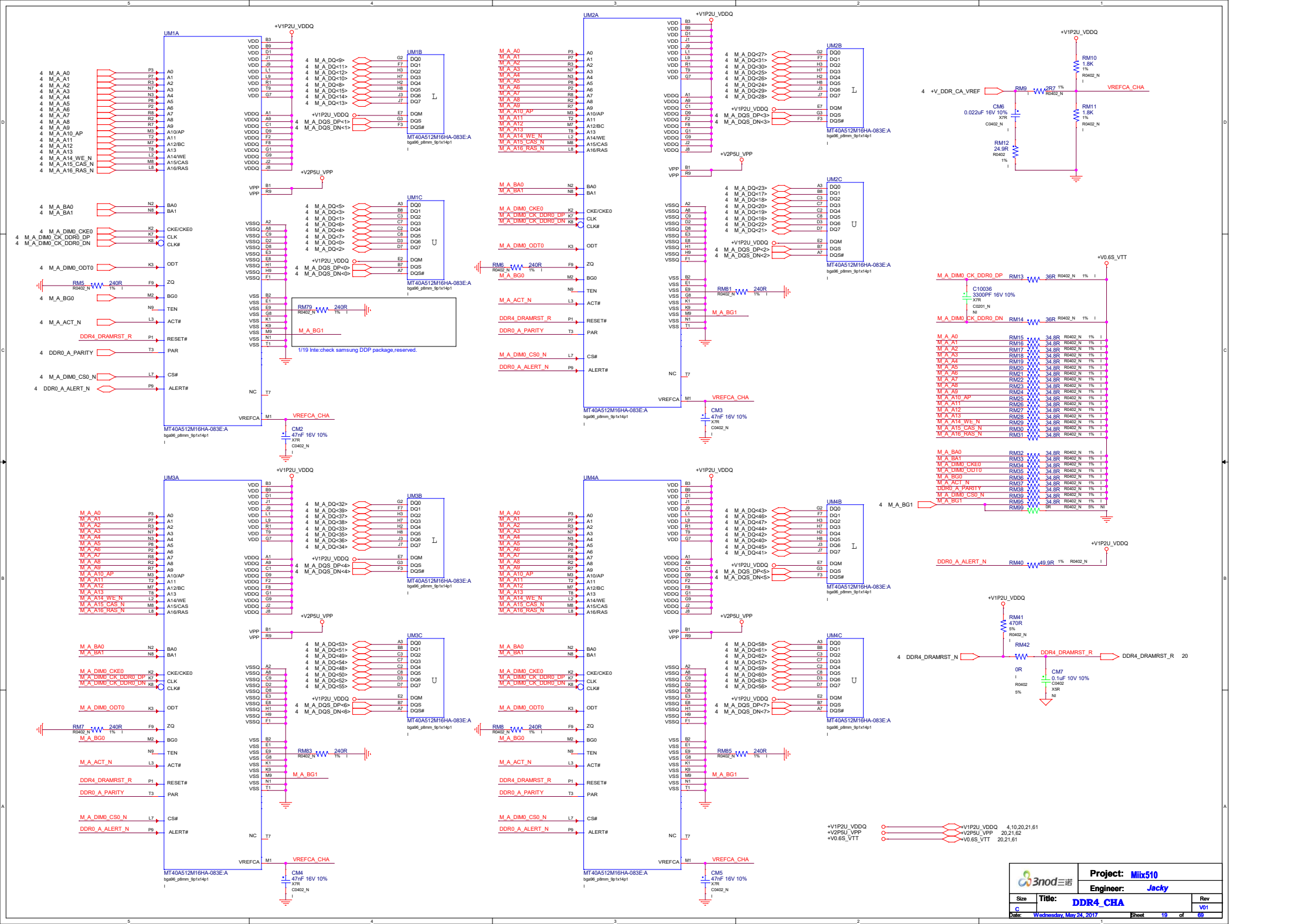
+VCC_CORE 12.67
+VCC_GT 12.67
+VCC_SA 10.23.67

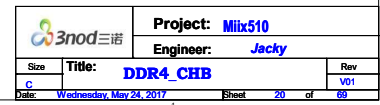
3nod 三诺		Project: Mlix510	
Size		Engineer: Jacky	
Title: SOC (DECOUPLING)		Rev: V01	
Date: Thursday, May 25, 2017	Sheet: 15	of 69	

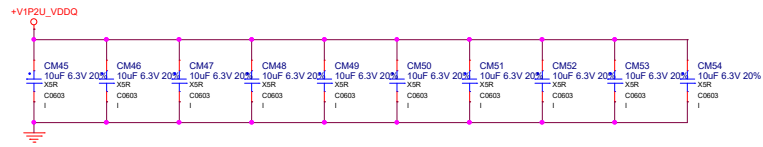
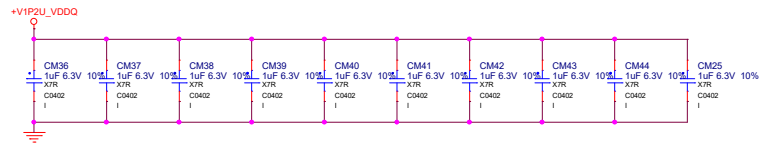
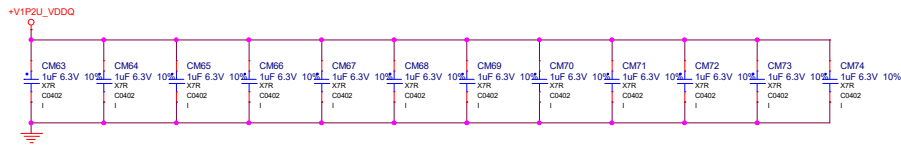
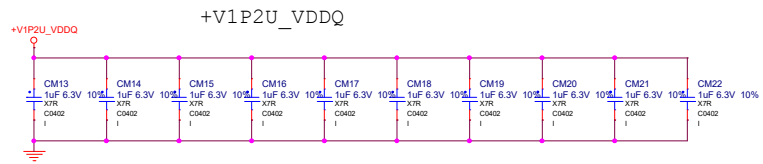
		Project: Miix510	
		Engineer: Jacky	
Size	Title: NA	Rev	
B		V01	
Date:	Wednesday, May 24, 2017	Sheet	16 of 69



		Project: Miix510	
		Engineer: Jacky	
Size	Title: NA		Rev
Custom			V01
Date:	Wednesday, May 24, 2017		Sheet 18 of 69



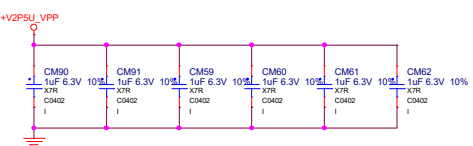
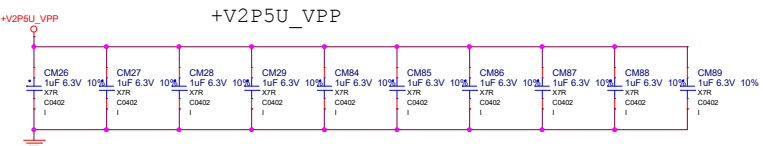




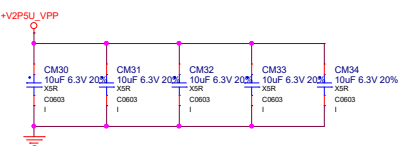
1uF:4 as near each x16
DRAM device as
possible

10uF:Distributed around
the DRAM devices

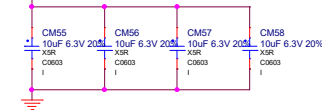
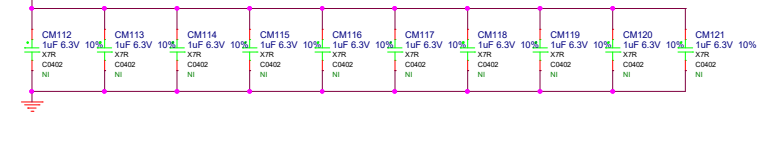
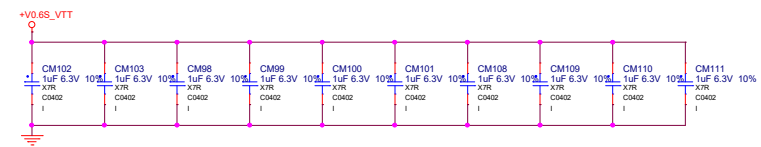
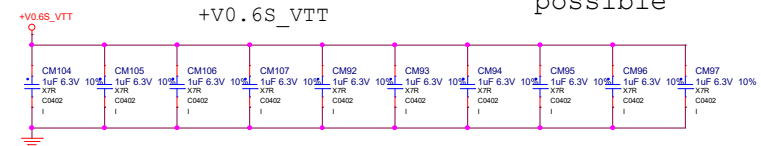
1uF:2 as near each x20
DRAM device as
possible



1uF:2 as near each x16
DRAM device as
possible



10uF:Distributed around
the DRAM devices



10uF:Distributed around
the DRAM devices

+VIP2U_VDDQ
+V2P5U_VPP
+V0.6S_VTT

+VIP2U_VDDQ 4,10,19,20,61
+V2P5U_VPP 19,20,62
+V0.6S_VTT 19,20,61

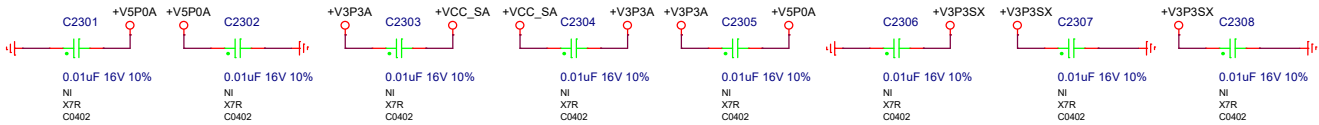


		Project: Miix510	
		Engineer: Jacky	
Size	Title: NA		Rev
Custom			V01
Date:	Wednesday, May 24, 2017		Sheet 22 of 69

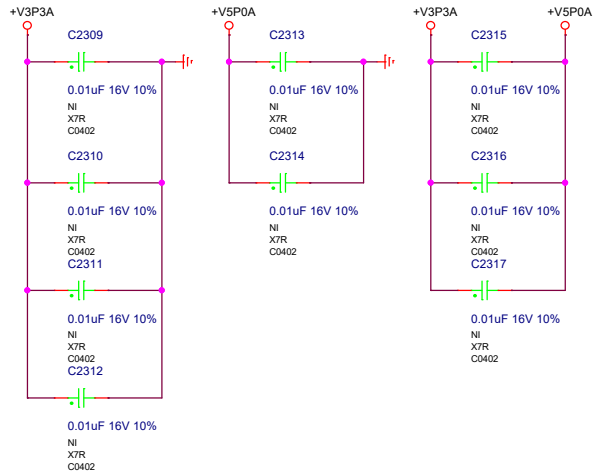
RF Solution

EMC Solution

1/26 EMC reserved



5/16 EMC reserved



D

D

C

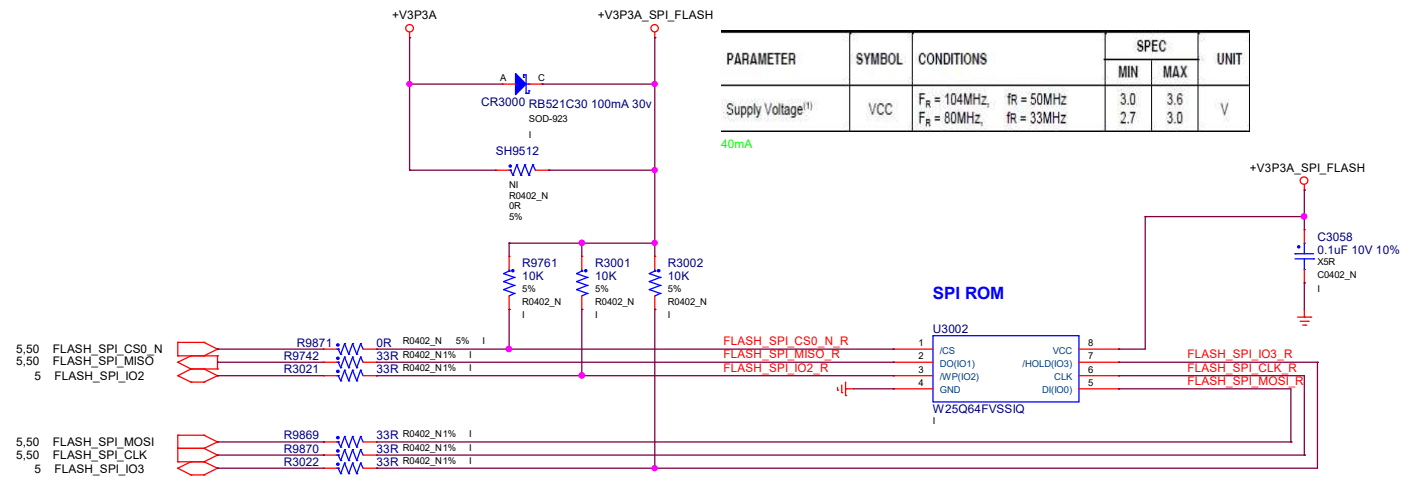
C

B

B

A

A



Difference with ARMOUR
Series-resistor 0R change to 33R

CIS ok
2/24 SIV:Delet ROM Socket @U3002

Difference with ARMOUR
U3002 package DFN8 change to SOP8

+V3P3A
+V3P3A_SPI_FLASH

INTERNAL ONLY

BPAGE DRAWING

sky_y_mrd.GND
Wed Jun 03 11:22:52 2015

		Project: Miix510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	SYSTEM FLASH	V01	
Date:	Wednesday, May 24, 2017	Sheet	24 of 69

<XR_PAGE_TITLE>		7	6	5	4	3	2	1	
D									D
C									C
B									B
A									A
		INTERNAL ONLY				BPAGE DRAWING			
		sky_y_mod.GND				Wed Jun 03 11:22:52 2015			
8	7	6	5	4	3	2	1		

		Project: Miix510	
		Engineer: Jacky	
Size	Title: EMMC		Rev
Custom	Wednesday, May 24, 2017		V01
Date:		Sheet 25	of 69



Project: **Miix510**

Engineer: **Jacky**

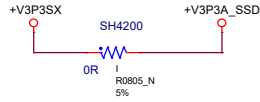
Size	Title: EMMC		Rev
Custom			V01
Date:	Wednesday, May 24, 2017	Sheet	25 of 69

M.2 SSD Module

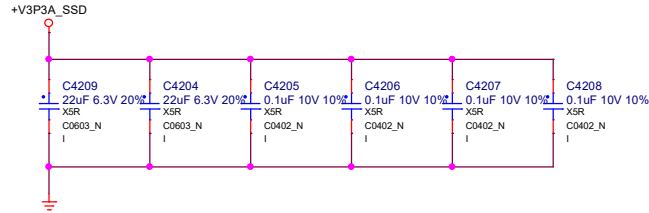
1. 4A @ADATA 128GB SSD
2. 6A @ADATA 256GB SSD

+V3P3SX

+V3P3SX 5,6,7,9,10,23,30,31,36,37,38,39,40,41,43,44,45,46



Change SH4200 0805 shunt to resistor



CIS ok

9 PCIE9_SSD_RX_DN
9 PCIE9_SSD_RX_DP
9 PCIE9_SSD_TX_DN_C
9 PCIE9_SSD_TX_DP_C
9 PCIE10_SSD_RX_DN
9 PCIE10_SSD_RX_DP
9 PCIE10_SSD_TX_DN_C
9 PCIE10_SSD_TX_DP_C
9 PCIE11_SSD_RX_DN
9 PCIE11_SSD_RX_DP
9 PCIE11_SSD_TX_DN_C
9 PCIE11_SSD_TX_DP_C
9 PCIE12_SSD_RX_DP
9 PCIE12_SSD_RX_DN
9 PCIE12_SSD_TX_DN_C
9 PCIE12_SSD_TX_DP_C
7 PCIE_REFCLK_SSD_DN
7 PCIE_REFCLK_SSD_DP

PCIE12 RX follow intel

Difference with intel
SSD interface SATA change to PCIE
If install SATA CARD, R4200, R4201 need install 0.01uF
C0606, C0607 need install 0.01uF

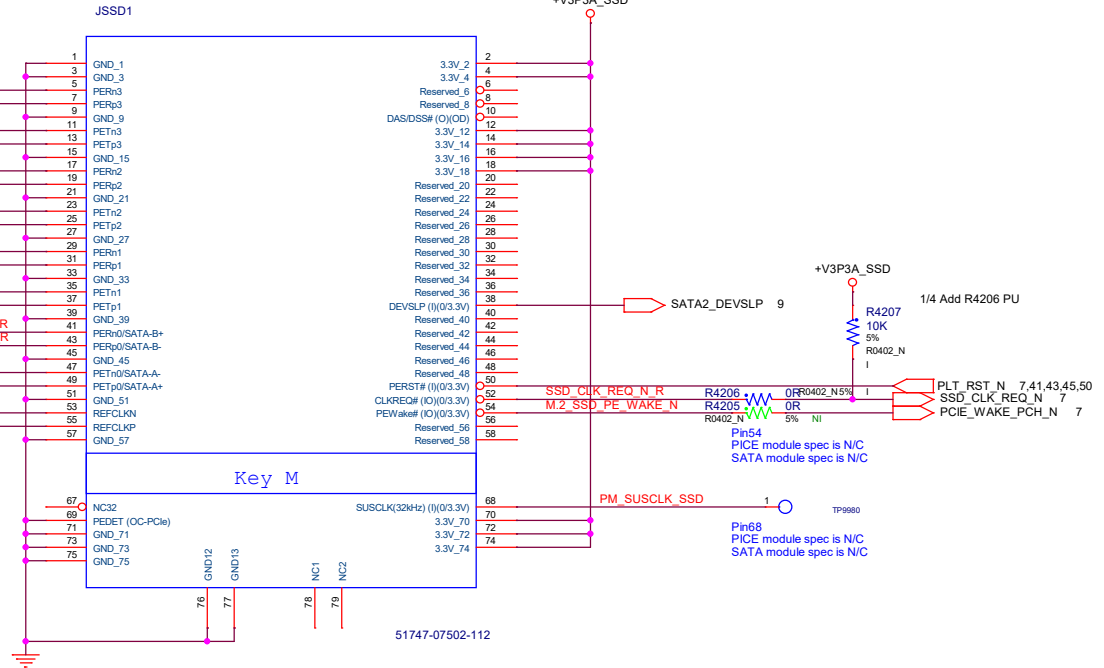
NGFF SSD module interface	PCIE	SATA
Reference	R4200, R4201 install 0ohm C0606, C0607 install 0.22uF	R4200, R4201 install 0.01uF C0606, C0607 install 0.01uF
Detect pin	R1050 install 10Kohm R1087 uninstall 100Kohm	R1050 uninstall 10Kohm R1087 install 100Kohm

Default

3/16 Add SSD(PCIE or SATA) BOM option table

Co-lay PCIE12 RX, reserved R4202, R4203
please close to R4200, R4201

3/9 Del R4202, R4203, don't Co-lay PCIE12 RX



INTERNAL ONLY

BPAGE DRAWING

sky_x_mnt+V3P3.36
Wed Jun 03 11:22:52 2015

		Project: Miix510	
Size: Custom		Engineer: Jacky	
Title: PCIE SSD MODULE		Rev: V01	
Date: Wednesday, May 24, 2017		Sheet 26 of 69	

<XR_PAGE_TITLE>		7	6	5	4	3	2	1	
D									D
C									C
B									B
A									A
8	7	6	5	4	3	2	1		

INTERNAL ONLY

BPAGE DRAWING

sky_y_mod.GND
Wed Jun 03 11:22:53 2015

		Project: Miix510	
		Engineer: Jacky	
Size	Title: MICRO-SD CARD		Rev
Custom	Date: Wednesday, May 24, 2017		V01
		Sheet 27 of	69

INTERNAL ONLY

BPAGE DRAWING

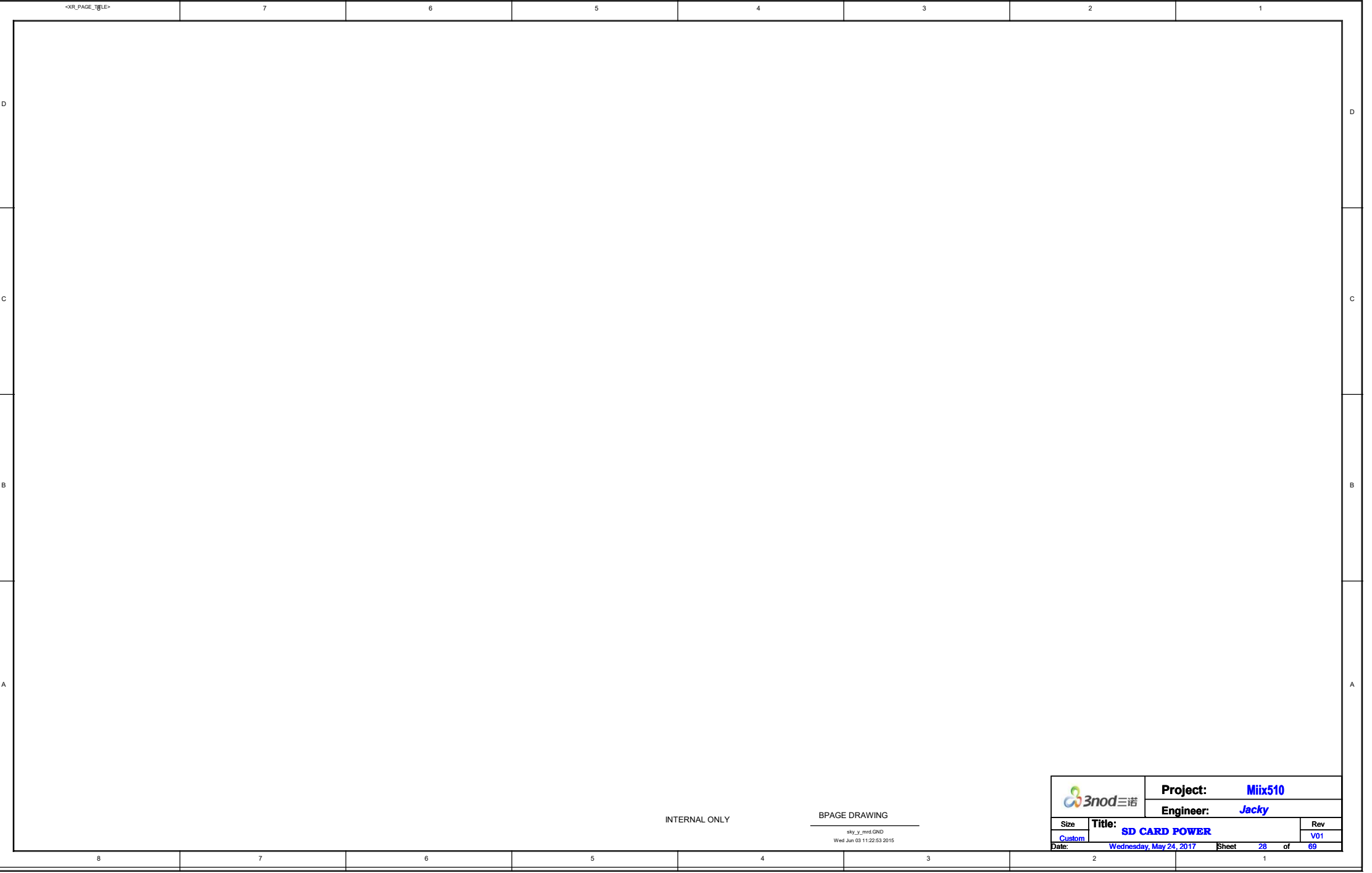
sky_y_mod.GND
Wed Jun 03 11:22:53 2015



Project: **Miix510**

Engineer: **Jacky**

Size	Title:	Rev
Custom	MICRO-SD CARD	V01
Date:	Wednesday, May 24, 2017	Sheet 27 of 69



D

D

C

C

B

B

A

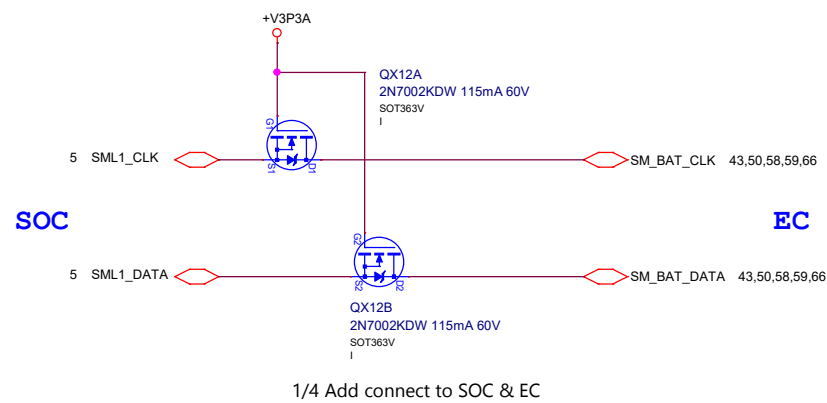
A

INTERNAL ONLY

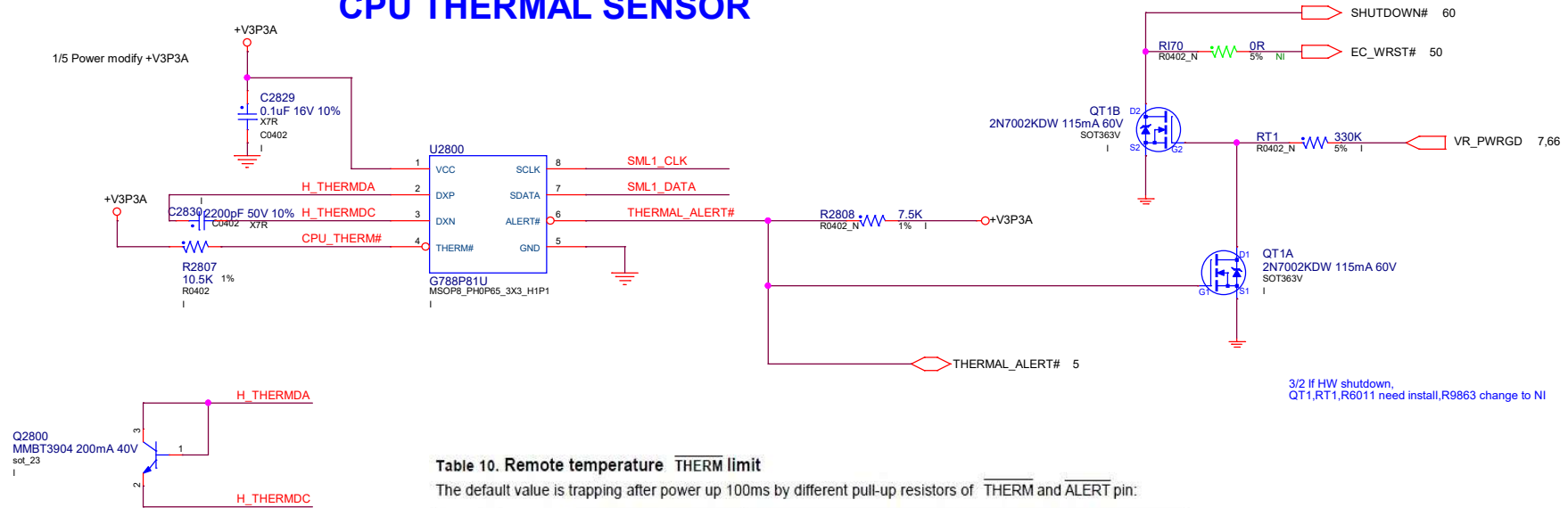
BPAGE DRAWING

sky_y_mind.GND
Wed Jun 03 11:22:53 2015

		Project: Miix510	
		Engineer: Jacky	
Size	Title: SD CARD POWER		Rev
Custom			V01
Date:	Wednesday, May 24, 2017	Sheet	28 of 69

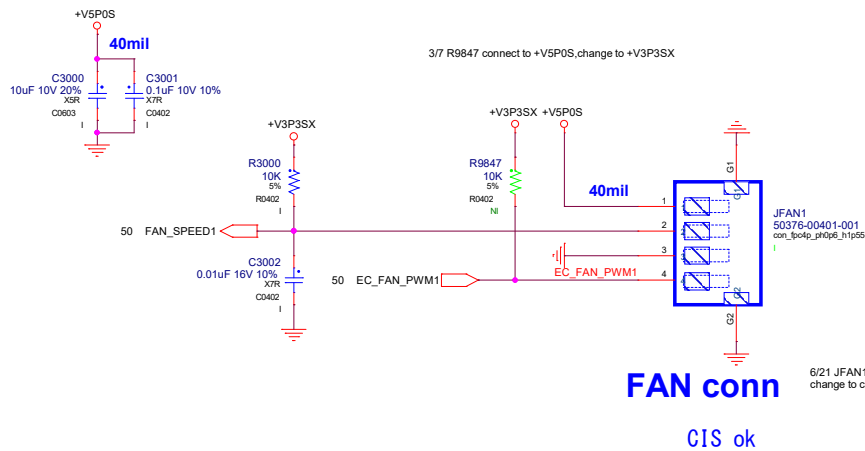


CPU THERMAL SENSOR

Table 10. Remote temperature $\overline{\text{THERM}}$ limit

The default value is trapping after power up 100ms by different pull-up resistors of THERM and ALERT pin:

TEMPERATURE (°C)		THERM				
		2KΩ	7.5KΩ	10.5KΩ	14KΩ	18.7KΩ
ALERT#	2KΩ	77	87	97	107	117
	7.5KΩ	79	89	99	109	119
	10.5KΩ	81	91	101	111	121
	14KΩ	83	93	103	113	123
	18.7KΩ	85	95	105	115	125

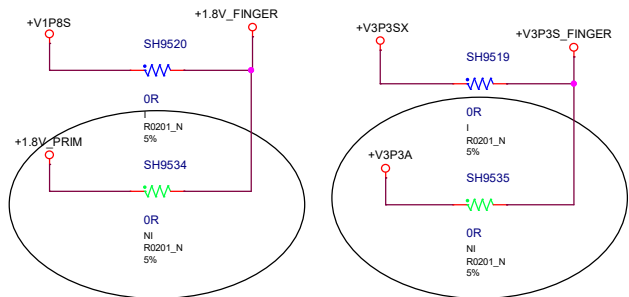


+V5P0S
+V3P3SX

+V5P0S 10.46
+V3P3SX 5,6,7,9,10,23,26,31,36,37,38,39,40,41,43,44,45,46

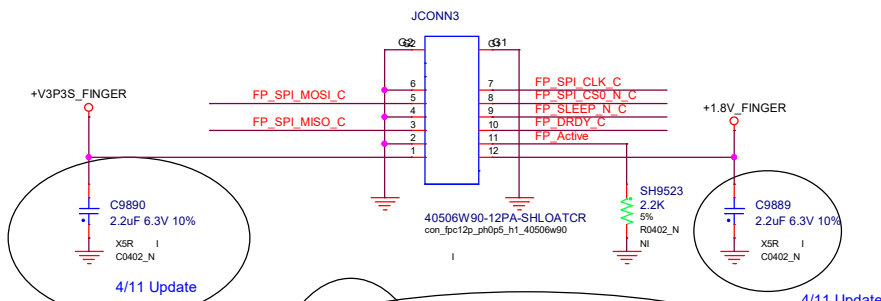
		Project: Miix510	
		Engineer: Jacky	
Size	Title: FAN conn	Rev	
Custom		V01	
Date:	Wednesday, May 24, 2017	Sheet	30 of 69

Fingerprint



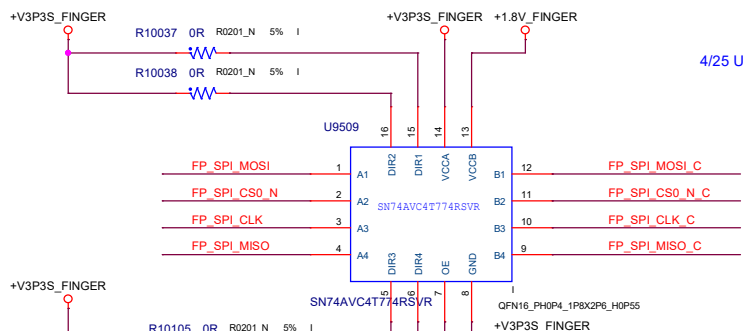
4/11 Support micro stanby function

+V3P3SX 5,6,7,9,10,23,26,30,36,37,38,39,40,41,43,44,45,46
+1.8V_PRIM 7,10,11,39,40,44,47,56,65
+V1P8S 10,38,46

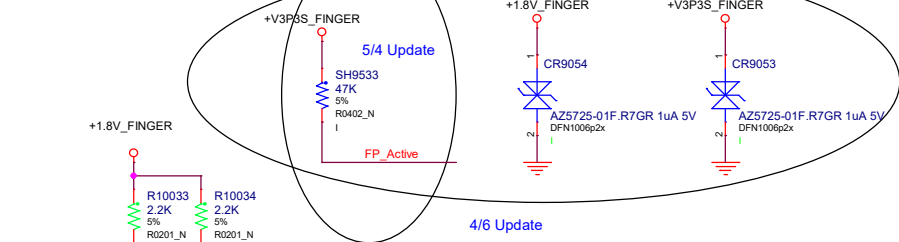


4/11 Update

4/11 Update

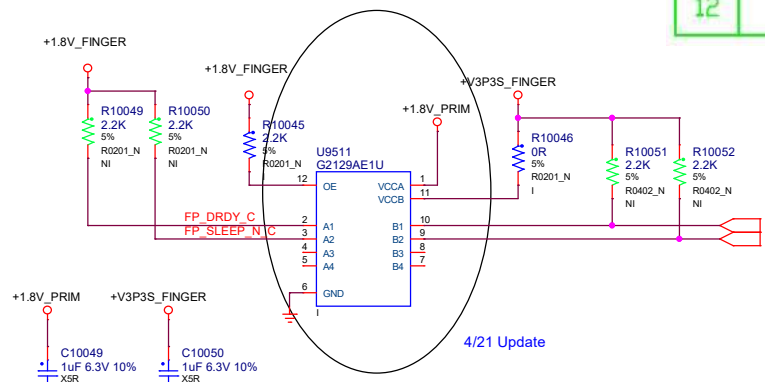
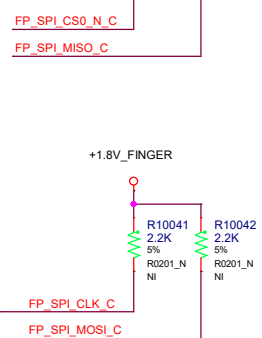
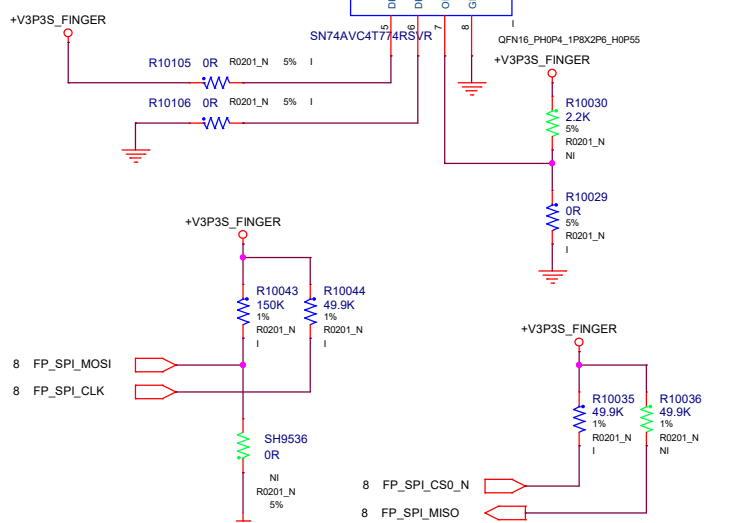


4/25 Update



5/4 Update

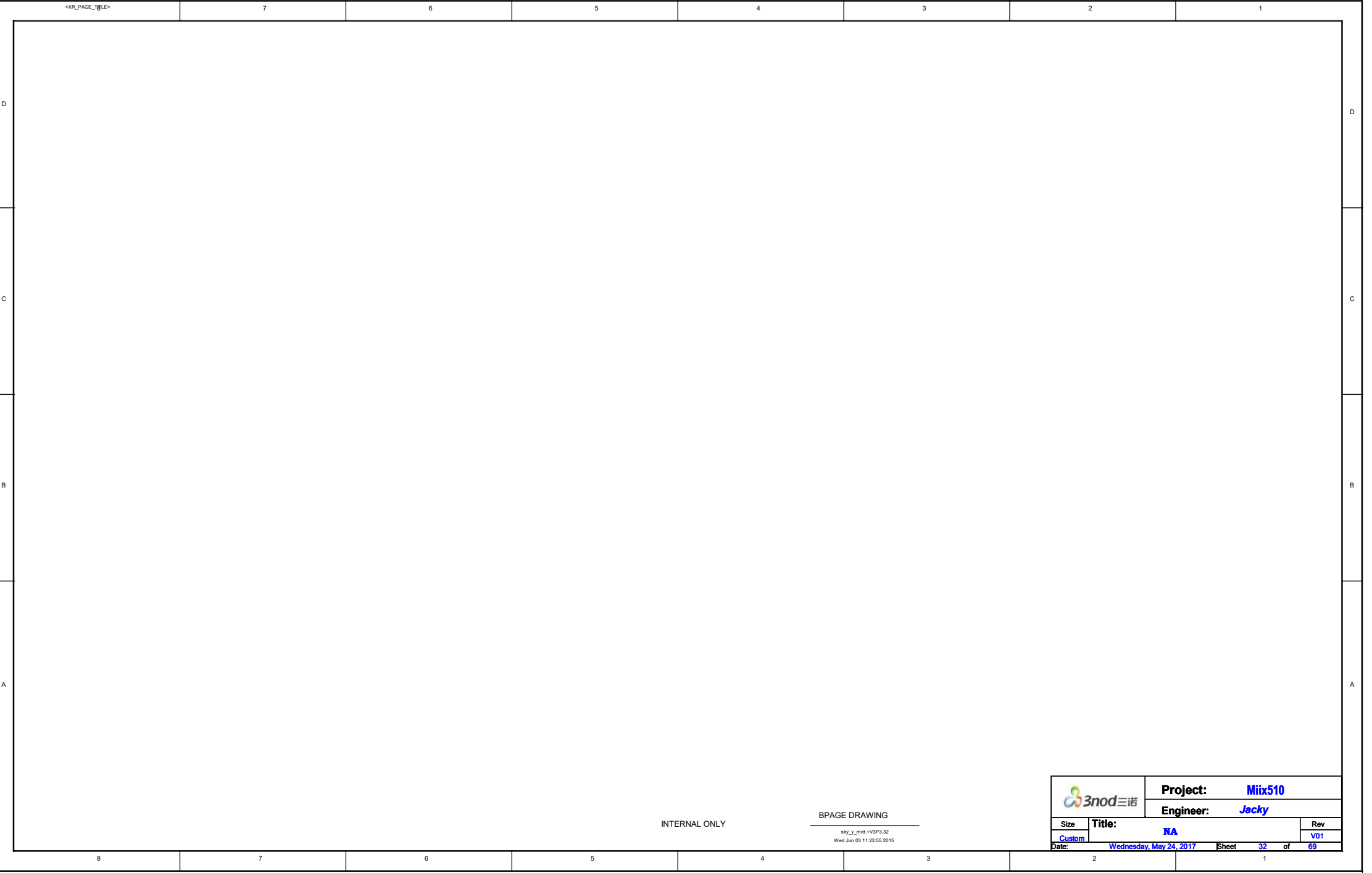
4/6 Update



4/21 Update

PIN define	
1	3.3VCC
2	GND
3	MISO
4	GND
5	MOSI
6	GND
7	CLK
8	CS0_N
9	SLEEP_N
10	DRDY
11	FP_ACTIVE
12	1.8VCC

FP_DRDY 8
FP_SLEEP_N 8



D

C

B

A

D

C

B

A

8 7 6 5 4 3 2 1

INTERNAL ONLY

BPAGE DRAWING

sky_y_mml+V3P3.32
Wed Jun 03 11:22:55 2015

		Project: Miix510	
		Engineer: Jacky	
Size	Title: NA		Rev
Custom			V01
Date:	Wednesday, May 24, 2017		Sheet 32 of 69

<XR_PAGE_TITLE>		7	6	5	4	3	2	1	
D									D
C									C
B									B
A									A
8	7	6	5	4	3	2	1		

3nod三诺

Size

Custom

Title:

HDMI LEVEL SHIFTERS

Date:

Wednesday, May 24, 2017

Project:

Miix510

Engineer:

Jacky

Rev

V01

Sheet

34

of

69

Wed Jun 03 11:22:56 2015

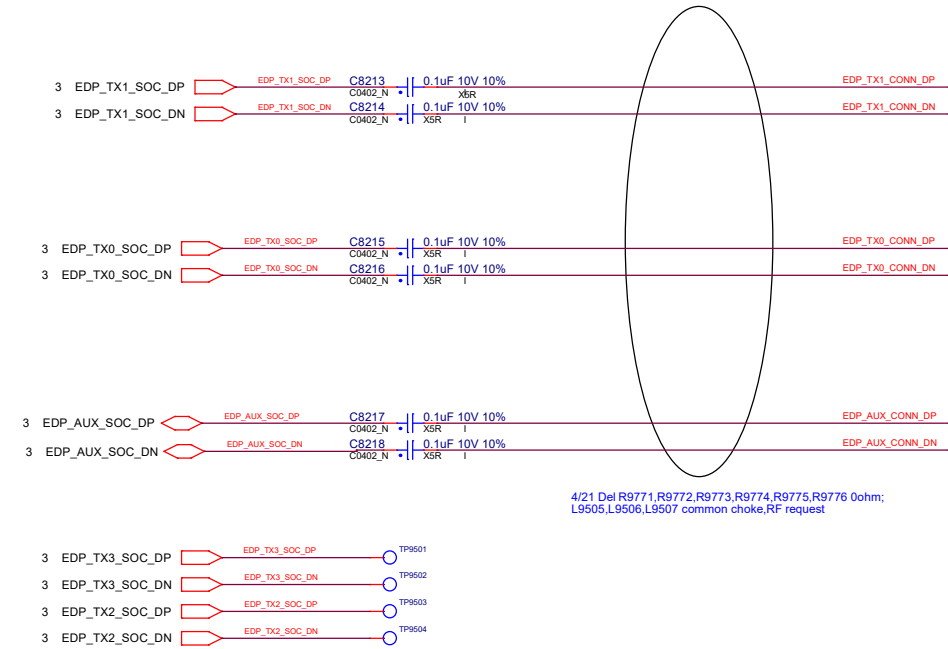
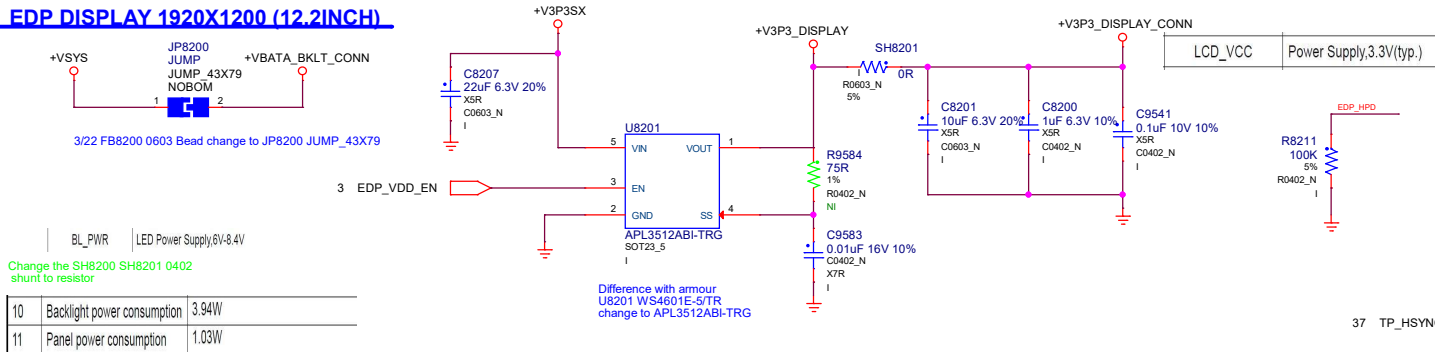
Wed Jun 03 11:22:56 2015

		Project: Miix510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	HDMI LEVEL SHIFTERS	V01	
Date:	Wednesday, May 24, 2017	Sheet	34 of 69

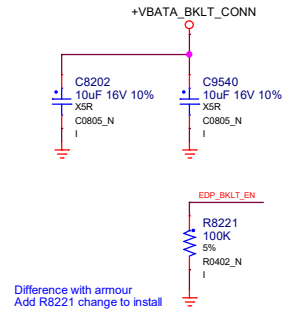


		Project: LENOVO_NB116BT	
		Engineer: Jason	
Size	Title: Sensor & HUB		Rev
Custom			V01
Date: Wednesday, May 24, 2017		Sheet	35 of 69

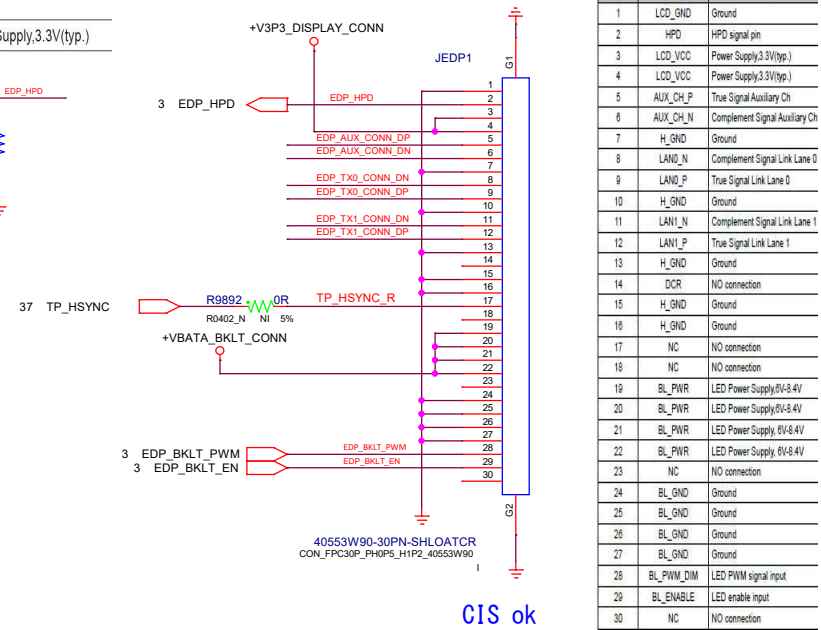
EDP DISPLAY 1920X1200 (12.2INCH)



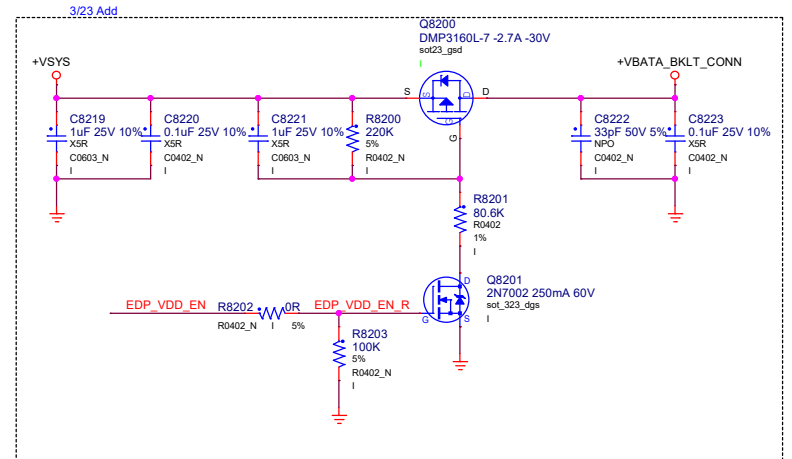
4/21 Del R9771,R9772,R9773,R9774,R9775,R9776 0ohm;
L9505,L9506,L9507 common choke,RF request



BL_PWM_DIM	LED PWM signal input. H=3.3V
BL_ENABLE	LED enable input. H=3.3V

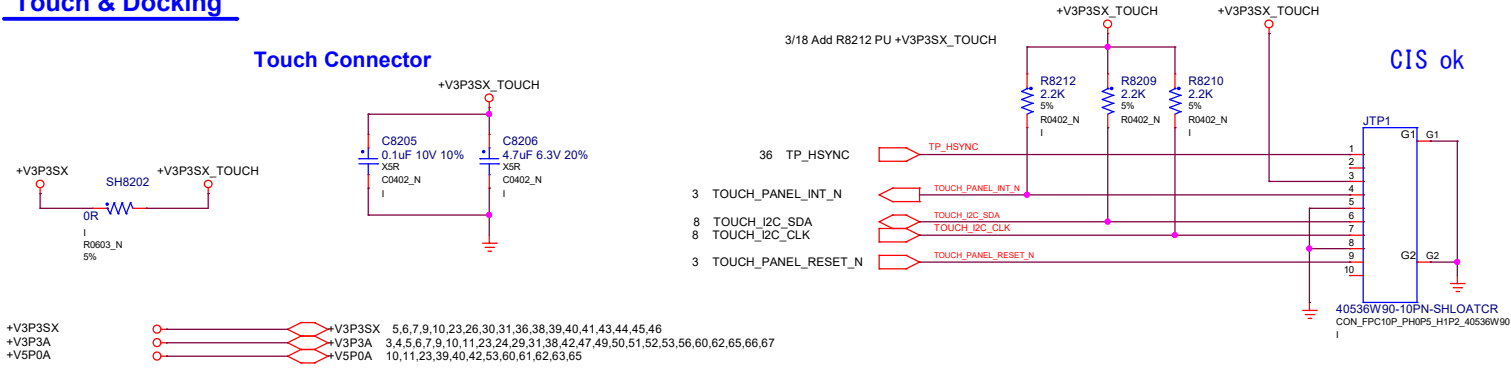


Interface Pin Connection		
Pin No.	Symbol	Function
1	LCD_GND	Ground
2	HPD	HPD signal pin
3	LCD_VCC	Power Supply 3.3V(Ip)
4	LCD_VCC	Power Supply 3.3V(Ip)
5	AUX_CH_P	True Signal Auxiliary Ch
6	AUX_CH_N	Complement Signal Auxiliary Ch
7	H_GND	Ground
8	LAN0_N	Complement Signal Link Lane 0
9	LAN0_P	True Signal Link Lane 0
10	H_GND	Ground
11	LAN1_N	Complement Signal Link Lane 1
12	LAN1_P	True Signal Link Lane 1
13	H_GND	Ground
14	DCR	NO connection
15	H_GND	Ground
16	H_GND	Ground
17	NC	NO connection
18	NC	NO connection
19	BL_PWR	LED Power Supply 5V<4.4V
20	BL_PWR	LED Power Supply 5V<4.4V
21	BL_PWR	LED Power Supply 5V<4.4V
22	BL_PWR	LED Power Supply 5V<4.4V
23	NC	NO connection
24	BL_GND	Ground
25	BL_GND	Ground
26	BL_GND	Ground
27	BL_GND	Ground
28	BL_PWM_DIM	LED PWM signal input
29	BL_ENABLE	LED enable input
30	NC	NO connection

$$6.5V \times [80.6/(220+80.6)] = 1.743V$$
$$1.743V - 6.5V = -4.757V$$


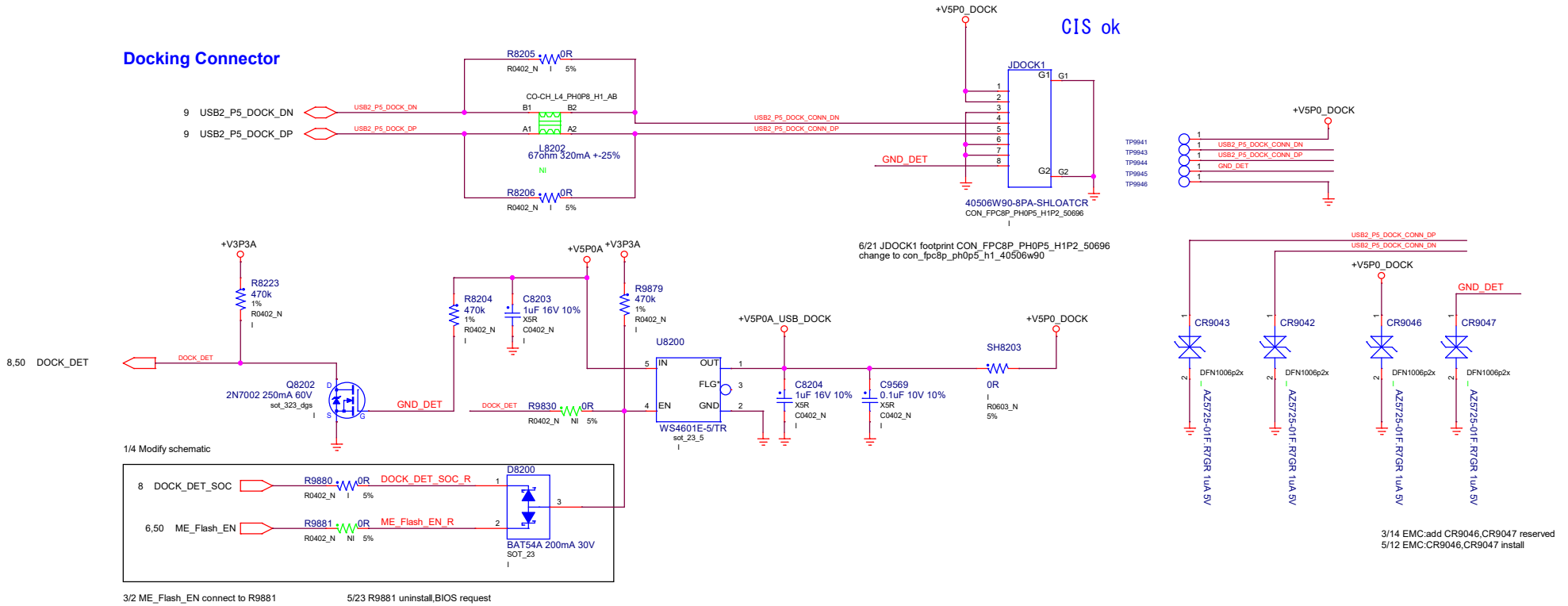
Touch & Docking

Touch Connector



CIS ok

Docking Connector



CIS ok

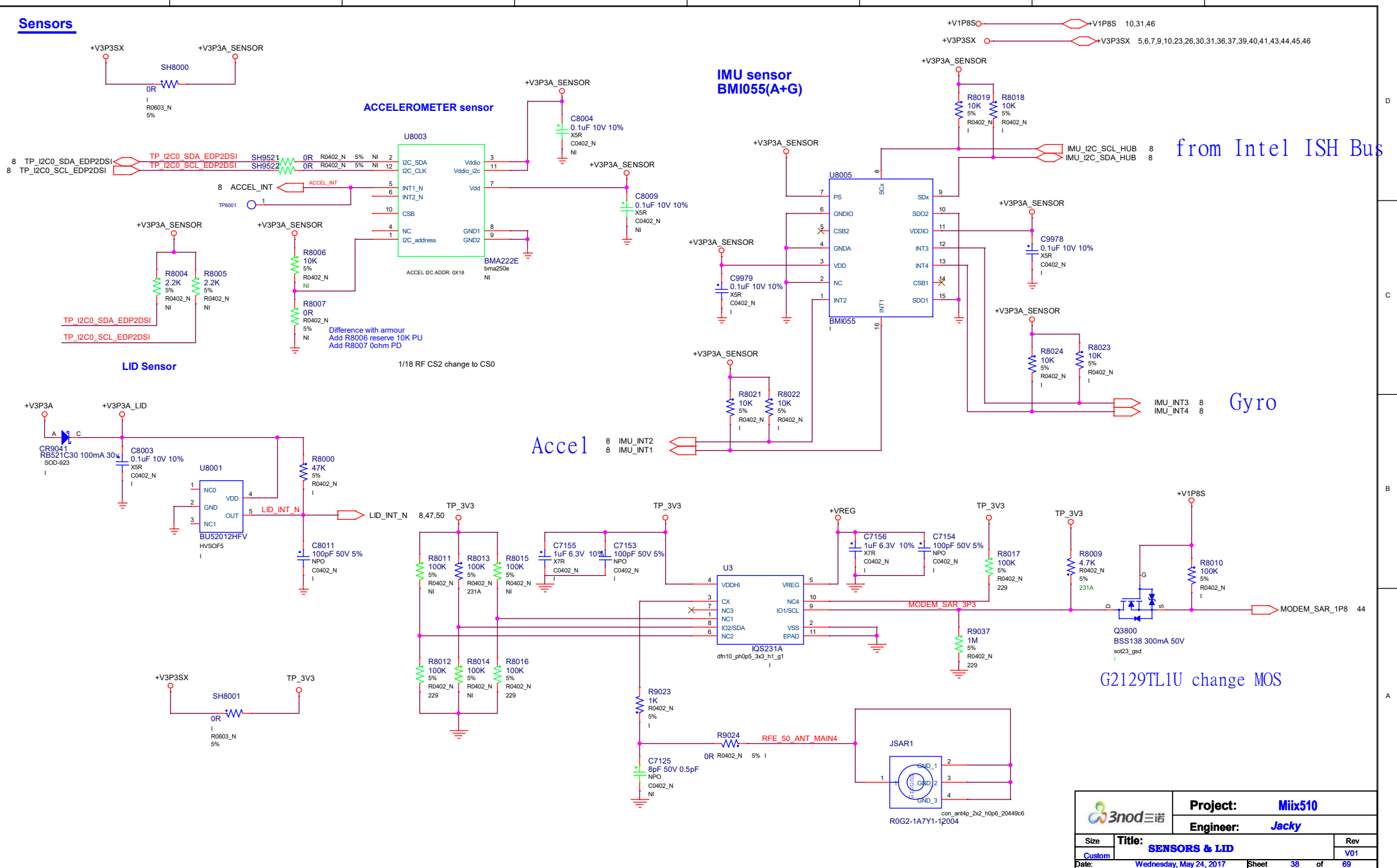
		Project: Miix510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	TOUCH PANEL AND DOCK	V01	
Date:	Wednesday, May 24, 2017	Sheet	37 of 69

INTERNAL ONLY

BPAGE DRAWING

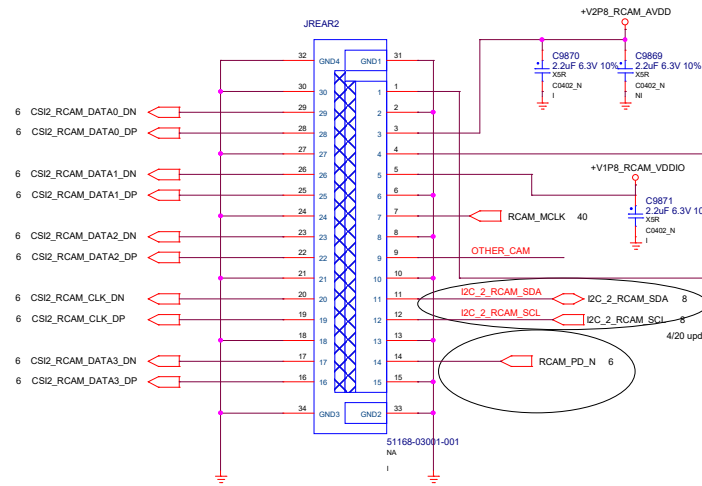
sky_x_mnt+V3P3.37
Wed Jun 03 11:22:57 2015

Sensors

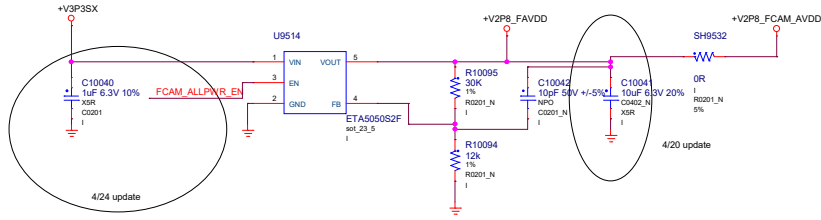


REAR CAMERA CONNECTOR

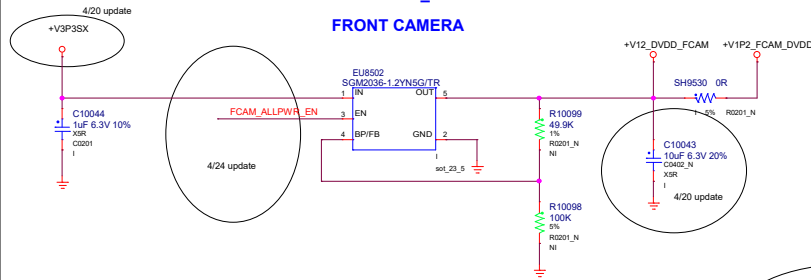
8M OV8858



FRONT CAMERA AVDD_2.8V

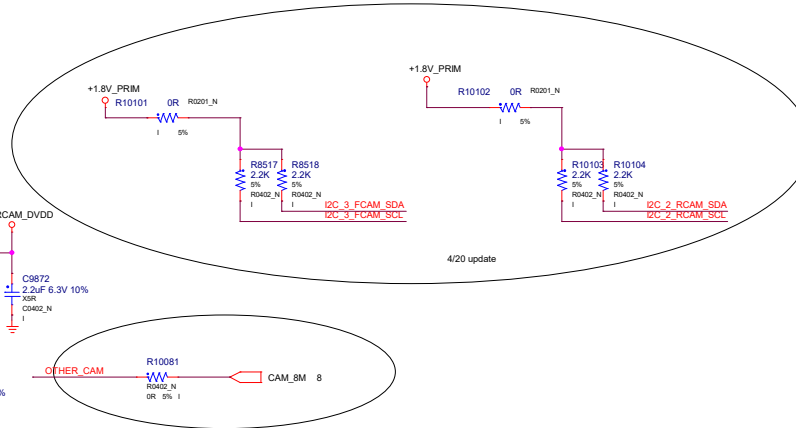


FRONT CAMERA DVDD_1.2V



+V1P2_RCAM_VDDIO
+V1P8_CAM
+V2P8_RCAM_AVDD
+V1P8_RCAM_VDDIO
+V2P8_RAF_VDD
+V1P8_FCAM_VDDIO
+V2P8_FCAM_AVDD

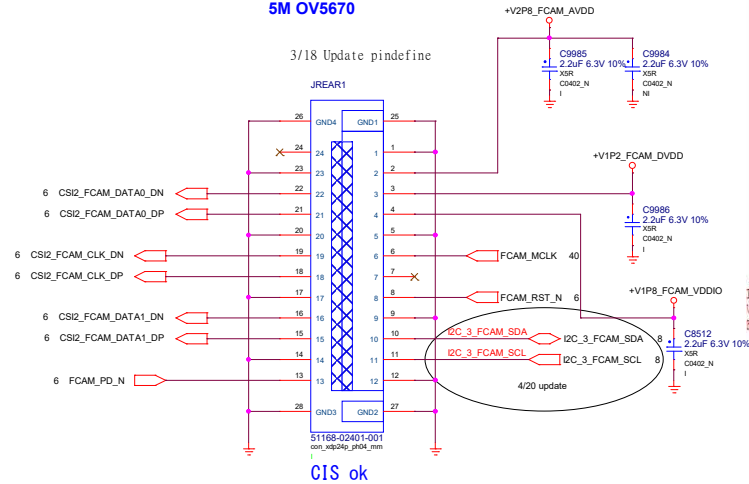
+V1P2_RCAM_VDDIO 40
+V1P8_CAM 40
+V2P8_RCAM_AVDD 40
+V1P8_RCAM_VDDIO 40
+V2P8_RAF_VDD 40
+V1P8_FCAM_VDDIO 40
+V2P8_FCAM_AVDD 40



8M Pin 9 internal is GND

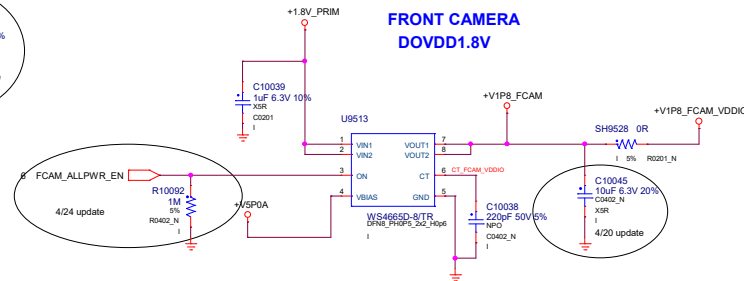
FRONT CAMERA CONNECTOR

5M OV5670

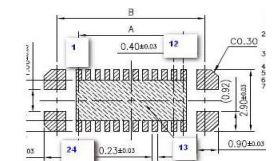


CIS ok

FRONT CAMERA DOVDD1.8V



1/18 JREAR1_JFRONT1 change to 24pin

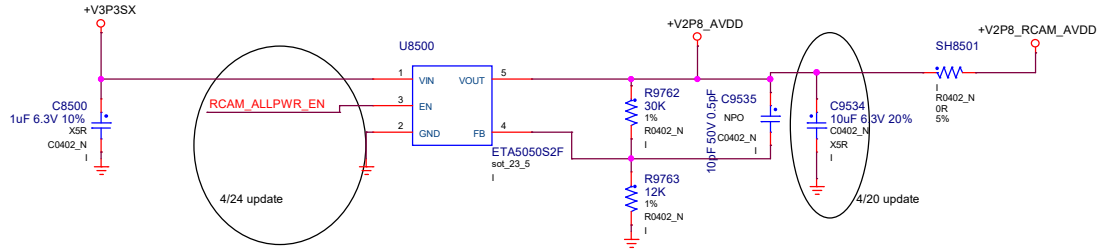


NO	SIGNAL
1	AGND
2	AVDD2.8V
3	DVDD1.2V
4	DOVDD1.8V
5	DGND
6	MCLK
7	DGND
8	NC(RESETB)
9	DGND
10	SIO_D
11	SIO_C
12	DGND
13	XSHUTDOWN
14	DGND
15	MD4_P
16	MD4_N
17	MD2_P
18	MD2_N
19	MD1_P
20	MD1_N
21	DGND
22	MD3_P
23	MD3_N
24	DGND
25	MD2_P
26	MD2_N
27	DGND
28	MD1_P
29	MD1_N
30	DGND

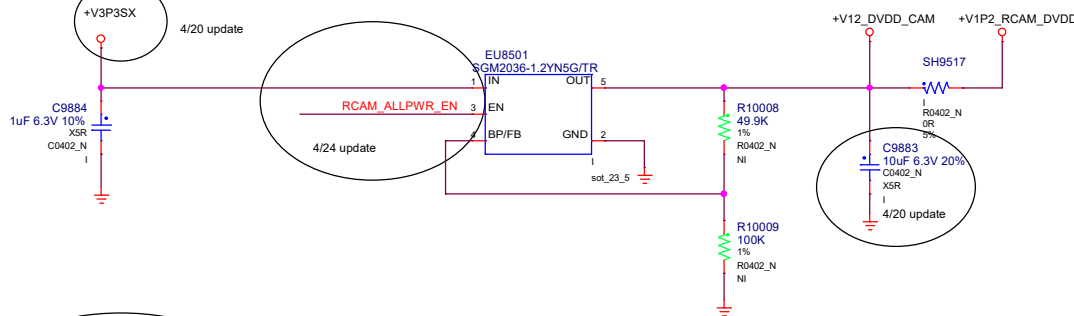
I2C Address:
Write: 0X20
Read: 0X21

I2C Address:
Write: 0X6C
Read: 0X6D

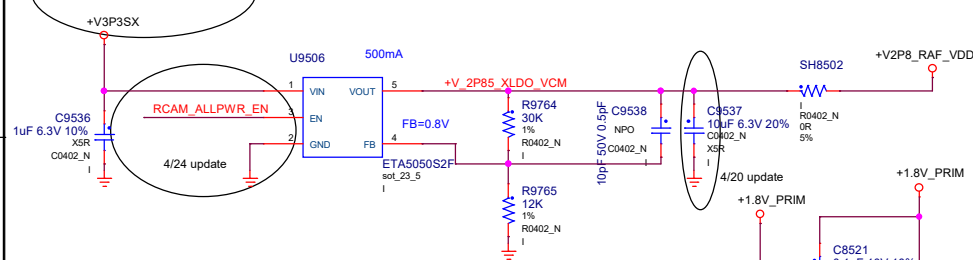
AVDD_2.8V REAR CAMERA



DVDD_1.2V REAR CAMERA



AF_VCC_2.8V



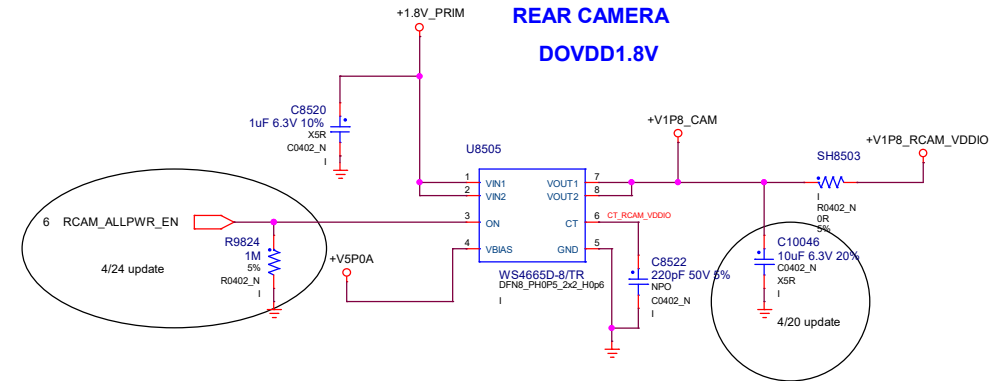
+V1P2_RCAM_DVDD → +V1P2_RCAM_DVDD 39
 +V3P3SX → +V3P3SX 5,6,7,9,10,23,26,30,31,36,37,38,39,41,43,44,45,46
 +V1P8_CAM → +V1P8_CAM 39
 +V2P8_RCAM_AVDD → +V2P8_RCAM_AVDD 39
 +V2P8_FCAM_AVDD → +V2P8_FCAM_AVDD 39
 +V2P8_AF_VDD → +V2P8_AF_VDD 39

+1.8V_PRIM → +1.8V_PRIM 7,10,11,31,39,44,47,56,65
 +V5P0A → +V5P0A 10,11,23,37,39,42,53,60,61,62,63,65
 +V1P8_RCAM_VDDIO → +V1P8_RCAM_VDDIO 39
 +V1P8_FCAM_VDDIO → +V1P8_FCAM_VDDIO 39

6/20 Y8500 24MHZ +/- 10PPM change to 19.2MHZ +/- 25PPM, Intel request

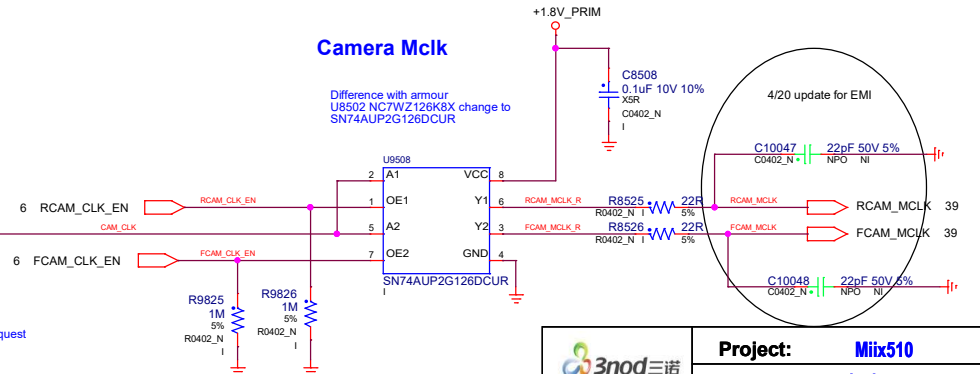
1/19 Delete DVDD_1.5V
 3/18 Add DVDD_1.5V,
 Rear camera change to OV5648

REAR CAMERA DOVDD1.8V



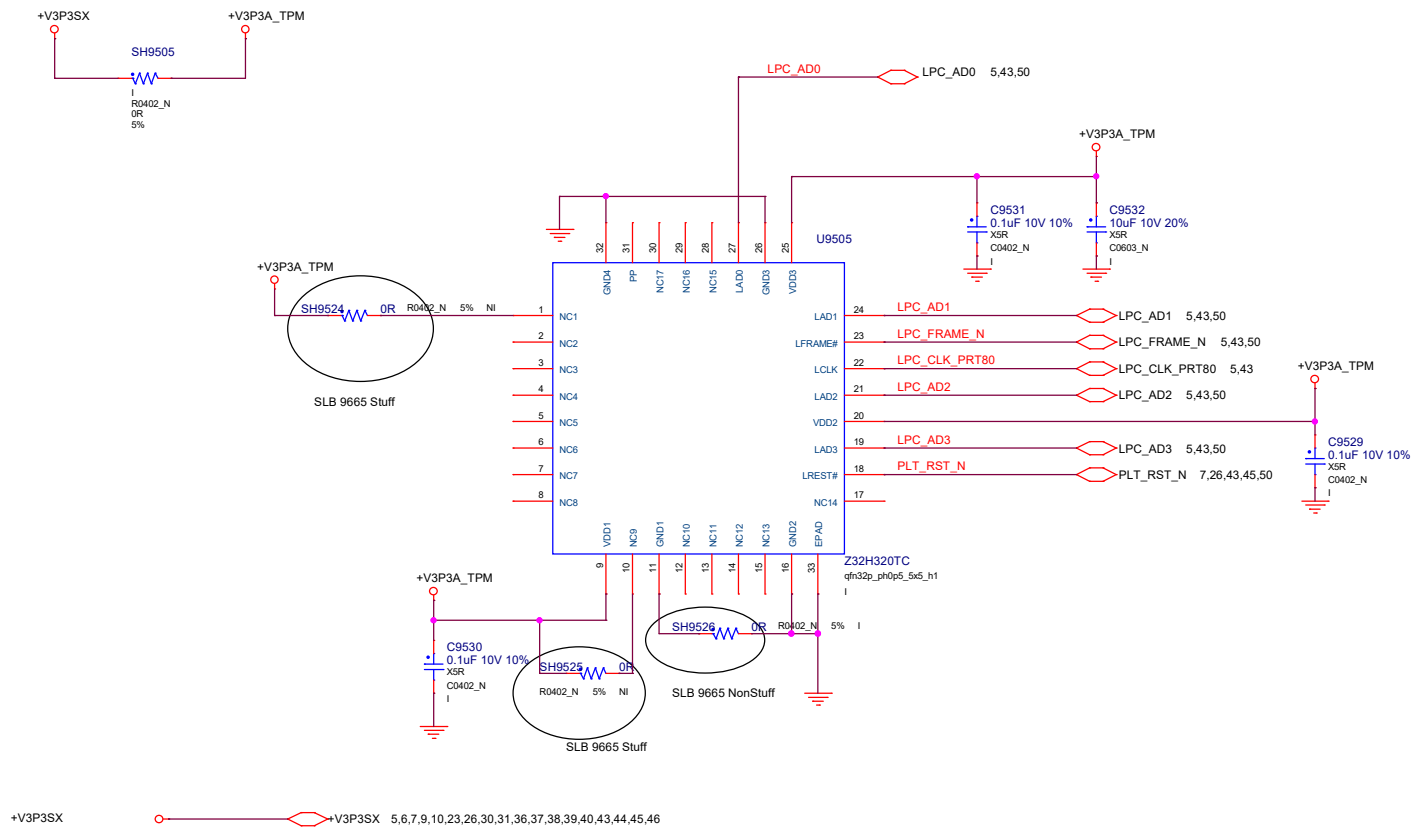
Camera Mclk

Difference with armour
 U8502 NC7WZ126K8X change to
 SN74AUP2G126DCUR



3nod 三諾		Project: Miix510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	CAMERA DISCRETE CONTROL LOGIC	V01	
Date:	Wednesday, May 24, 2017	Sheet	40 of 69

TPM 2.0



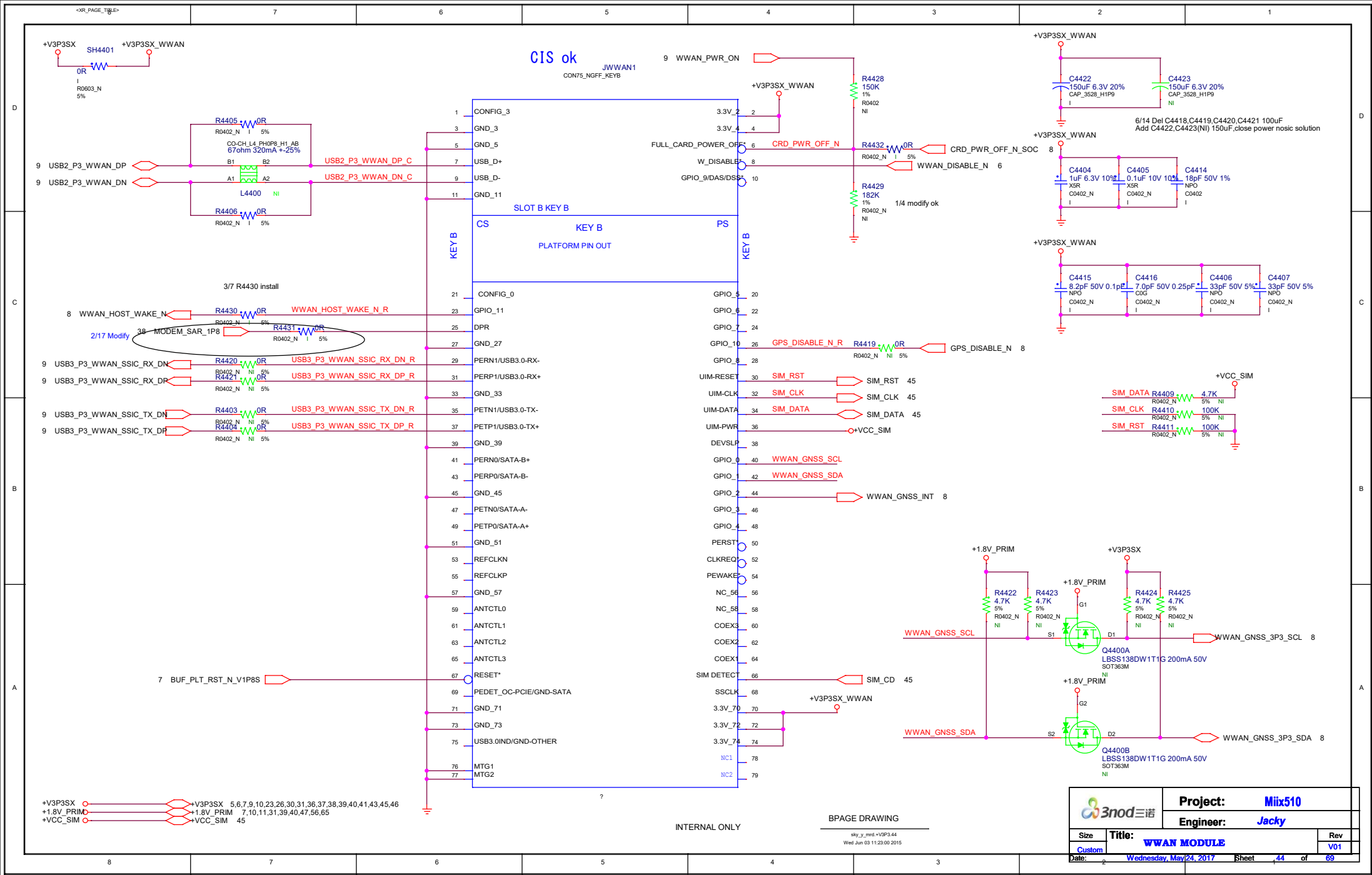
INTERNAL ONLY

BPAGE DRAWING

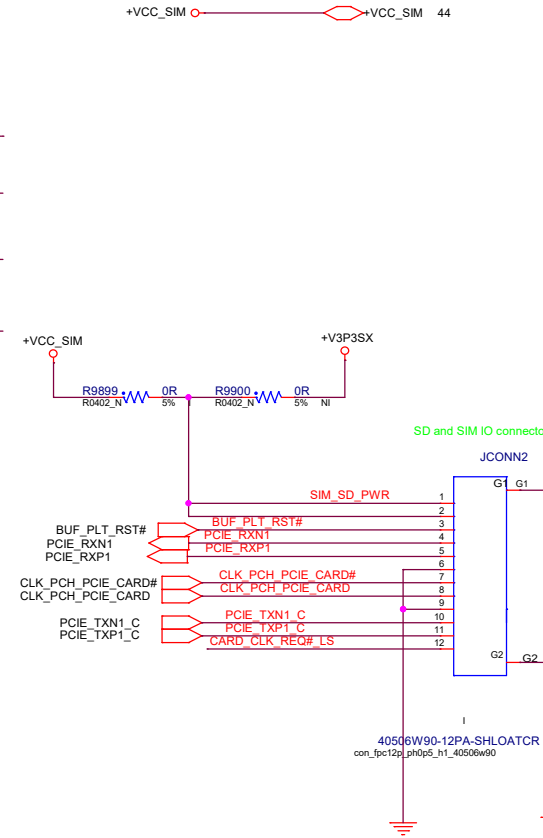
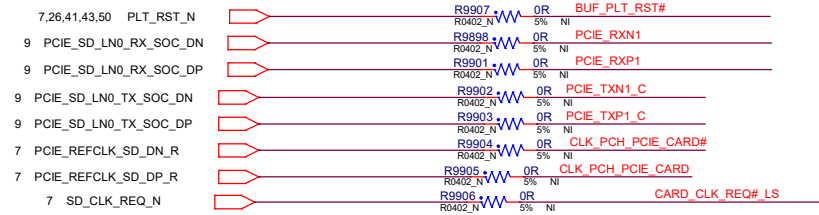
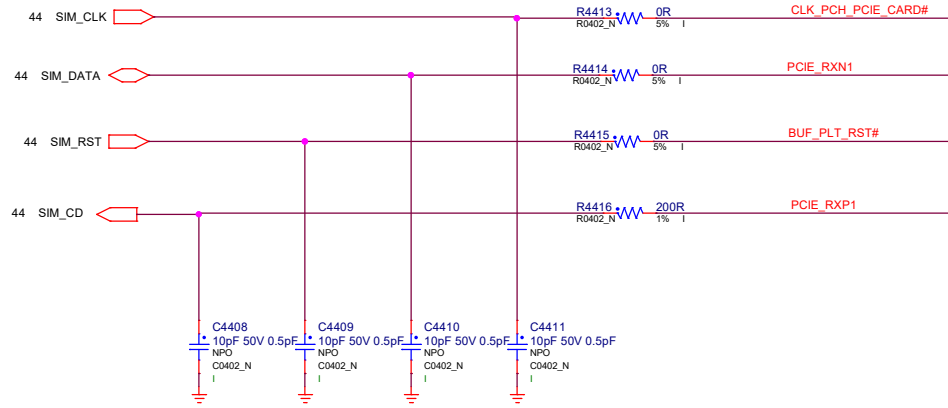
shy_y_msd-V3P3.41
Wed Jun 03 11:22:59 2015

		Project: Miix510	
Size: Custom		Engineer: Jacky	
Title: TPM		Rev: V01	
Date: Wednesday, May 24, 2017		Sheet 41 of 69	

		Project: Miix510	
		Engineer: Jacky	
Size	Title: WLAN WIFI BT MODULE	Rev	
Custom		V01	
Date:	Thursday, May 25, 2017	Sheet	43 of 69



2016/10/07

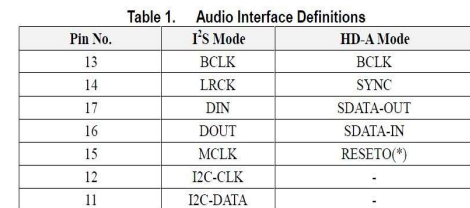


INTERNAL ONLY

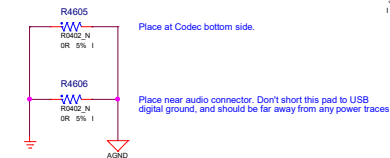
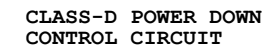
BPAGE DRAWING

sky_y_mrd.GND
Wed Jun 03 11:23:01 2015

		Project: Miix510	
Size		Engineer: Jacky	
Custom	Title: MICRO SIM	Rev	V01
Date: Wednesday, May 24, 2017	Sheet 45 of 69		



PC BEEP



49 HPOUT_JD

+V3P3SX_AUDIO

R4607 100K R4602_N 1% I

HP_LINE1_JD

R4608 100K R4602_N 1% I

49 HPOUT_JD

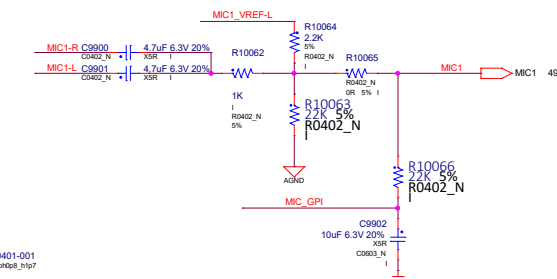
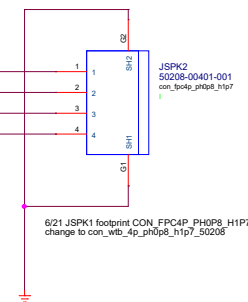
+V3P3SX_AUDIO

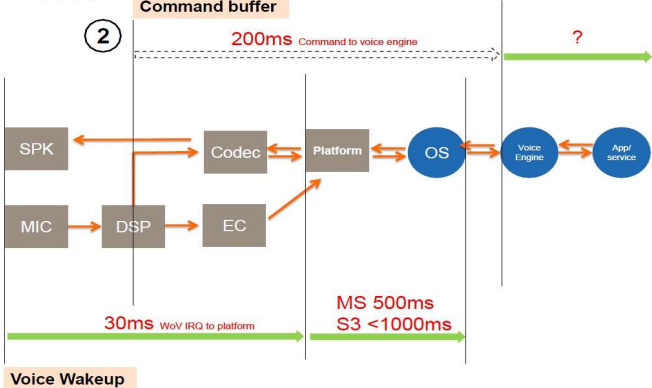
R4609 100K R4602_N 1% I

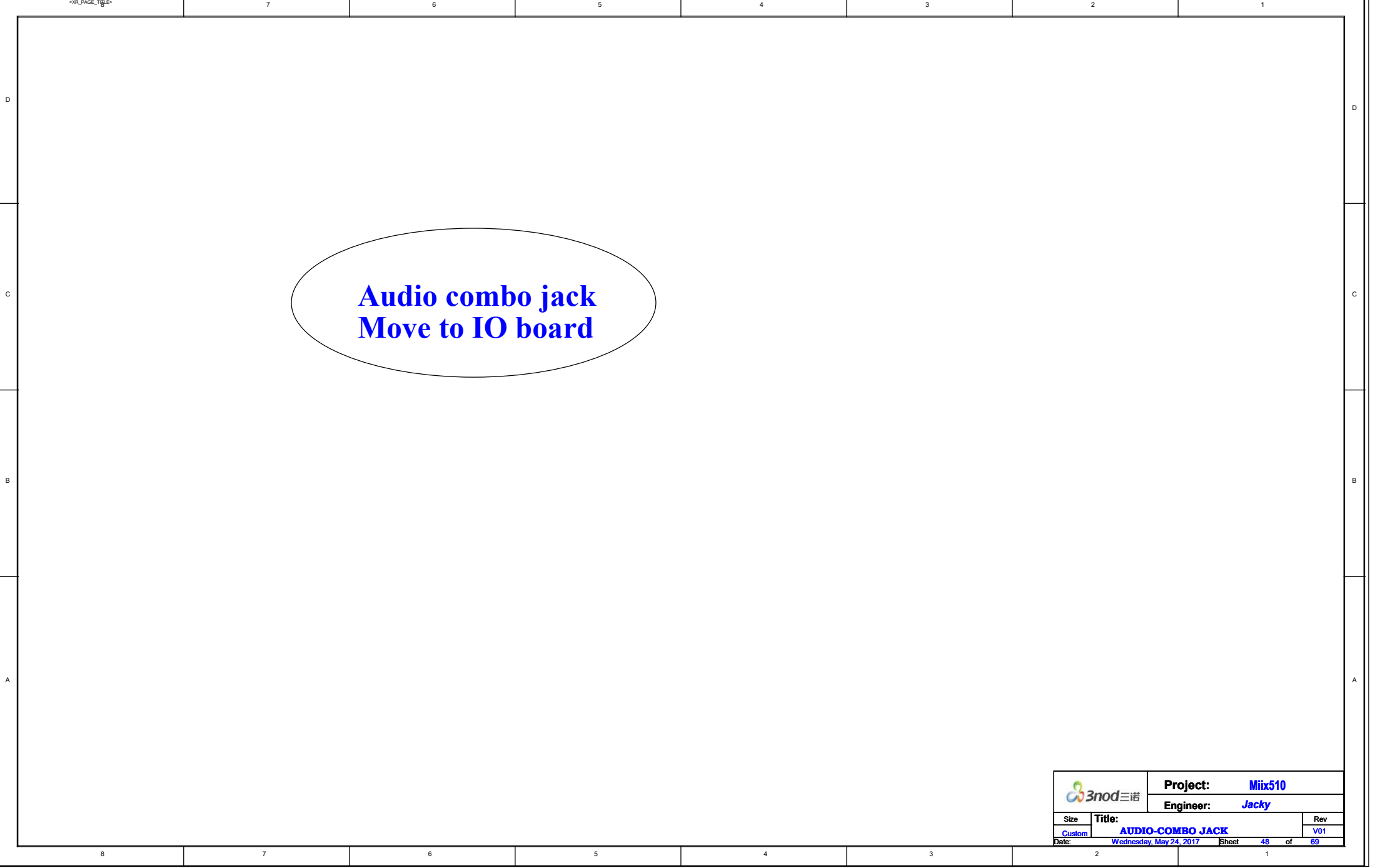
MIC_GPI

If you don't support Dock audio_JD function, please keep pull high

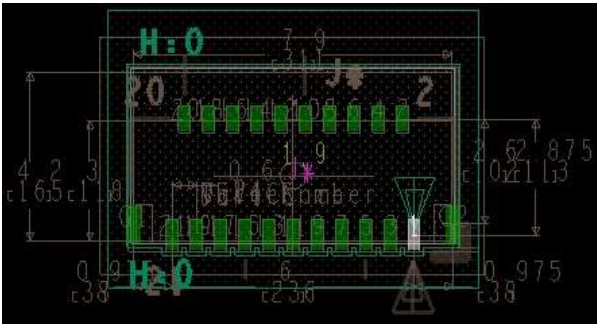
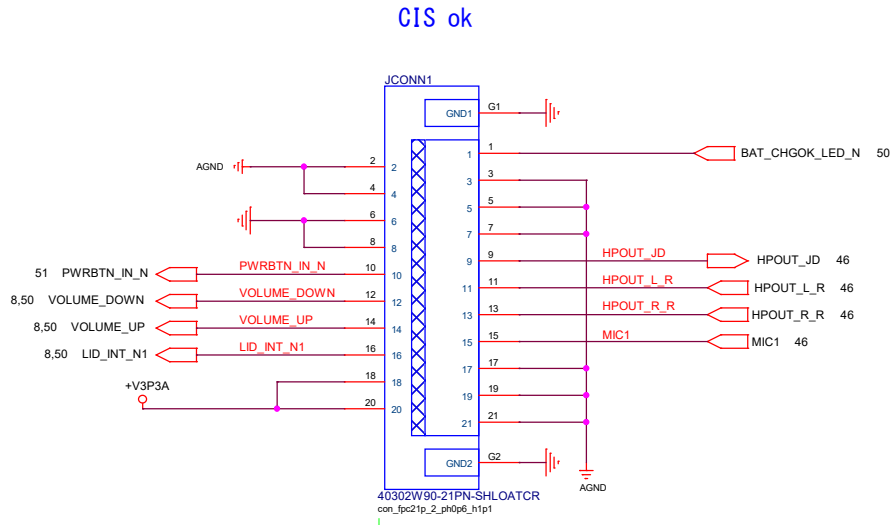
POS +V3P3SX 10.30
P33X +V3P3SX 5.6, 7.8, 10.23, 26.30, 31.36, 37.38, 39.40, 41.43, 44.45
P8S +V1P8S 10.31, 38







IO Board CONN



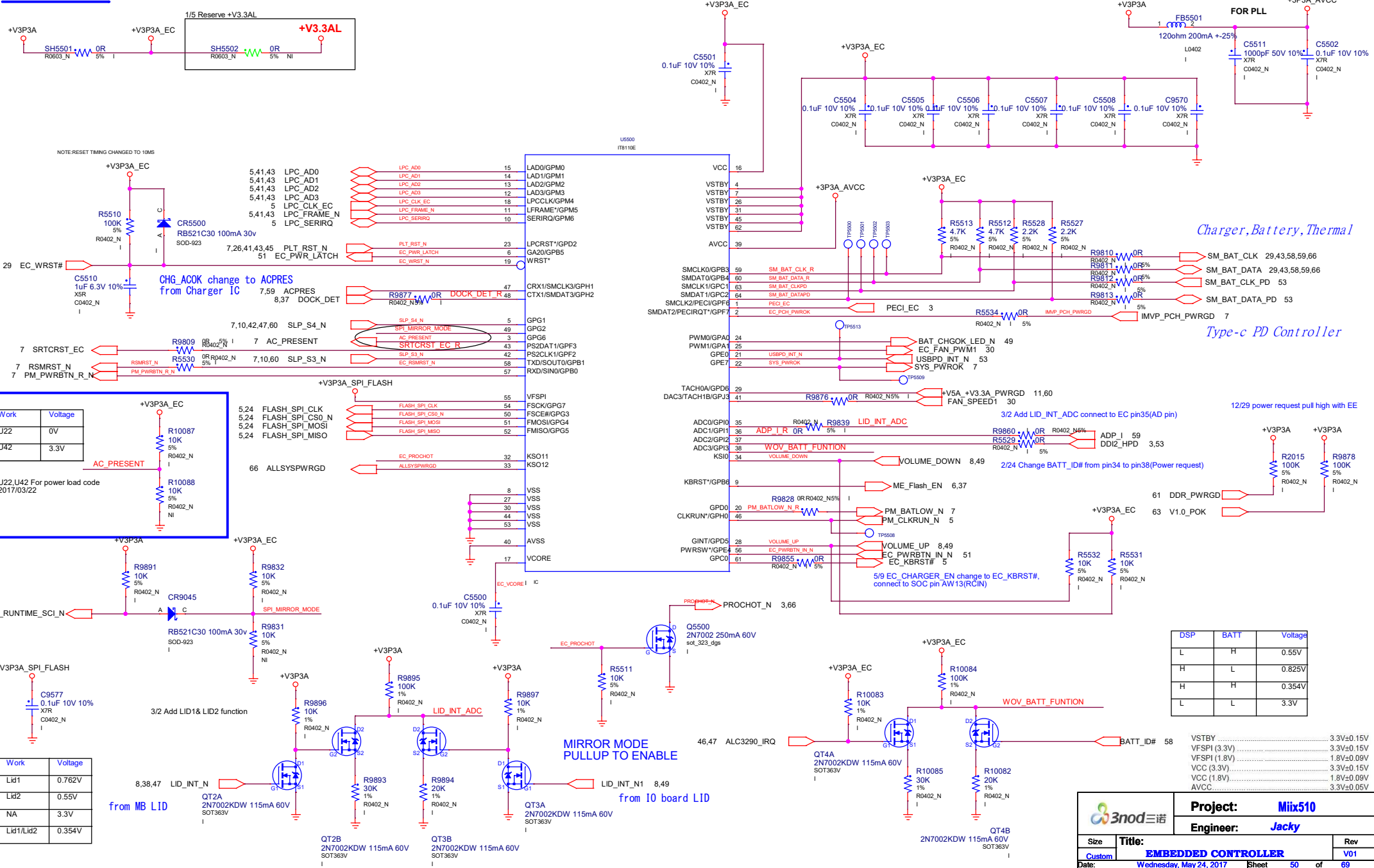
INTERNAL ONLY

BPAGE DRAWING

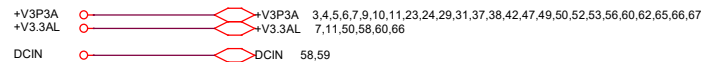
sky_x_mtd +VCHG.49
Wed Jun 03 11:23:03 2015

		Project: MiiX510	
		Engineer: Jacky	
Size	Title: IO board CONN		Rev
Custom			V01
Date:	Wednesday, May 24, 2017	Sheet	49 of 69

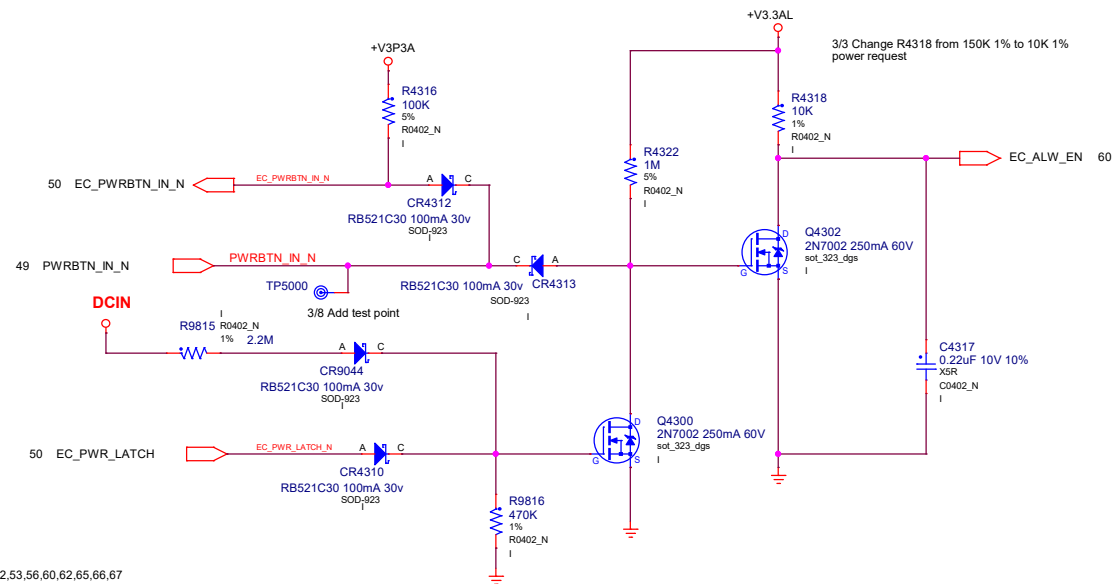
EC controller



Power switch Move to IO board

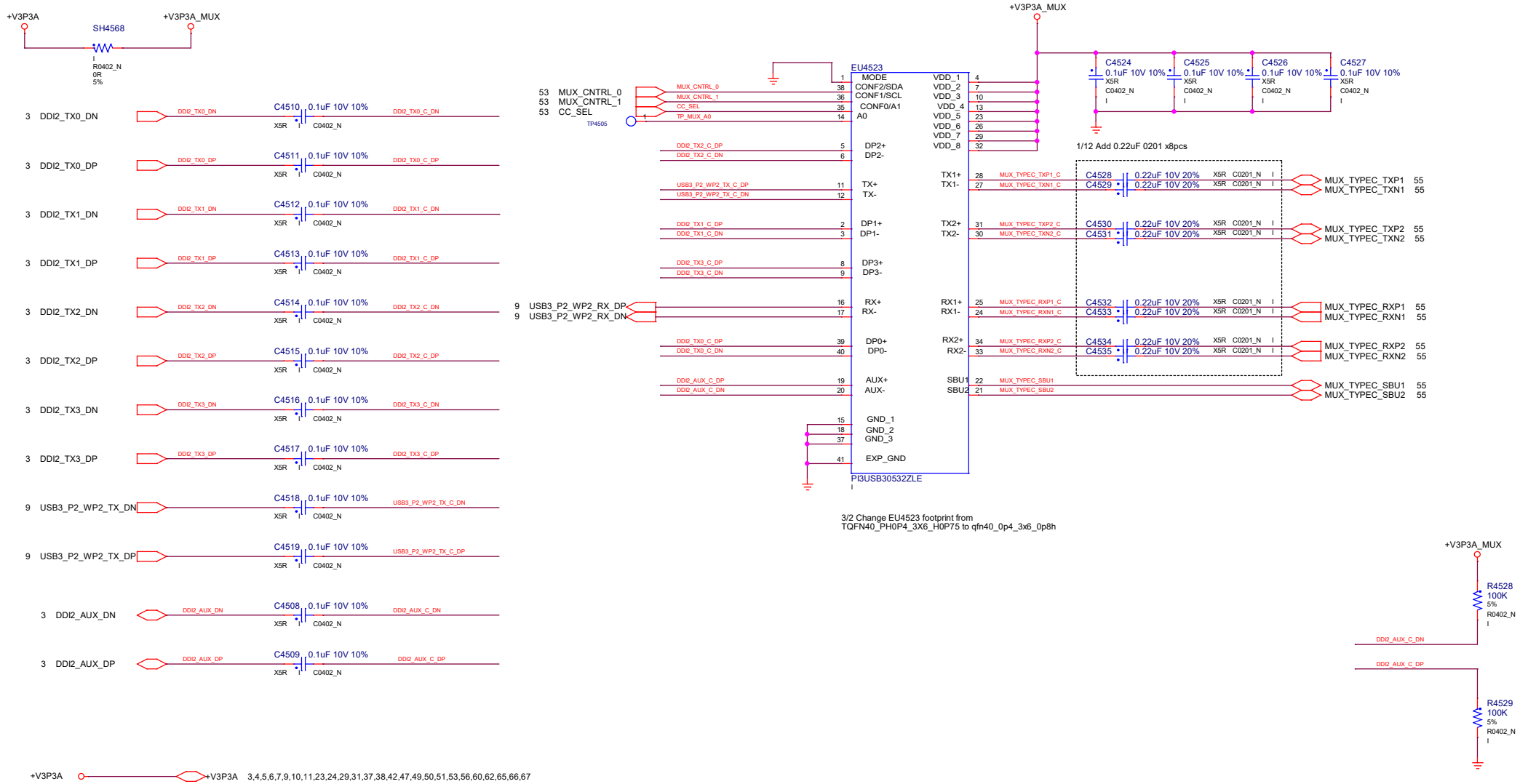


Power LED



	Battery Life <5%			Battery Life <20%			Battery Life <80%			Battery Life <100%		
	S0	S3	S4/S5	S0	S3	S4/S5	S0	S3	S4/S5	S0	S3	S4/S5
Charge	Amber			Amber			White			White		
	0.25s on			<			0.1s off			solid on		
	0.25s off			<			5s on			/		
	0.25s on			<			/					
	0.25s off			<								
	0.25s on			<								
Discharge	3s off			<								
	Amber	Off	Off	Amber	Off	Off	Off	Off	Off	Off	Off	Off
	0.25s on			solid on								

TYPE-C Multiplexer



INTERNAL ONLY

BPAGE DRAWING

sky_y_mtd+V3P3.62
Wed Jun 03 11:23:04 2015

VARIANT:

<VARIANT>

INTEL

CONFIDENTIAL

DOCUMENT_NUMBER

H78885

REV

1P0

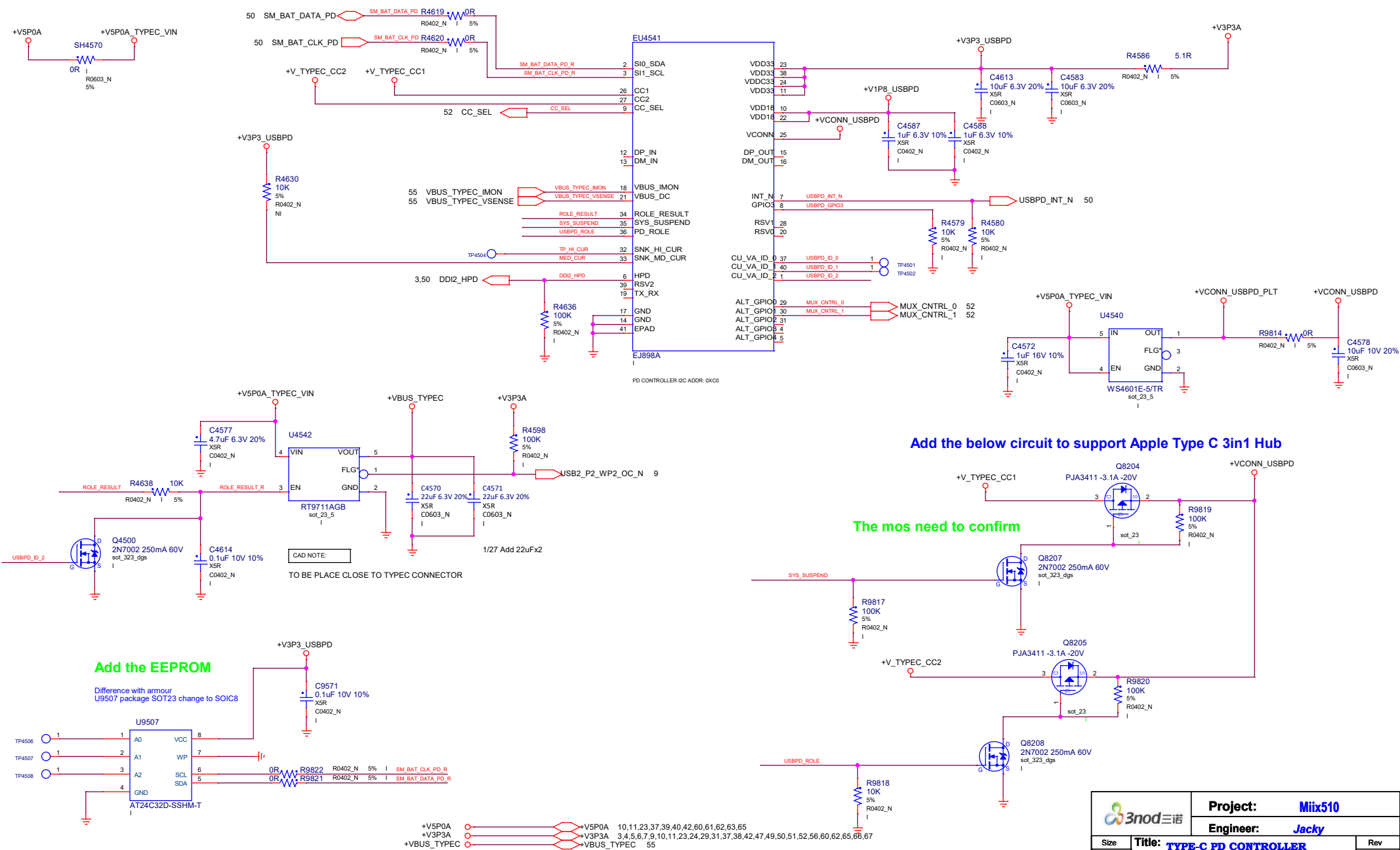
PAGE

52/57

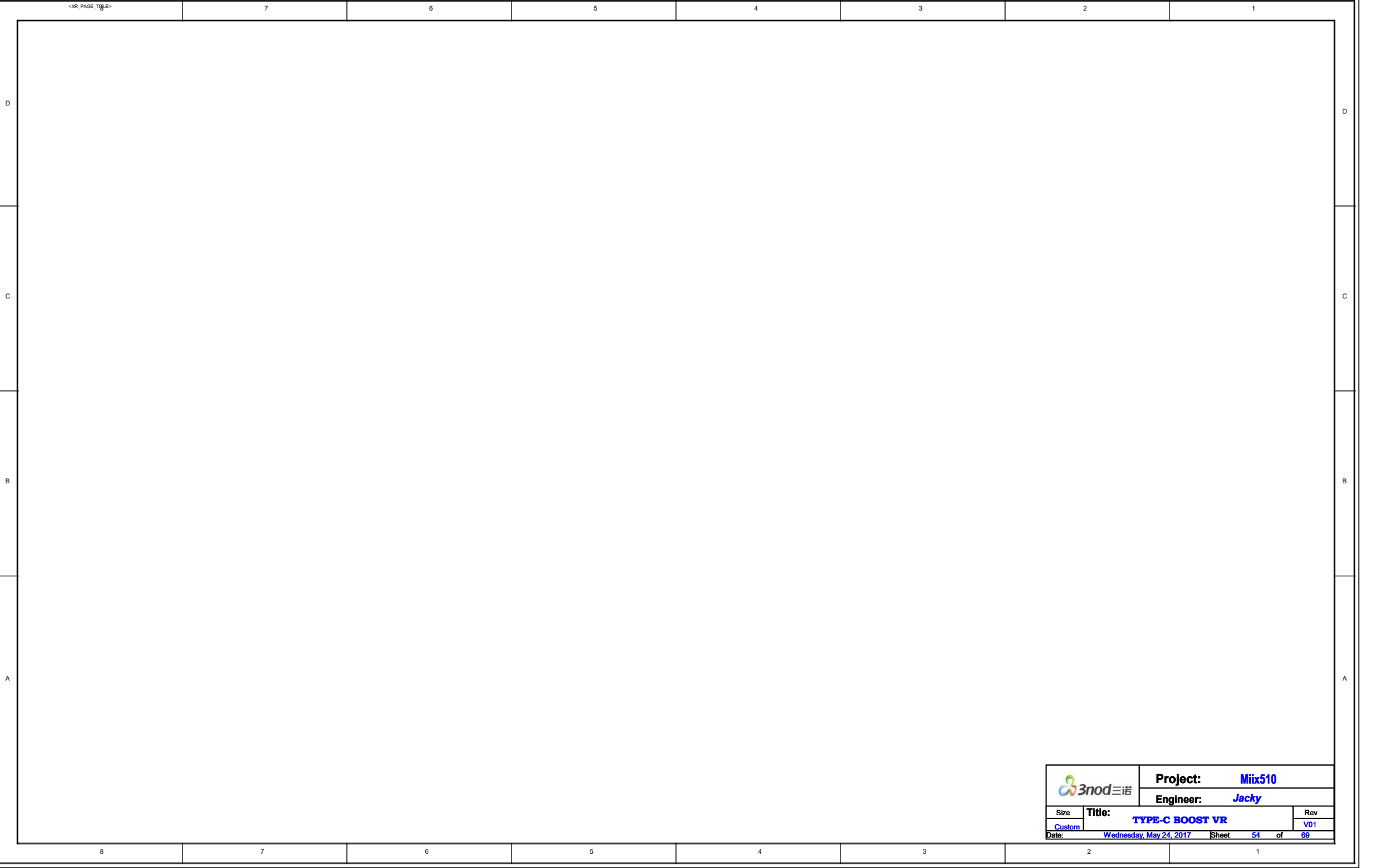
		Project: Miix510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	TYPE-C MULTIPLEXER	V01	
Date:	Wednesday, May 24, 2017	Sheet	52 of 69
VARIANT:		DOCUMENT_NUMBER	REV
<VARIANT>		H78885	1P0
		PAGE	52/57

Type-c PD Controller

PD schematic NEED CONFIRM

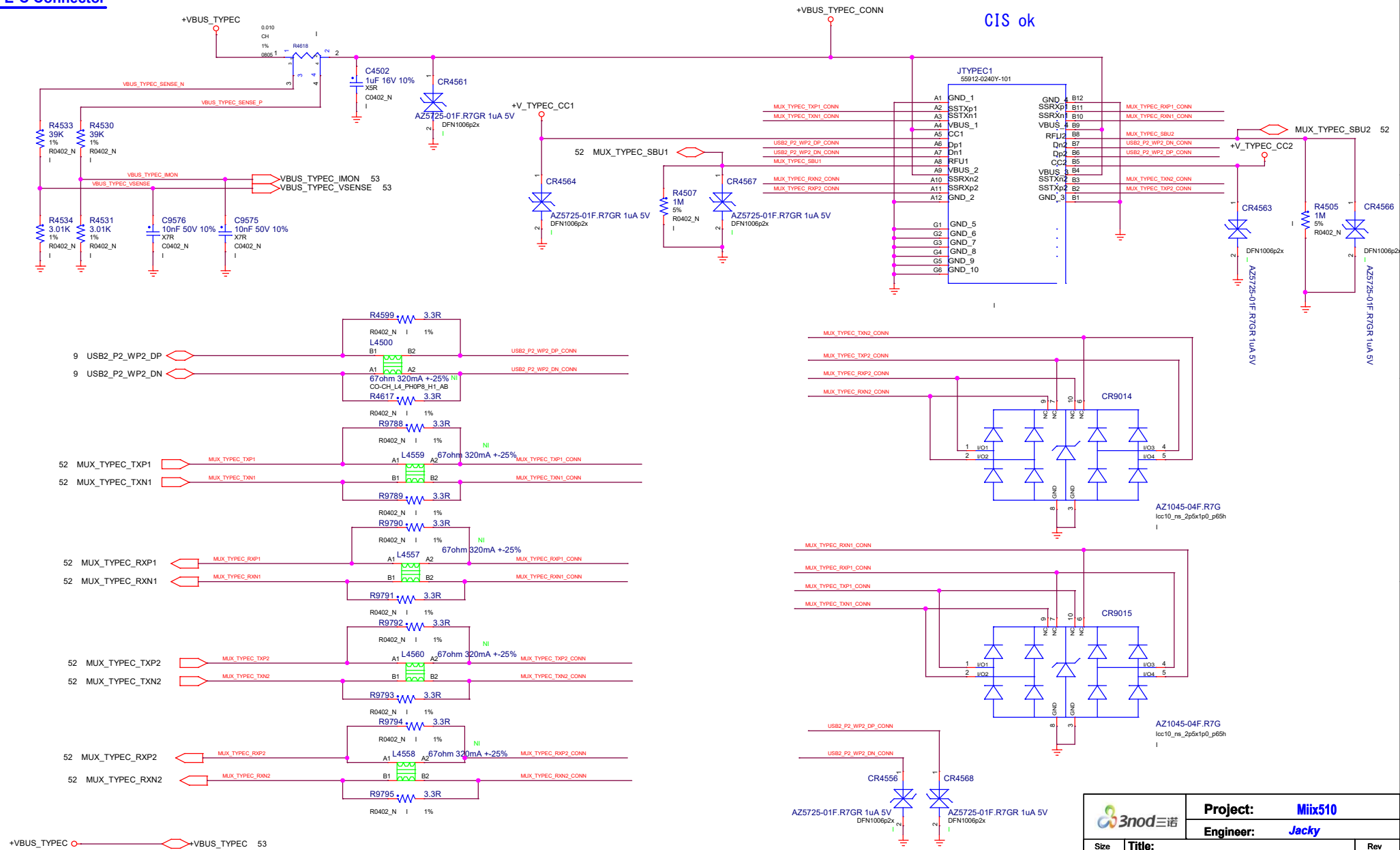


		Project:	Miix510
		Engineer:	Jacky
Size	Title: TYPE-C PD CONTROLLER	Rev	V01
Custom			
Date:	2 Wednesday, May 24, 2017	Sheet	531 of 69

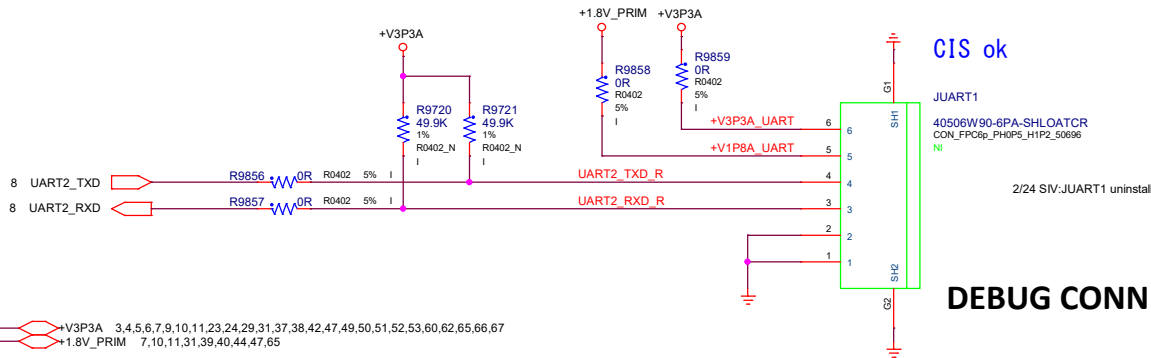


	Project: Mix510	
	Engineer: Jacky	
Size	Title:	Rev
Custom	TYPE-C BOOST VR	V01
Date: Wednesday, May 24, 2017 Sheet 54 of 69		

TYPE-C Connector

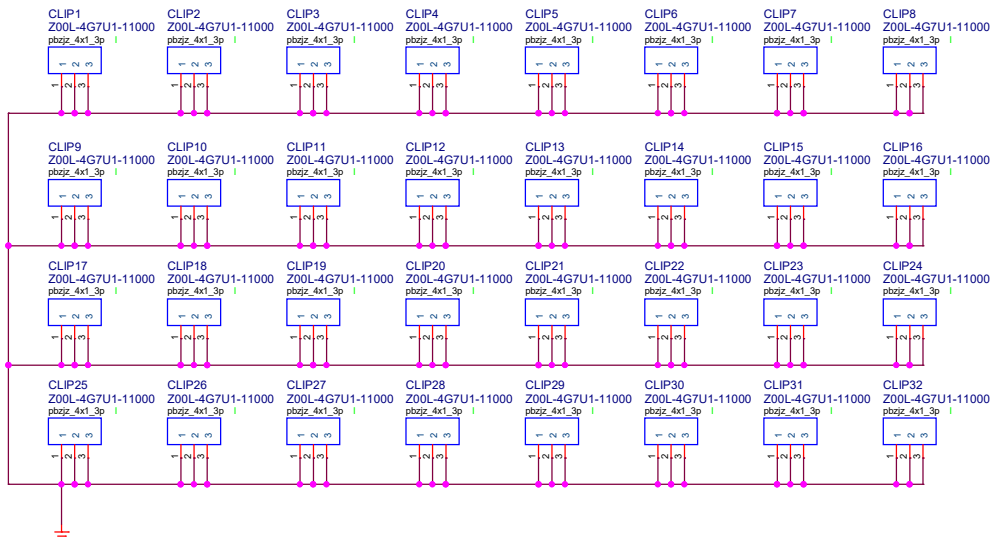


		Project: Mix510	
		Engineer: Jacky	
Size	Title:	TYPE-C CONNECTOR	
Custom			
Date:	Wednesday, May 24, 2017	Sheet	55 of 69



+V3P3A 3,4,5,6,7,9,10,11,23,24,29,31,37,38,42,47,49,50,51,52,53,60,62,65,66,67
+1.8V_PRIM 7,10,11,31,39,40,44,47,65

Shielding

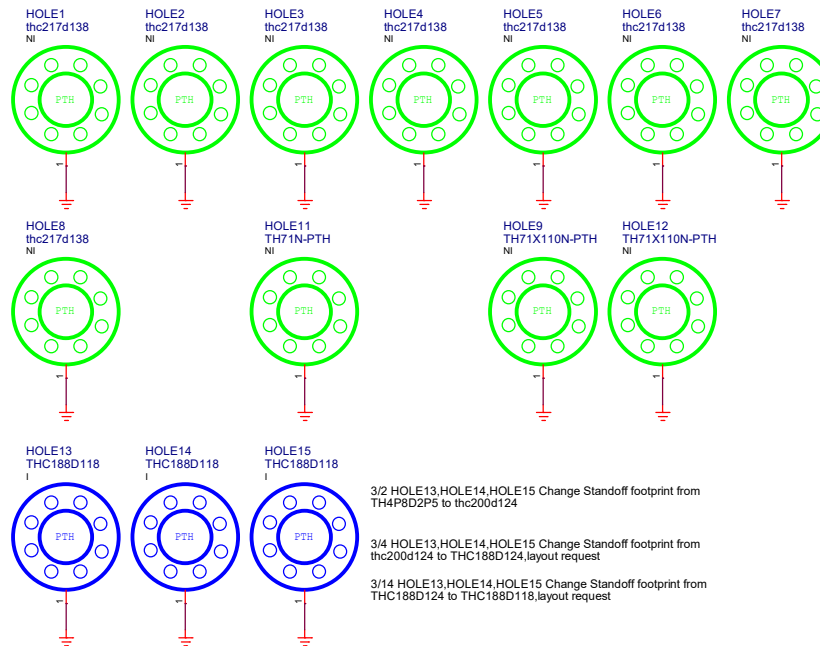


1/13 copy 11.6" NB Shielding

3/9 Del Z00L-4G7U1-11000(CLIP1~CLIP24),
add Z00L-4G7U1-11000(CLIP1~CLIP32)

5/5 footprint pbzjz_4x1_3p change to SHEILDING_CASE_3P_OP8X4.SMT request

Holes



3/2 HOLE13,HOLE14,HOLE15 Change Standoff footprint from TH4P8D2P5 to thc200d124

3/4 HOLE13,HOLE14,HOLE15 Change Standoff footprint from thc200d124 to THC188D124,layout request

3/14 HOLE13,HOLE14,HOLE15 Change Standoff footprint from THC188D124 to THC188D118,layout request

INTERNAL ONLY

BPAGE DRAWING

sky_y_msd.GND
Wed Jun 03 11:23:06 2015

		Project: Mix510	
		Engineer: Jacky	
Size	Title:	Rev	
Custom	UART CONN & HOLE & CLIP	V01	
Date:	Wednesday, May 24, 2017	Sheet	56 of 69

SDV=>SIV

2/2 Page04 Add Rev RM97, RM98 for 16Gb memory(B61)
2/2 Page04 Add (4Gb 8Gb) & (16Gb) BOM option table
2/2 Page19,20 Memory pin M9 connect to CPU BG1

2/24 Page10 UC6, UC7 pin9 connect GND, need change to +1.0V_PRIM (HW issue)
2/24 Page07 Add R1042, VR_PWRGD connect to IMVP_PCH_PWRGD, SOC and EC (HW issue)
2/24 Page56 Delete JUART1, Debug conn
2/24 Page24 Delete @U3002, SPI ROM conn
2/24 Page50 Change BATT_ID# from pin34 to pin38[ADC pin] (Power request)
2/24 Page50 Change LID_INT_N from pin38 to pin34

3/2 Page05 R9863 change to NI, THERMAL HW shutdown
3/2 Page08 Change memory ID PU from +1.8V_PRIM to +3V_PRIM
3/2 Page37 ME_Flash_EN connect to R9881
3/2 Page50 Add LID1 & LID2 function, add QT2, QT3, R9893, R9894, R9895, R9896, R9897
3/2 Page56 HOLE13, HOLE14, HOLE15 Change Standoff footprint from TH4P8D2P5 to thc200d124
3/2 Page52 Change EU4523 footprint from TQFM40_PHOP4_3X6_HOP75 to qfn40_Op4_3x6_Op8h

3/3 Page51 Change R4318 from 150K 1% to 10K 1%, power request
3/3 Page50 Change EC_CHARGER_EN to pin61(pin61 can outpin)
3/4 Page56 hange Standoff footprint from thc200d124 to THC188D124(layout request)
3/7 Page19,20 Add RM99, RM100 0ohm to GND, for 4/8 Gb memory
3/7 Page38 +1.8V_PRIM change to +V3P3SX, and add R8020, close +V3P3SX leakage
3/7 Page30 R9847 connect to +V5POS, change to +V3P3SX
3/7 Page07 Del R1088, Add R9865 , HW_ID SIV
3/7 Page44 R4430 install
3/8 Page06 Del RCAM_PD_N offpage, add TP1061
3/8 Page39 JREAR1 pin8 change to NC, pin11 change to RCAM_RST_N, delete RCAM_PD_N
3/8 Page08 Change WWAN_SAR_DET from BA7 to AD11(Group F is 1.8V)
3/8 Page08 Change R1094 from 100K to 0ohm, Del R1095 120K, can use HUAMEI module
3/8 Page51 Add TP5000, close to PWRBTN_IN_N
3/9 Page26 Del R4202, R4203, don't Co-lay PCIE12 RX
3/9 Page11 Del RC429, don't connect to BATT_RTC
3/9 Page56 Del Z000-467U1-11000 (GLIP1~GLIP24), add Z00L-467U1-11000 (GLIP1~GLIP32)
3/10 Page07 Change Y1000 from seiko to HOSONIC
3/10 Page07 C1251, C1252 from 18pF to 12pF, HOSONIC request
3/10 Page07 C1249, C1250 from 22pF to 8.2pF, HOSONIC request
3/11 All ESD part, ESDL0402-05 Born change to AZ5725-01F. R7GR Amazing;
ESD5344D Willae change to AZ1045-04F. R7G Amazing

3/14 Page56 HOLE13, HOLE14, HOLE15 Change Standoff footprint from
THC188D124 to THC188D116, layout request

3/14 Page42 Change U9001.3 from +V5POA to SLP_S4_N
3/14 Page15 Add CG390, CG391 reserved, Power request
3/15 Page37 Add CR9046, CR9047 reserved, EMC request
3/15 Page07 R9889, R9890 move to page43, RF request
3/16 Page26 Add SSD(PCIE or SATA) BOM option table
3/18 Page06 Add TP1061
3/18 Page39 Update REAR CAMERA pindefine(Use ov5648 Rear camera module)
3/18 Page40 Add DVDD_1.5V solution(ov5648 Rear camera module need)
3/18 Page37 Add R8212 PU +V3P3SX_TOUCH, for TOUCH_PANEL_INT_N
3/21 Page07 Change C1251, C1252 from 12pF to 15pF, hosonio & seiko share
3/22 Page36 FB8200 Q603 Bead change to JP8200 JUMP_43X79, for EDP VBAT
3/23 Page36 Add Q8200, Q8201, R8200, R8201, R8202, R8203, C8219, C8220, C8221, C8222, C8223, for Panel power
3/24 Page50 Add R9898 0ohm reserved, connect to EDP_VDD_EN_R

SIV=>SIT

4/21 Page36 Del R9771, R9772, R9773, R9774, R9775, R9776 0ohm; L9505, L9506, L9507 common choke, RF request
4/21 Page43 Add SM_BAT_DATA connect to JWLAN1.58, Add SM_BAT_CLK connect to JWLAN1.60, Debug card need.
4/21 Page43 Add R4325, R4326 0ohm for Debug card
4/21 Page07 Del R9865, R1089, add R1088, R9866, for HW_ID SIT
4/28 Page38 U8002 G2129BAE1U change to G3401A916, 4bit=>2bit
5/4 Page09 WIFI PCIE port 8 change to port 4, because PCH HS10 8 can use PCIE interface (for Base-U)
5/9 Page50 EC_CHARGER_EN change to EC_KBRST#, connect to SOC pin AW13 (RC1N)
5/9 Page05 EC_KBRST# Add PU R1066 10Kohm +V3P3SX
5/10 Page50 Del R9898, Del net EDP_VDD_EN_R offpage
5/10 Page06 Del TP1055, TP1056, TP1057, TP1058, TP1059, TP1060, TP1016, TP1017, WIP1 defferential don't test point
5/12 Page37 EMC: CR9046, CR9047 install
5/16 Page23 EMC reserved C2309, C2310, C2311, C2312, C2313, C2314, C2315, C2316, C2317
5/23 Page37 R9881 uninstall, BIOS request
5/23 Page06 R9848 install, BIOS request

SIT=>SIT2

Page38 R8014 install, SAR_PROX_INT need PU
Page38 Del JSAR1, JSAR2 416990534200, del R8006 0ohm, del TP8002; add JSAR1 conn 416990528900, RF request
Page44 Del C4418, C4419, C4420, C4421 100u, add C4422, C4423 (N1) 150uF, close power noise solution

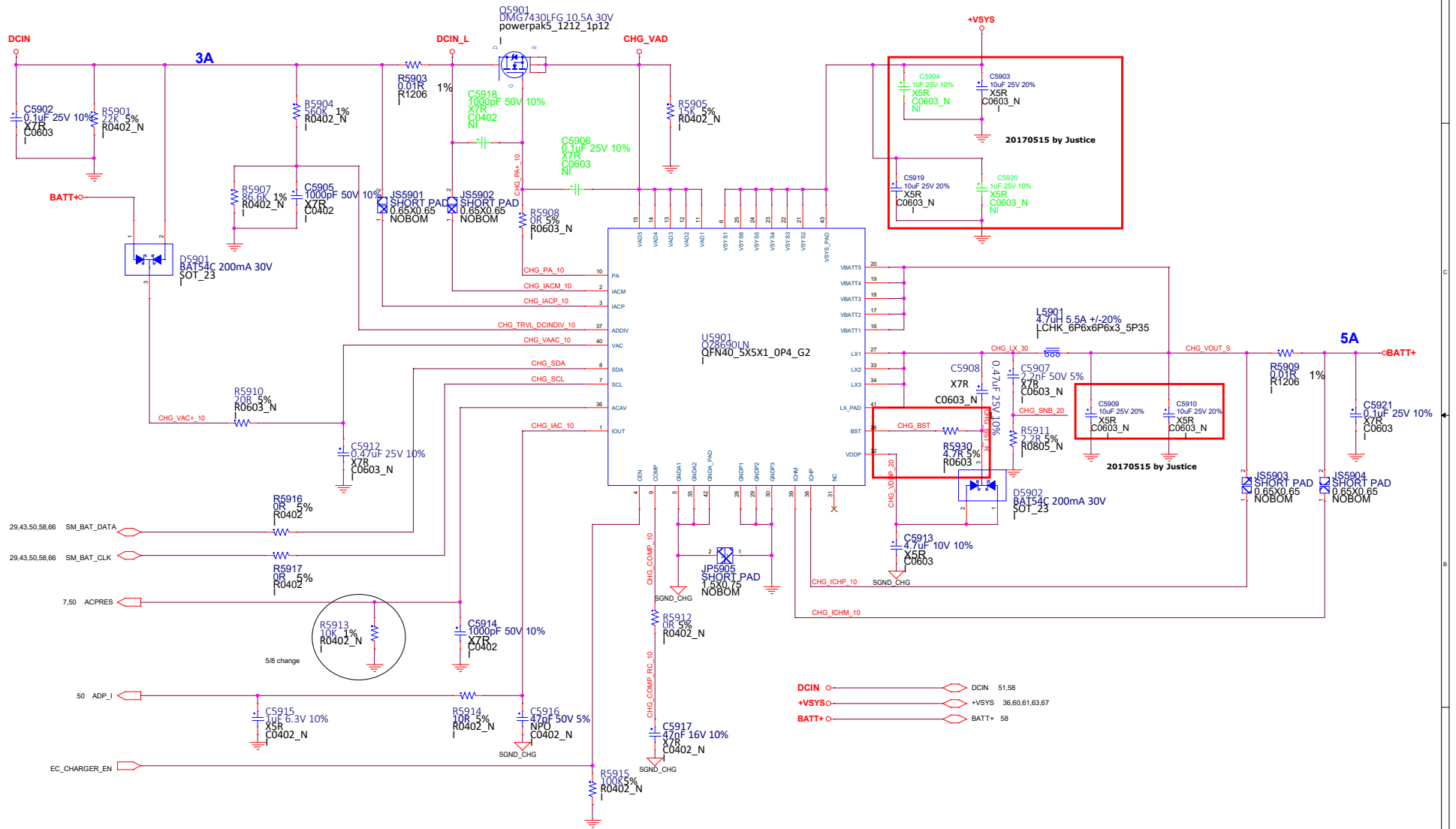
SIT2=>SVT

5/30 Page07 HW_ID3 add SAR sensor to decide on, driver request
5/30 Page07 Del R1088, add R9865, for SVT phase
6/6 Page51 Del LED1 for SVT phase
6/20 Page40 Y8500 24MHZ +/- 10PPM change to 19.2MHZ +/- 25PPM, Intel request
6/21 Page38 Reserve R8021, R8022 0ohm, ISH I2C to SAR sensor
6/24 Page38 SAR_PROX_RST add R8023 PU, RF request
6/24 Page08 SAR_PROX_RST, reserved R1096 connect to GPP_A12, add R1095 connect to GPP_A22, BIOS request
6/27 Page43 R4325, R4326 change to NI, because WLAN card "Intel 2x2AC 8260" I2C is 1.8V, mother board I2C is 3.3V

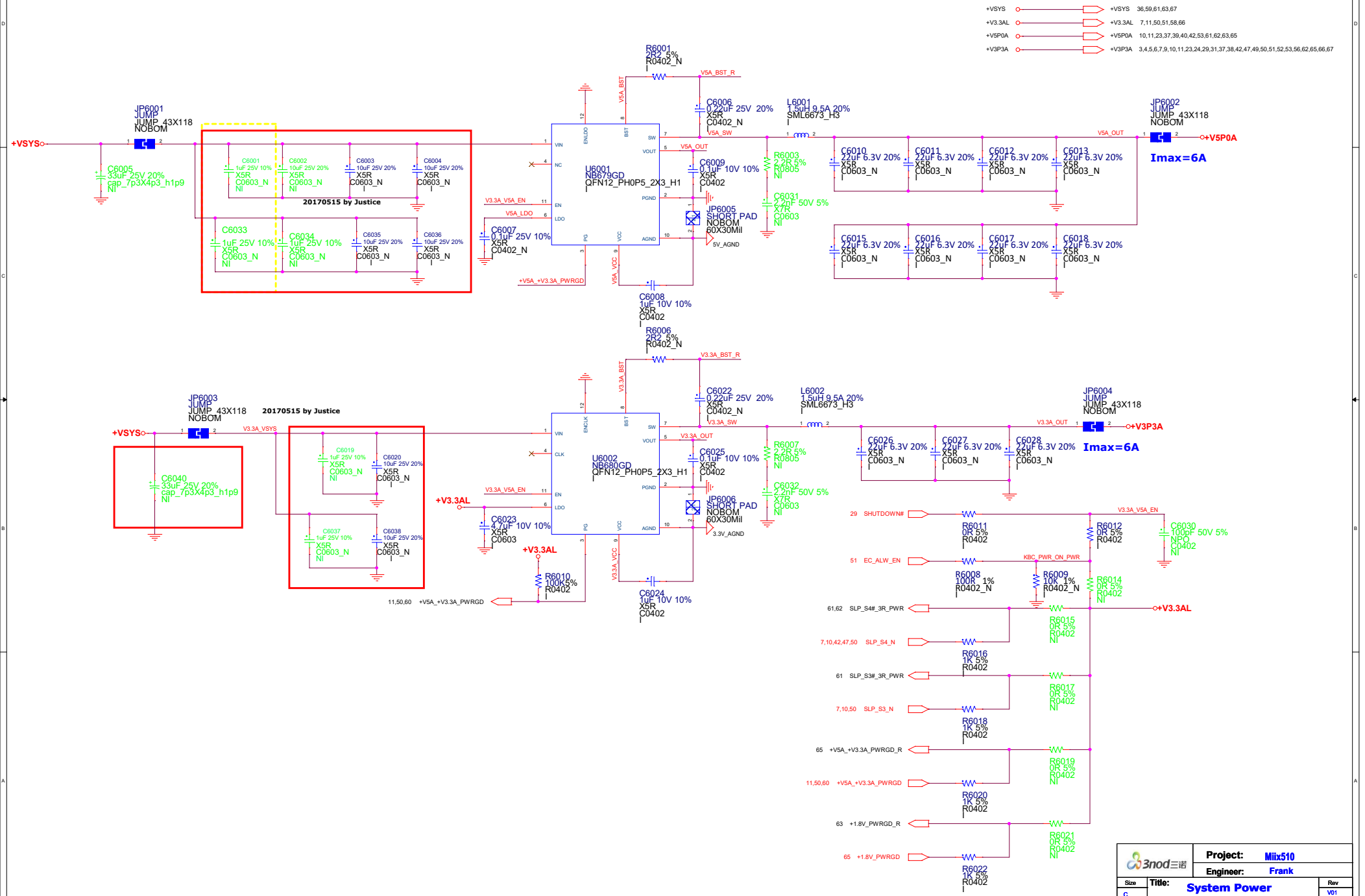
		Project: Mibx510	
		Engineer: Jacky	
Size	Title: HW Change list		Rev
C			V01
Date:	Wednesday, May 24, 2017	Sheet 57 of 69	

3nod 三诺		Project: Mix510		
		Engineer: Frank		
Size	Title: DCIN/BATT CONN			Rev
C				V01
Date:	Wednesday, May 24, 2017	Sheet	58	of 69

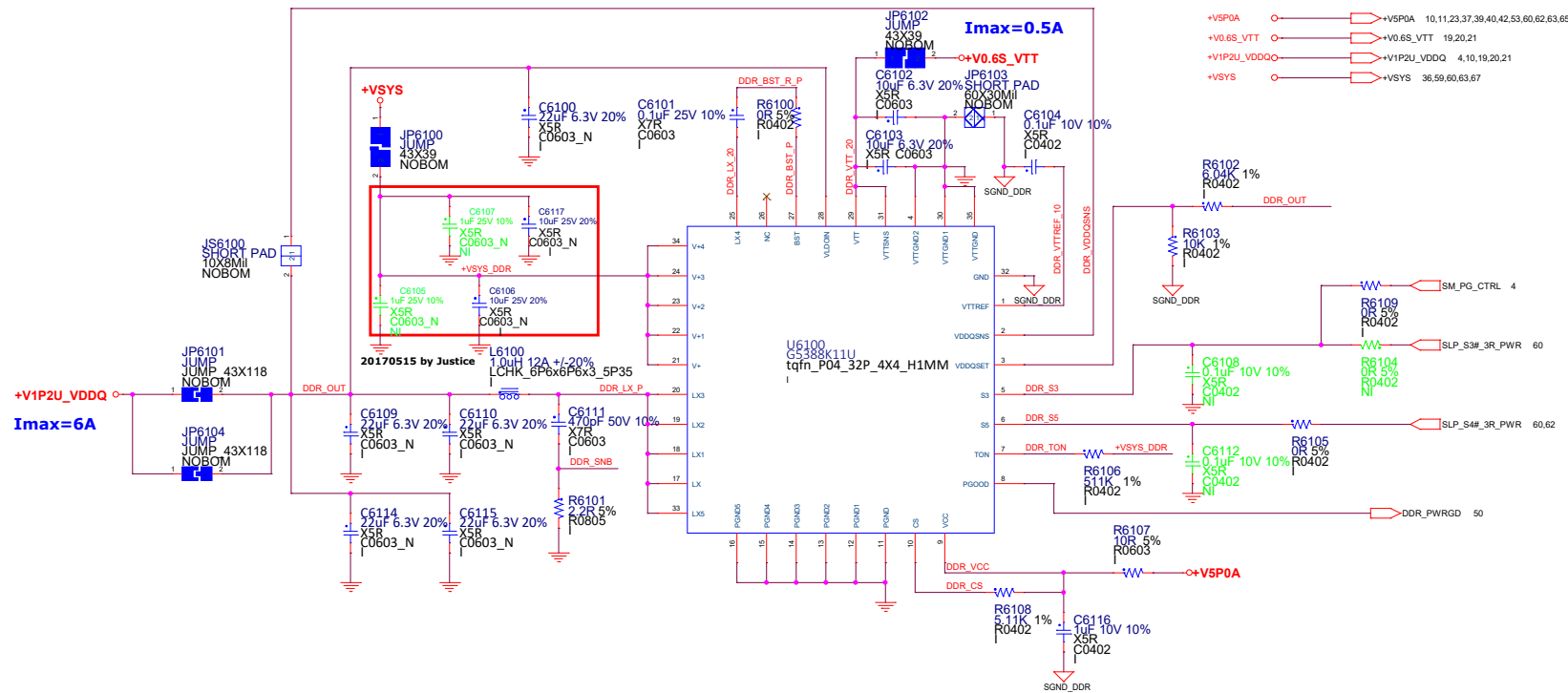
59: BATTERY CHARGER



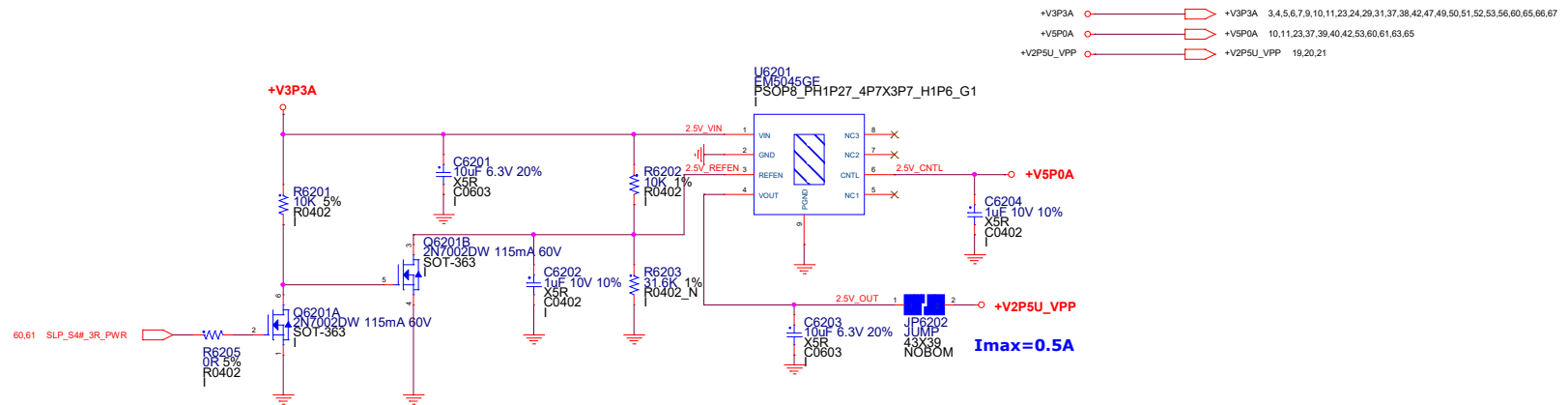
60: +V5P0A / +V3P3A POWER SUPPLY



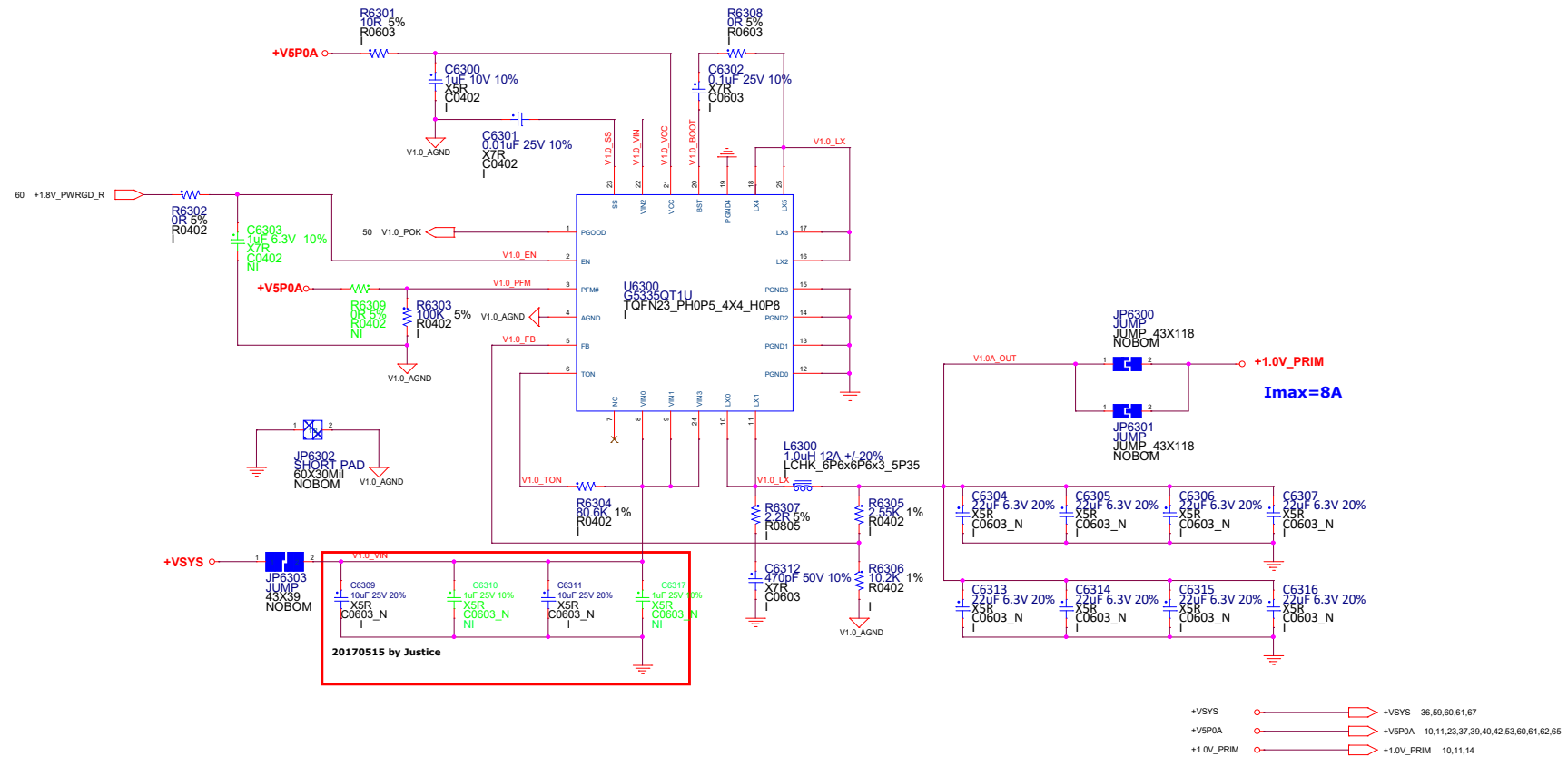
61: DDR POWER SUPPLY



62: +V2P5U_VPP POWER SUPPLY



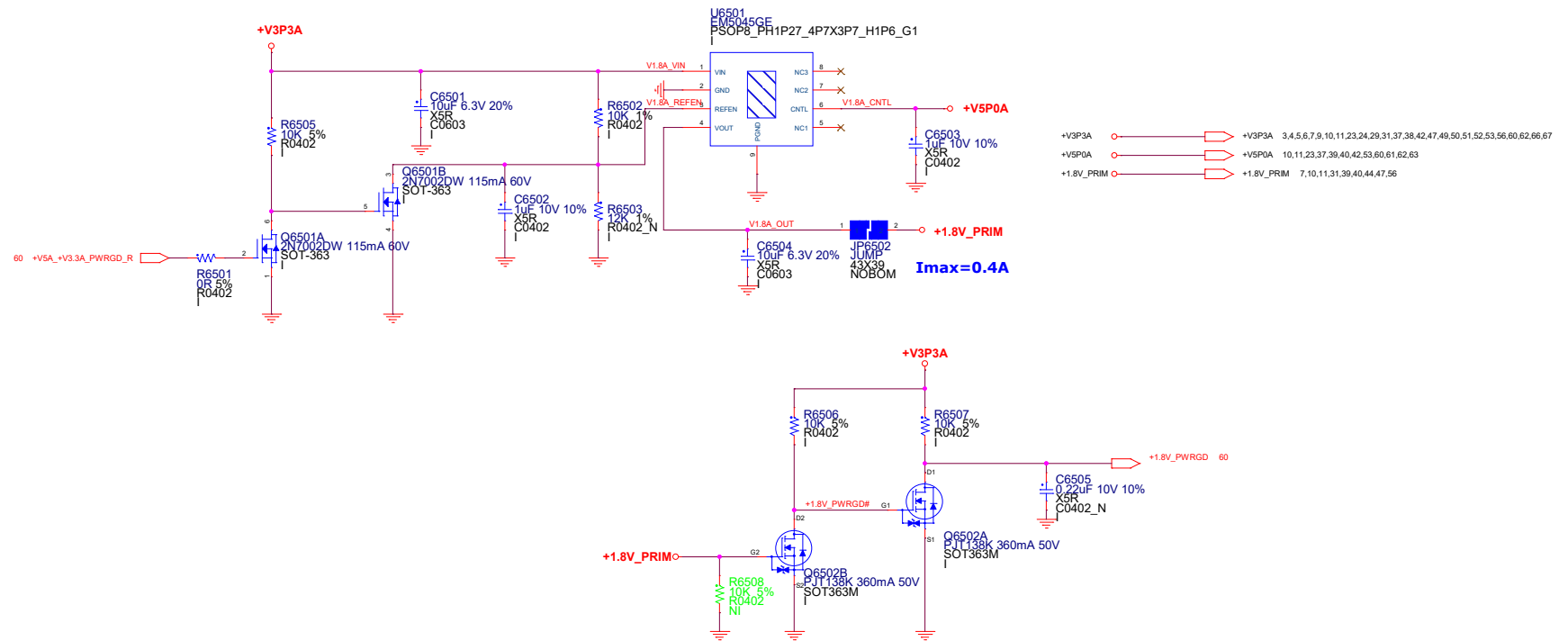
63: +1.0V_PRIM POWER SUPPLY



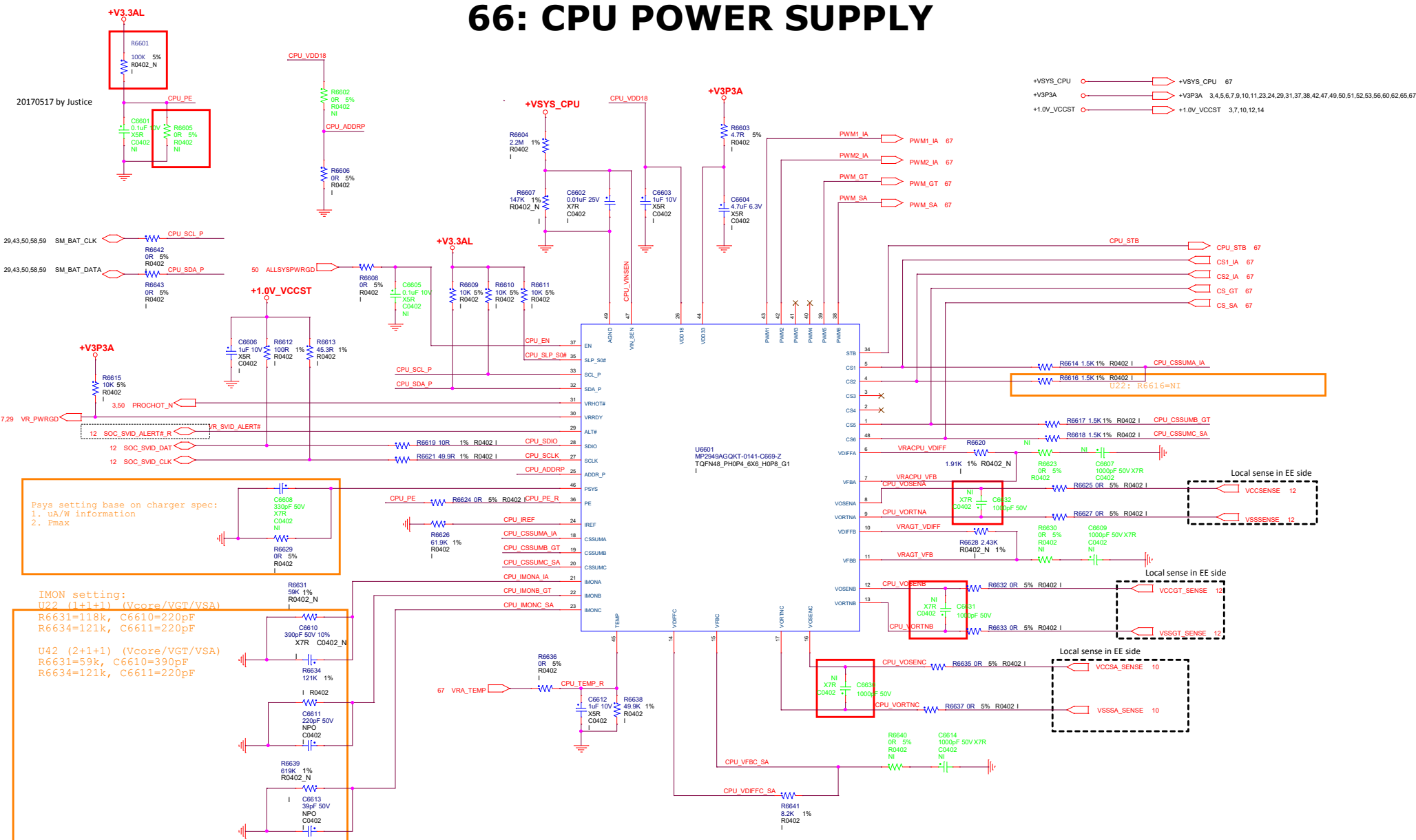


		Project: Mlix510	
		Engineer: Frank	
Size	Title: NA		Rev
C			V01
Date: Wednesday, May 24, 2017		Sheet 64 of 69	

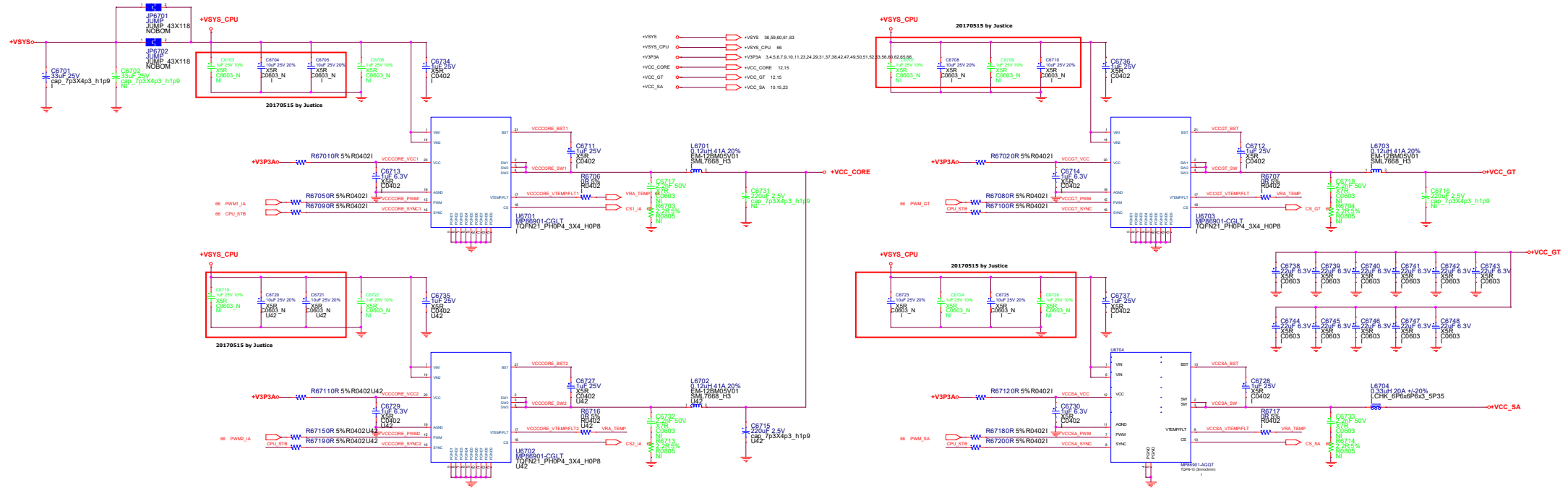
65: +1.8V_PRIM POWER SUPPLY



66: CPU POWER SUPPLY



67: VCC_CORE/GT/SA POWER SUPPLY





		Project: Mlix510	
		Engineer: Frank	
Size	Title:	Rev	
C	NA	V01	
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POWER CHANGE LIST
SDV to SIV

3/3	Page60. Change R6008 from 1k to 100R and R6009 from 150k to 10k to fine tune enable level.
3/17	Page66. Fine tune CPU transient,LL. Change R6603 to 1.87Kohm. Change R6619 to 604ohm. Change C6615 to 3300pF. Change R6628 to 150Kohm. Change C6622 to 68nF. Change R6651 to 39.2Kohm. Change R6655 to 100Kohm. Change R6644 to 1.1Kohm. Change R6646 to 1.5Kohm. Change R6635 to 30Kohm. Change R6618 to 69.8Kohm. Change C6609 to 3300pF